

LEMBAR PERSETUJUAN

**PERENCANAAN DAN PEMBUATAN PLL BERBASIS
PIC16F84 DENGAN PENAMPIL LCD DAN APLIKASINYA
SEBAGAI EXCITER FM**

SKRIPSI

Diajukan Untuk Memenuhi Salah Satu Syarat Memperoleh Gelar Sarjana Teknik
Pada Jurusan Teknik Elektro S-1 Konsentrasi Elektronika

Oleh :

Nanang Roni Wibowo

02.17.062

Dosen Pembimbing I



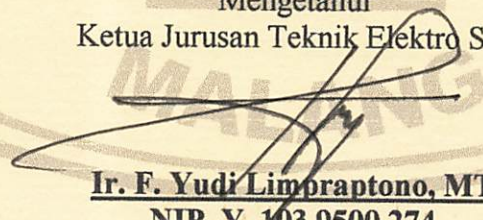
Ir. Sidik Noertjahjono, MT.
NIP. 102 8700 167

Dosen Pembimbing II



Ir. F. Yudi Limpraptono, MT
NIP. Y. 103 9500 274

Mengetahui
Ketua Jurusan Teknik Elektro S-1



Ir. F. Yudi Limpraptono, MT
NIP. Y. 103 9500 274

**KONSENTRASI ELEKTRONIKA
JURUSAN TEKNIK ELEKTRO S-1
FAKULTAS TEKNOLOGI INDUSTRI
INSTITUT TEKNOLOGI NASIONAL
MALANG**



BERITA ACARA UJIAN SKRIPSI
FAKULTAS TEKNOLOGI INDUSTRI

Nama : Nanang Roni Wibowo
NIM : 02.17.062
Jurusan : Teknik Elektro S-1
Konsentrasi : Teknik Elektronika
Masa Bimbingan : 09 Januari 2007 – 09 Juli 2007
Judul Skripsi : Perencanaan dan pembuatan PLL berbasis PIC16F84 dengan penampil LCD dan aplikasinya sebagai exciter FM.

Dipertahankan di hadapan Tim Penguji Skripsi Jenjang Strata Satu (S-1)
pada :

Hari : Sabtu
Tanggal : 17 Maret 2007
Nilai : A (95,65) *by*

Panitia Majelis Penguji,



(Ir. Mochtar Asroni, MSME)
NIP.Y. 1018100036

(Ir. F. Yudi Limpraptono, MT)
NIP.Y. 1039500274

Anggota Penguji

(DR. Cahyo Chrysdian, MSc)
NIP. 103 0400 412

(I Komang Somawirata, ST, MT)
NIP. Y. 103 0100 361

ABSTRAKSI

PERENCANAAN DAN PEMBUATAN PLL BERBASIS PIC16F84 DENGAN PENAMPIL LCD DAN APLIKASINYA SEBAGAI EXCITER FM

(Nanang Roni Wibowo, 0217062, Teknik Elektro/Elektronika S-1)
(Dosen Pembimbing : Ir.Sidik Noertjahjono, MT ; Ir.F. Yudi Limpraptono, MT)

Kata Kunci : Transmitter FM, Teknik PLL, Exciter FM

Penggunaan teknik modulasi telah berkembang pesat, diantaranya adalah teknik modulasi frekuensi yang murah dan lebih tahan terhadap noise, namun demikian dalam beberapa aplikasi belum menerapkan teknik kendali dengan umpan balik. Dalam Skripsi ini akan dipaparkan mengenai teknik penguncian fasa menggunakan PLL, yaitu teknik dengan membandingkan sinyal frekuensi output dengan sinyal frekuensi referensi dari oscilator kristal, error dari kedua sinyal tersebut berbentuk beda fasa, dengan *low pass filter* diperoleh tegangan dc untuk mengendalikan VCO dengan sistem antiphase. Sinyal yang akan dibandingkan diambil dari harmonisa kedua frekuensi output, besar pencacahan ditampilkan mikrokontroler ke LCD sebagai nilai frekuensi. Perangkat ini dioperasikan untuk bekerja pada frekuensi FM 87,5 – 108 MHz dengan spasi 100KHz tiap channel. Perangkat lunak digunakan : MPLAB IDE V74.3. Perangkat keras yang digunakan : minimum sistem PIC16F84, VCO, detector phase, $\div N$ Counter, D Flip Flop, Oscilator kristal, keypad, dan LCD.

ABSTRAKSI

PERENCANAAN DAN PEMBUATAN PTL BERBASIS PIC16F84 DENGAN PENAMPIL LCD DAN APLIKASINYA SEBAGAI EXCITER FM

(Nisang Rani Wibowo, 0217002, Teknik Elektronika 2-1)
(Dosen Pembimbing : Ir. Rizki Nurjannah, MT ; Ir. Yudi Limpatono, MT)

Kata Kunci : Transmitter FM, Teknik PTL, Exciter FM

Penggunaan teknik modulasi telah berkembang pesat diantaranya adalah teknik modulasi frekuensi yang sudah dan lebih telah terdapat noise, namun demikian dalam beberapa aplikasi belum menerapkan teknik kendali dengan umpan balik. Dalam Skripsi ini akan dipaparkan mengenai teknik pengujian phase menggunakan PTL, yaitu teknik dengan membandingkan sinyal frekuensi output dengan sinyal frekuensi referensi dari osilator kristal, error dari kedua sinyal tersebut berbentuk beda phase dengan Van Vleck diperoleh tegangan dc untuk mengendalikan VCO dengan sistem antiphaser. Sinyal yang akan dibandingkan diambil dari harmonisa kedua frekuensi output beam pemancar dan ditampilkan mikrokontroler ke LCD sebagai nilai frekuensi. Perangkat ini dioperasikan untuk bekerja pada frekuensi FM 87,5 – 108 MHz dengan spasi 100KHz tiap channel. Perangkat lunak digunakan : MPLAB IDE V4.3. Perangkat keras yang digunakan : minimum sistem PIC16F84, VCO, detector phase + N Counter, D Flip Flop, Osilator kristal, keypad, dan LCD.

KATA PENGANTAR

Dengan mengucapkan puji syukur kehadiran Allah SWT atas segala rahmat, hidayah dan inayah-Nya, sehingga penulis bisa menyelesaikan laporan skripsi dengan judul :

”PERENCANAAN DAN PEMBUATAN PLL BERBASIS PIC16F84 DENGAN PENAMPIL LCD DAN APLIKASINYA SEBAGAI EXCITER FM”

Pada kesempatan ini penulis ingin menyampaikan apresiasi dan terima kasih yang sebesar-besarnya kepada dosen pembimbing skripsi yaitu :

Ir.Sidik Noertjahjono, MT dan Ir.F. Yudi Limpraptono, MT

Yang telah memberikan bimbingan dan pengarahan, sehingga skripsi ini dapat diselesaikan. Selain itu penulis juga ingin menyampaikan terima kasih kepada :

- Bapak Ir.F.Yudi Limpraptono, MT selaku Ketua Jurusan Teknik Elektro S-1.
- Bapak Ir.Sidik Noertjahjono, MT selaku Kasie Laboratorium Jaringan Telekomunikasi.
- Bapak Ir. Eko Nurcahyo, MT selaku Dosen Wali.
- Bapak dan Ibu serta kakak dan adikku tersayang yang telah memberi dukungan materil dan moril beserta doa yang makbul selama penulis menyelesaikan skripsi ini.

KATA PENGANTAR

Dengan mengucap puji syukur kehadirat Allah SWT atas segala rahmat, hidayah dan inayah-Nya sehingga penulis bisa menyelesaikan laporan skripsi dengan judul :

"PERENCANAAN DAN PEMBUATAN PTL BERBASIS PIC16F84 DENGAN PENAMPIL LCD DAN APLIKASINYA SEBAGAI EXCITER PWT"

Pada kesempatan ini penulis ingin menyampaikan apresiasi dan terima kasih yang sebesar-besarnya kepada dosen pembimbing skripsi yaitu :

Ir.Sidik Noorjafono, MT dan Ir.W. Yudi Limpaqotono, MT

Yang telah memberikan bimbingan dan pengajaran, sehingga skripsi ini dapat diselesaikan. Selain itu penulis juga ingin menyampaikan terima kasih kepada :

- > Bapak Ir.W. Yudi Limpaqotono, MT selaku Ketua Jurusan Teknik Elektro 2-1.
- > Bapak Ir.Sidik Noorjafono, MT selaku Kasie Laboratorium Jaringan Telekomunikasi.
- > Bapak Ir. Eko Nurcahyo, MT selaku Dosen Wali.
- > Bapak dan Ibu serta kakak dan adikku tersayang yang telah memberi dukungan materi dan moril beserta doa yang taklah selama penulis menyelesaikan skripsi ini.

DAFTAR ISI

	Halaman
JUDUL	i
LEMBAR PERSETUJUAN	ii
BERITA ACARA UJIAN SKRIPSI	iii
ABSTRAKSI	iv
KATA PENGANTAR	v
DAFTAR ISI	vi
DAFTAR GAMBAR	ix
DAFTAR GRAFIK	x
DAFTAR TABEL	xi
BAB I PENDAHULUAN	
1.1 Latar Belakang	1
1.2 Permasalahan.....	2
1.3 Tujuan.....	2
1.4 Batasan Masalah.....	3
1.5 Metodologi Penelitian	3
1.6 Sistematika Penulisan.....	4
BAB II TEORI PENUNJANG	
2.1 Modulasi Frekuensi.....	5
2.2 Index Modulasi.....	6
2.3 Analisa Frekuensi Sinyal FM.....	6
2.4 Kebutuhan Bandwitdh pada FM	8
2.5 FM Broadcast	9

5.2	FM Broadcastasi	0
5.4	Kerjasama Broadcasti (Dua)	8
5.3	Analisa Broadcasti Sistem FM	0
5.2	Index Modulasi	0
5.1	Modulasi Broadcasti	2

BAB II TEORI PENDIDIKAN

1.0	Sistematisasi Pendidikan	4
1.2	Metodologi Penelitian	3
1.4	Bagian Masalah	3
1.3	Tujuan	3
1.5	Pemrosesannya	3
1.1	Gaya Berpikir	1

BAB I PENDAHULUAN

DALAM TUBUH	vi
DALAM SEKELING	v
DALAM CUMBUK	ix
DALAM ISI	vi
KATA PENGANTAR	v
ABSTRAKSI	iv
BERITA ACARA DARI SEKELING	iii
SEMANGAT BERSEKELING	ii
TUJUAN	i

Daftar Isi

2.6	Pre Emphasis	10
2.7	Daya pada Gelombang FM	11
2.8	Modulator FM	12
2.9	PLL (<i>Phase Lock Loop</i>)	14
2.10	Mikrokontroler PIC16F84.....	17
2.10.1	Arsitektur mikrokontroler	18
2.10.2	Organisasi Memori.....	20

BAB III PERANCANGAN DAN PEMBUATAN ALAT

3.1	Gambaran Umum Alat	23
3.2	Perancangan Alat.....	24
3.2.1	RF Unit.....	25
3.2.2	PLL Unit.....	27
3.2.3	Minimum sistem unit	30

BAB IV PENGUJIAN ALAT

4.1	Tujuan	38
4.2	Pengujian Rangkaian Pre-Emphasis.....	38
4.3	Pengujian VCO	41
4.4	Pengujian Detektor Phasa.....	44
4.5	Pengujian Oscilator Lokal.....	46
4.6	Pengujian PLL.....	47

BAB V PENUTUP

5.1	Kesimpulan.....	54
5.2	Saran-saran	55

DAFTAR PUSTAKA

LAMPIRAN

DAFTAR GAMBAR

	Halaman
Gambar 2.1 Gelombang FM untuk Pemodulasi Gelombang sinus.....	5
Gambar 2.2 Band FM Broadcast Komersial	9
Gambar 2.3 Rangkaian Emphasis dengan konstanta waktu $75\mu\text{S}$	11
Gambar 2.4 Aplikasi Dioda Varactor pada Oscilator Colpitts.....	13
Gambar 2.5 Diagram Blok dasar PLL.....	15
Gambar 2.6 Pin Diagram PIC16F84	17
Gambar 2.7 Arsitektur MCU PIC16F84	19
Gambar 2.8 Peta Memori Program PIC16F84.....	21
Gambar 2.9 Peta Register File PIC16F84	22
Gambar 3.1 Diagram Blok PLL Berbasis PIC16F84.....	32
Gambar 3.2 Skematik Rangkaian Pre- Emphasis	25
Gambar 3.3 LPF (<i>Low Pass Filter</i>).....	26
Gambar 3.4 Rangkaian VCO	26
Gambar 3.5 Rangkaian Buffer	27
Gambar 3.6 Rangkaian Oscilator Lokal dan Pembaginya	28
Gambar 3.7 Rangkaian Detektor Fasa	28
Gambar 3.8 Rangkaian Pembagi 4.....	29
Gambar 3.9 Rangkaian N Devider	30
Gambar 3.10 Rangkaian Minimum Sistem.....	31
Gambar 4.1 Penguukuran Rangkaian Pre-Emphasis	39
Gambar 4.2 Pengukuran VCO	41
Gambar 4.3 Pengukuran Rangkaian Detektor Fasa	44

DAFTAR GAMBAR

Halaman

2	Gelombang FM untuk Pemodulasi Gelombang sinus.....	Gambar 2.1
9	Band FM Broadband Komersial.....	Gambar 2.2
11	Rangkaian Impedansi dengan konstanta waktu $75\mu s$	Gambar 2.3
13	Aplikasi Dioda Varactor pada Oscillator Colpitts.....	Gambar 2.4
15	Diagram Blok dasar PLL.....	Gambar 2.5
17	Pin Diagram PIC16F84.....	Gambar 2.6
19	Arsitektur ALU PIC16F84.....	Gambar 2.7
21	Peta Memori Program PIC16F84.....	Gambar 2.8
22	Peta Register File PIC16F84.....	Gambar 2.9
22	Diagram Blok PLL Berbasis PIC16F84.....	Gambar 3.1
23	Skematik Rangkaian Pre-Empedansi.....	Gambar 3.2
26	LPE (Low Pass Filter).....	Gambar 3.3
26	Rangkaian VCO.....	Gambar 3.4
27	Rangkaian Buffer.....	Gambar 3.5
28	Rangkaian Oscillator Lokal dan Pembagiya.....	Gambar 3.6
28	Rangkaian Detektor Fasa.....	Gambar 3.7
29	Rangkaian Pembagi 4.....	Gambar 3.8
30	Rangkaian Divider.....	Gambar 3.9
31	Rangkaian Minimum Sistem.....	Gambar 3.10
39	Pengerukan Rangkaian Pre-Empedansi.....	Gambar 4.1
41	Pengerukan VCO.....	Gambar 4.2
44	Pengerukan Rangkaian Detektor Fasa.....	Gambar 4.3

Gambar 4.4	Pengukuran Rangkaian frekuensi referensi.....	46
Gambar 4.5	Pengukuran Modul PLL	47
Gambar 4.6	Hasil Pengukuran Pre- Emphasis	52
Gambar 4.7	Hasil Pengujian VCO	53
Gambar 4.8	Hasil Pengujian Detektor Phasa	53
Gambar 4.9	Hasil Pengujian PLL	53

DAFTAR GRAFIK

	Halaman
Grafik 2-1. Komponen Spectral dari Frekuensi Carrier.....	8
Grafik 2-1. Kurva Karakteristik Dioda	13
Grafik 4-1. Respon Frekuensi terhadap attenuator	40
Grafik 4-3. Respon Frekuensi terhadap tegangan	43

DAFTAR TABEL

	Halaman
Tabel 2.1 Hasil Perhitungan Fungsi Bessel.....	7
Tabel 4.1 Data Hasil Pengukuran Pre-Emphasis.....	39
Tabel 4.2 Data Hasil Pengukuran VCO	42
Tabel 4.3 Data Hasil Pengukuran Detektor phasa.....	45
Tabel 4.4 Data Hasil Pengukuran Oscilator Lokal.....	47
Tabel 4.5 Data Pengujian PLL	48

BAB I

PENDAHULUAN

1.1. Latar Belakang

Semenjak komunikasi radio dikembangkan oleh ilmuwan *Guglielmo Marconi* tahun 1894, maka sejak itu pula mata dunia terbuka akan pentingnya komunikasi nirkabel yang sanggup menghubungkan antar negara. Komunikasi nirkabel dalam penerapannya di Indonesia menjadi salah satu teknologi yang berkembang dengan cepat, hal ini terjadi dengan melihat kondisi wilayah Indonesia yang mayoritas pegunungan dan laut.

Pergeseran kebutuhan manusia yang menginginkan penyampaian informasi yang cepat dan akurat menjadikan perkembangan komunikasi selalu berkembang, salah satu perkembangan yang sampai sekarang terus dikembangkan adalah teknologi pemodulasian frekuensi karena lebih tahan terhadap noise dari pada modulasi amplitudo.

Kebutuhan masyarakat sekarang sudah mulai bergeser, dahulu informasi hanya diterima melalui isyarat Morse (telegram) kemudian berkembang dengan teknologi pemodulasian amplitudo dan diperbaiki lagi dengan teknologi pemodulasian frekuensi. Kelebihan teknologi pemodulasian frekuensi adalah diperolehnya sinyal informasi lebih jernih mendekati sumber aslinya.

Pada transmitter dengan pemodulasian frekuensi, pengiriman informasi dilakukan dengan merubah perubahan amplitudo sinyal informasi kedalam bentuk perubahan frekuensi dari sinyal *carrier* sehingga diperlukan kestabilan dari frekuensi *center* tidak bergeser.

BAB I PENDAHULUAN

1.1. Latar Belakang

Sejarah komunikasi radio dikembangkan oleh Nikola Tesla dan Guglielmo Marconi tahun 1894, maka sejak itu pada masa dunia terbuka akan pentingnya komunikasi nirkabel yang sangat mempengaruhi antar negara. Komunikasi nirkabel dalam penerapannya di Indonesia menjadi salah satu teknologi yang berkembang dengan cepat. Hal ini terjadi dengan meluas kondisi wilayah Indonesia yang mayoritas penggunaan dan jasa.

Persebaran kebutuhan manusia yang menginginkan penyampaian informasi yang cepat dan akurat menjadikan perkembangan komunikasi seluler berkembang, salah satu perkembangan yang sangat penting dikembangkannya adalah teknologi pemodulasian frekuensi karena lebih tahan terhadap noise dan pada modulasi amplitudo.

Kebutuhan masyarakat akan informasi yang cepat, dalam informasi yang diterima melalui isyarat Morse (telegram) kemudian berkembang dengan teknologi pemodulasian amplitudo dan dipertahankan lagi dengan teknologi pemodulasian frekuensi. Kelebihan teknologi pemodulasian frekuensi adalah dipertahkannya sinyal informasi lebih tahan terhadap sumber aslinya.

Pada transmitter dengan pemodulasian frekuensi, pengiriman informasi dilakukan dengan membuat perubahan amplitudo sinyal informasi kedalam bentuk perubahan frekuensi dari sinyal carrier sehingga diperlukan kestabilan dari frekuensi carrier tidak bergeser.

Karena kestabilan frekuensi *center* menentukan salah satu kualitas pemodulasian, maka pengontrolannya pun diberlakukan berbeda pula. Untuk mengontrol sistem dibutuhkan komponen dan rangkaian elektronik yang mampu menjaga agar nilai elektrisnya tidak bergeser dari yang diinginkan yaitu menggunakan PLL (Phase Locked Loop) pada pemodulasian agar dicapai standarisasi dari CCIR (Commite Consultatif International des Radiocommunication).

1.2. Permasalahan

Berdasarkan latar belakang yang telah diuraikan sebelumnya dapat dirumuskan permasalahannya mencakup:

1. Bagaimana merancang dan membuat rangkaian PLL sebagai pengendali oscilator terkendali tegangan.
2. Bagaimana merancang dan membuat oscilator terkendali tegangan untuk exciter FM.
3. Bagaimana merancang dan membuat perangkat lunak berbasis mikrokontroler PIC16F84.

1.3. Tujuan

Adapun tujuan perancangan dan pembuatan alat ini adalah menerapkan teknologi PLL berbasis mikrokontroler yang memberikan tampilan pada LCD.

1.4. Batasan Masalah

Dalam menyusun tugas akhir ini diperlukan suatu batasan masalah agar tidak menyimpang dari ruang lingkup yang akan dibahas. Adapun batasan masalahnya:

1. Alat ini bekerja pada jalur VHF.
2. Tidak membahas final amplifier.
3. Hanya membahas masalah perancangan perangkat kerasnya .
4. Tidak membahas masalah antenna dan saluran transmisi.
5. Pemroses sinyal informasi, catu daya hanya di jelaskan secara umum.

1.5. Metodologi

Metodologi yang digunakan dalam pembahasan skripsi ini adalah :

1. Studi Literatur rangkaian oscilator, penguat frekuensi tinggi, filter dan pembagi frekuensi serta teori mikrokontroler PIC16F84.
2. Merencanakan dan membuat secara langsung alat dengan praktek secara langsung tiap bagian rangkaian.
3. Melakukan pengujian terhadap tiap bagian alat.
4. Melakukan pengujian keseluruhan sistem yang direncanakan
5. Penyusunan laporan skripsi.

1.4. Batasan Masalah

Dalam menyusun tugas akhir ini dibatasi suatu batasan masalah agar tidak menyimpang dari ruang lingkup yang akan dibahas. Adapun batasan masalahnya:

1. Alat ini bekerja pada jalur VHF.
2. Tidak membahas final amplifier.
3. Hanya membahas masalah perencanaan perangkat kerjanya.
4. Tidak membahas masalah antenna dan saluran transmisi.
5. Proses sinyal informasi, cara daya hanya di jelaskan secara umum.

1.5. Metodologi

Metodologi yang digunakan dalam pembahasan skripsi ini adalah :

1. Studi Literatur mengenai oscilator, penguat frekuensi tinggi, filter dan pembagi frekuensi serta teori mikrokontroler PIC16F84.
2. Merencanakan dan membuat secara langsung alat dengan praktik secara langsung tiap bagian rangkaian.
3. Melakukan pengujian terhadap tiap bagian alat.
4. Melakukan pengujian keseluruhan sistem yang direncanakan.
5. Penyusunan laporan skripsi.

1.6. Sistematika Penulisan

Penulisan tugas akhir ini terbagi menjadi lima bab dengan sistematika sebagai berikut:

BAB I PENDAHULUAN

Berisi latar belakang, tujuan, permasalahan, batasan masalah, metodologi, dan sistematika penulisan.

BAB II LANDASAN TEORI

Membahas teori – teori dasar sebagai penunjang perencanaan dan pembuatan alat.

BAB III PERENCANAAN DAN PEMBUATAN ALAT

Membahas tentang perencanaan alat baik perangkat keras maupun perangkat lunak sistem berdasarkan diagram blok.

BAB IV PENGUJIAN ALAT

Membahas pengujian tiap bagian dan keseluruhan sistem serta analisa terhadap hasil pengujian..

BAB V PENUTUP

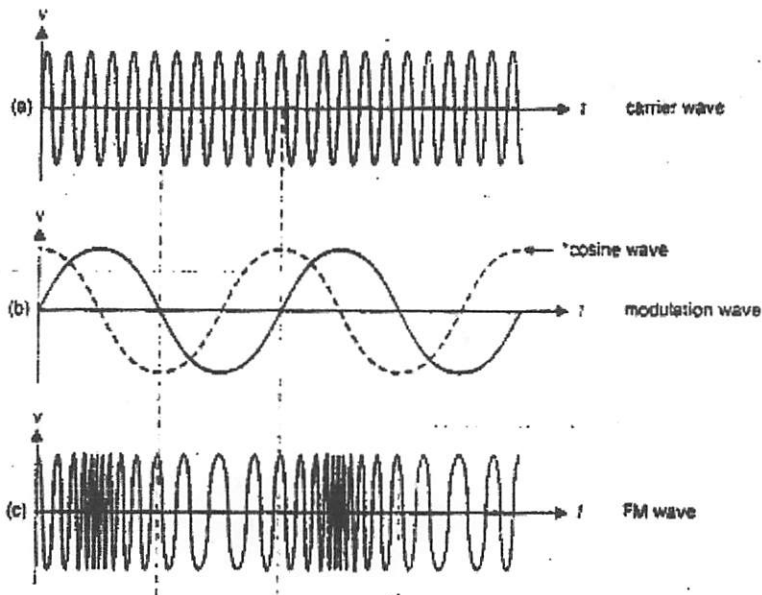
Berisi kesimpulan dan saran.

BAB II

TEORI PENUNJANG

2.1. Modulasi Frekuensi

Merupakan salah satu teknik pemodulasian dimana deviasi frekuensi sinyal carrier disebabkan oleh perubahan amplitude sinyal informasi, sebagaimana ditunjukkan dalam gambar 2-1, berikut:



Gambar 2-1. Gelombang FM untuk Sinyal Pemodulasi Gelombang Sinus; (a) Sinyal Carrier; (b) Sinyal Informasi ; (c) Gelombang FM¹

¹ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International.Inc. 1998. USA. Hal 50

2.2. Index Modulasi

Merupakan perbandingan antara deviasi frekuensi maksimum terhadap frekuensi sinyal informasi, dan diberikan oleh persamaan, sebagai berikut :

$$m_f = \frac{\delta}{f_m}$$

indeks modulasi untuk FM sebanding dengan amplitudo dari signal modulasi yang mengakibatkan deviasi (δ) dan juga berbanding terbalik terhadap frekuensi sinyal modulasi.

2.3. Analisa Frekuensi Sinyal FM

Mengingat dalam AM, komponen frekuensi terdiri atas frekuensi carrier tetap dengan sisi band atas dan bawah sama ditunjukkan di atas dan bawah frekuensi carrier. Komponen frekuensinya merupakan pencerminan terhadap lainnya serta identik, untuk spectrum frekuensi gelombang FM jauh lebih kompleks. Untuk sinyal modulasi sinus terhadap frekuensi carrier FM diperoleh sisi band yang tak terhingga, kompleksitas sisi bandnya meningkat dengan kompleksitas sinyal modulasi.

Analisa komponen frekuensi dan amplitudo dalam gelombang FM memerlukan penggunaan matematika integral yang kompleks yang diketahui sebagai fungsi *Bessel* jenis pertama pada ordè ke-n, seperti ditunjukkan dalam persamaan berikut:

$$\begin{aligned} e_{FM} = & A_c J_0(m_f) \sin \omega_c t + A_c \{J_1(m_f)[\sin(\omega_c + \omega_m)t - \sin(\omega_c - \omega_m)t \\ & + A_c \{J_2(m_f)[\sin(\omega_c + 2\omega_m)t - \sin(\omega_c - 2\omega_m)t \\ & + A_c \{J_3(m_f)[\sin(\omega_c + 3\omega_m)t - \sin(\omega_c - 3\omega_m)t + \dots \} \} \} \end{aligned}$$

2.2. Index Modulasi

Melakukan perbandingan antara deviasi frekuensi maksimum terhadap

frekuensi sinyal informasi dan diberikan oleh persamaan sebagai berikut :

$$m_i = \frac{\delta}{f_m}$$

indeks modulasi untuk FM sebanding dengan amplitudo dari sinyal modulasi yang mengakibatkan deviasi (δ) dan juga berbanding terbalik terhadap frekuensi sinyal modulasi.

2.3. Analisis Frekuensi Sinyal FM

Mengingat dalam AM, komponen frekuensi terdiri atas frekuensi carrier tetap dengan sisi band atas dan bawah sama ditunjukkan di atas dan bawah frekuensi carrier. Komponen frekuensinya merupakan pencerminan terhadap frekuensi carrier, untuk spectrum frekuensi gelombang FM jauh lebih kompleks. Untuk sinyal modulasi sinus terhadap frekuensi carrier FM diperoleh sisi band yang tak terhingga kompleksitas sisi bandnya meningkat dengan kompleksitas sinyal modulasi.

Analisis komponen frekuensi dan amplitudo dalam gelombang FM memerlukan penggunaan matematika integral yang kompleks yang diketahui sebagai fungsi Bessel jenis pertama pada orde ke-n seperti ditunjukkan dalam persamaan berikut:

$$e^{j\omega_c t + m \cos(\omega_m t)} = J_0(m) \cos(\omega_c t) + 2J_1(m) \cos(\omega_c t) \cos(\omega_m t) + 2J_2(m) \cos(\omega_c t) \cos(2\omega_m t) + \dots$$

Keterangan :

e_{FM} = Amplitudo sesaat gelombang FM yang dimodulasi

A_C = Amplitudo puncak Carrier

J_n = Solusi untuk fungsi *Bessel* orde ke-n dari index modulasi m_f

m_f = Indeks Modulasi FM.

Pada persamaan diatas dapat dilihat bahwa gelombang FM berisi nilai tak hingga pada komponen sisi bandnya yang mempunyai amplitudo tersendiri didahului koefisien $J_n(m_f)$. Masing - masing sisiband atas dan bawah digantikan oleh frekuensi carrier oleh integral berlipat dari frekuensi modulasi. Dengan bantuan komputer matematika integral tersebut sudah ditabelkan dan digrafikan seperti berikut:

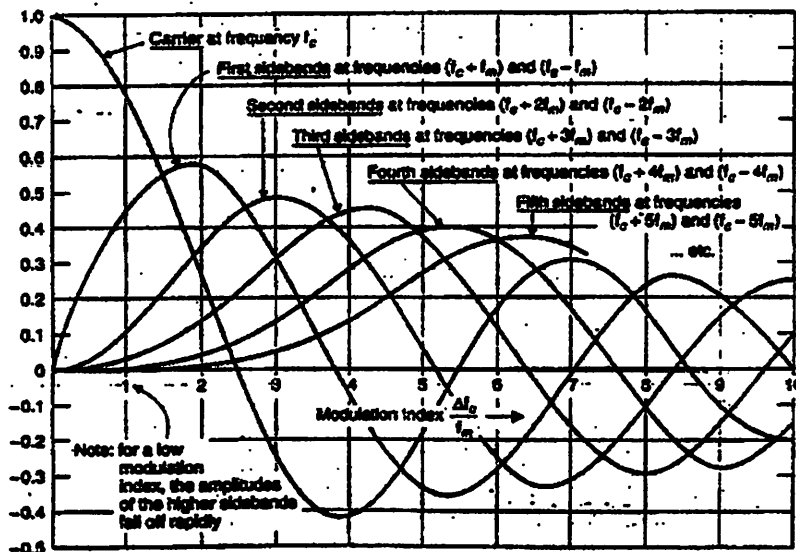
Tabel 2-1. Hasil Perhitungan Fungsi *Bessel*²

TABLE 4-1
Bessel functions of the first kind

Modulation Index (m_f)	Carrier Frequency f_c in order of subscripts															
	J_0	J_1	J_2	J_3	J_4	J_5	J_6	J_7	J_8	J_9	J_{10}	J_{11}	J_{12}	J_{13}	J_{14}	
0.00	1.00															
0.25	0.98	0.12														
0.5	0.94	0.31	0.08													
1.0	0.77	0.44	0.11	0.02												
1.5	0.51	0.56	0.23	0.06	0.01											
2.0	0.22	0.58	0.35	0.13	0.03											
2.5	0.05	0.50	0.45	0.22	0.07	0.02										
3.0	0.26	0.34	0.49	0.31	0.13	0.04	0.01									
4.0	0.40	0.07	0.40	0.44	0.28	0.11	0.05	0.02								
5.0	0.18	-0.33	0.05	0.36	0.39	0.26	0.13	0.05	0.02							
6.0	0.15	-0.28	0.24	0.11	0.36	0.36	0.25	0.13	0.06	0.02						
7.0	0.30	0.09	0.40	0.17	0.16	0.34	0.34	0.23	0.13	0.06	0.02					
8.0	0.17	0.23	0.11	0.29	0.10	0.19	0.34	0.32	0.22	0.11	0.05	0.03				
9.0	0.09	0.24	0.14	-0.18	-0.27	-0.06	0.20	0.33	0.30	0.21	0.12	0.05	0.03			
10.0	0.25	0.04	0.25	0.06	-0.22	-0.23	-0.04	0.22	0.31	0.29	0.20	0.12	0.05	0.03		
12.0	0.05	-0.22	0.08	0.20	0.18	-0.07	-0.24	-0.17	0.05	0.23	0.30	0.27	0.20	0.12	0.07	0.03
15.0	0.01	0.21	0.04	0.19	-0.12	0.13	0.21	0.03	-0.17	-0.22	-0.09	0.10	0.24	0.28	0.25	0.18

Source: H. C. Tuckwell, *Bessel Functions*, Third Edition, Van Nostrand Reinhold, New York, N.Y., 1948. Courtesy of the publisher.

² Hioki, Warren. "Telecommunication Third Edition". Prentice-Hall International, Inc. 1998. USA. Hal 54



Grafik 2-1. Komponen Spectral dari Frekuensi Carrier³

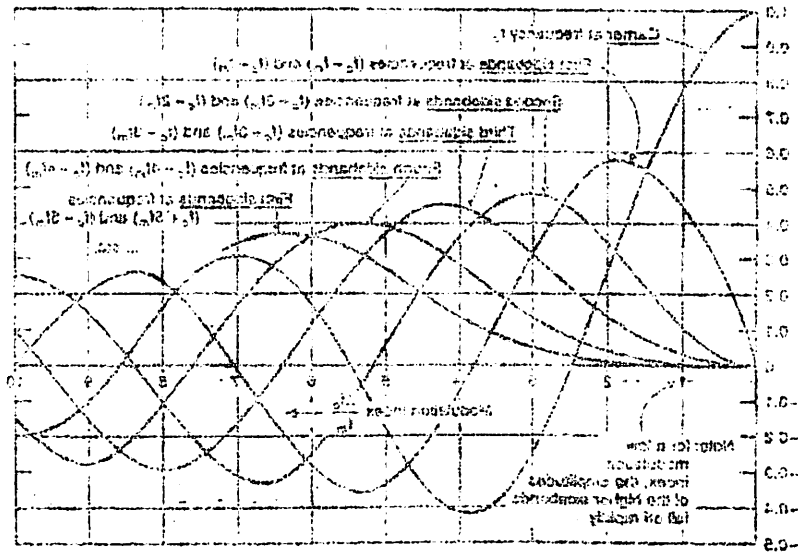
2.4. Kebutuhan Bandwidth pada FM

Secara teori gelombang FM mempunyai band sisi tak hingga, sehingga membutuhkan bandwidth tak terhingga yang dibutuhkan untuk pemancaran dan penerimaan. Dalam kenyataan, bagaimanapun amplitudo band sisi diabaikan diluar range frekuensi yang pasti dari carrier. Range tersebut merupakan fungsi dari indeks modulasi m_f , sehingga semakin tinggi indeks modulasi semakin tinggi bandwidth yang dibutuhkan.

$$BW = 2(n * f_n)$$

Dengan menggunakan diatas dapat diperoleh kebutuhan bandwidth, dengan n adalah komponen band sisi tertinggi, f_m adalah frekuensi modulasi tertinggi. Pada tahun 1938 J.R. Carson dalam memorandumnya menuliskan

³ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International.Inc. 1998. USA. Hal 53



Graph 3-1. Komponen Spektral dari Frekuensi Carrier

3.4. Kebutuhan Bandwidth pada FM

Secara teori gelombang FM mempunyai band sisi tak hingga sehingga membutuhkan bandwidth tak terhingga yang dibutuhkan untuk pemancaran dan penerimaan. Dalam kenyataan, bagaimanapun amplitudo band sisi dibatasi oleh rentang frekuensi yang pasti dari carrier. Range tersebut merupakan fungsi dari indeks modulasi m_f , sehingga semakin tinggi indeks modulasi semakin tinggi bandwidth yang dibutuhkan.

$$BW = 2(f_m + \Delta f)$$

Dengan menggunakan diatas dapat diperoleh kebutuhan bandwidth. Dengan n adalah komponen band sisi tertinggi, ia adalah frekuensi modulasi tertinggi. Pada tahun 1928 J.R. Carson dalam penelitiannya memuliskan

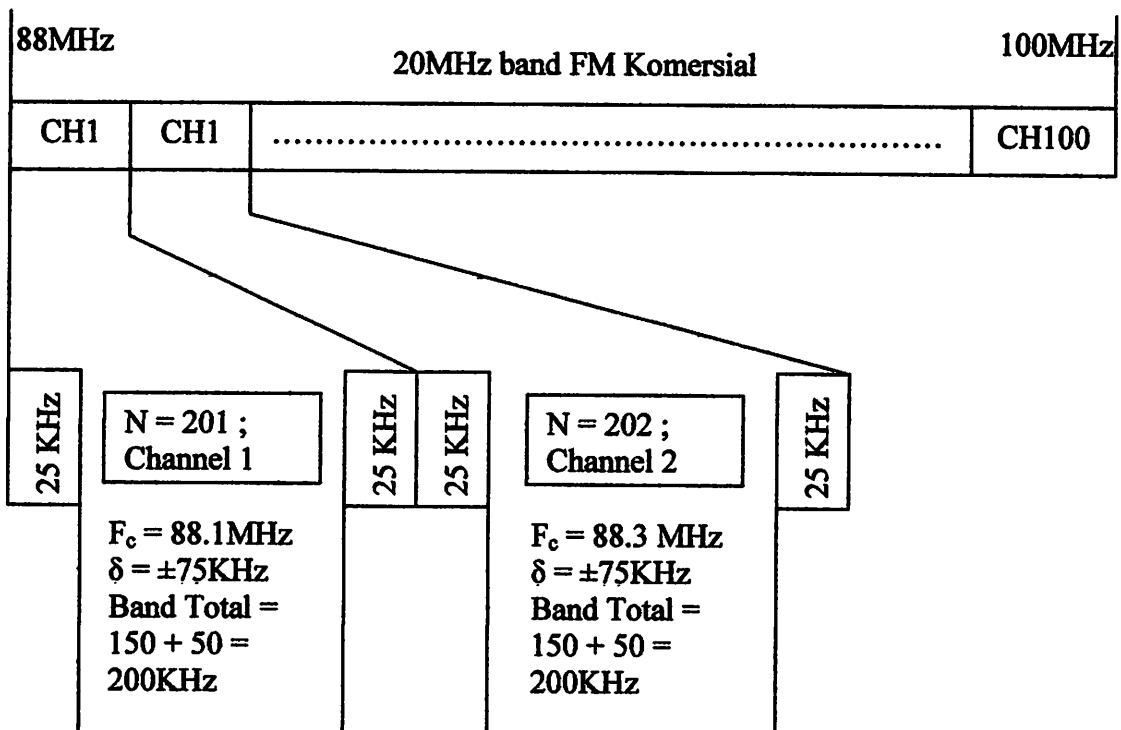
¹ H. H. Wood, "Telecommunication Third Edition", Prentice-Hall International, Inc. 1998. (USA) Hal 53

bahwa bandwitdh yang diperlukan untuk transmisi gelombang modulasi sudut sebagaimana dirumuskan berikut:

$$BW = 2(\delta + f_m)$$

2.5. FM Broadcast

Band untuk FM komersial, sebagaimana ditunjukkan dalam Gambar 2-2. diperluas dari 88 – 108 MHz dan dibagi kedalam 100 channel, alokasi bandwitdh yang diperbolehkan oleh FCC sebesar 200KHz dan ditunjukkan dalam nilai numerik N.



Gambar 2-2. Band FM Broadcast Komersial⁴

⁴ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International. Inc. 1998. USA. Hal 60

Masing- masing channel range mulai 88,1 MHz dengan $N = 201$ hingga 107,9 MHz dengan $N = 300$, hal ini dapat ditemukan dengan menggunakan persamaan:

$$N = 5(f - 47,9)$$

deviasi sinyal carrier yang diperbolehkan adalah $\pm 75\text{KHz}$, pemancar diperbolehkan untuk memodulasi frekuensi carrier dengan range band frekuensi dari 50 Hz ke maksimum 15KHz, sehingga range indeks modulasinya 5 untuk f_m 15KHz dan 1500 untuk f_m 50Hz, sehingga kebutuhan bandwidth sebesar 150KHz dengan 25KHz band pandu pada sisi atas dan bawah frekuensi center, sehingga total bandwidth keseluruhan 200KHz.

2.6. Pre Emphasis

Pengaruh dari noise terhadap signal carrier FM sebanding langsung terhadap frekuensi modulasi. Meningkatnya frekuensi modulasi f_m , menurunkan SNR (*signal to noise ratio*), karena informasi yang dikirimkan seperti suara dan music mempunyai frekuensi yang berubah, dan disalurkan melalui band modulasi yang diberikan, sehingga pemancar perlu untuk meningkatkan level signal dari frekuensi modulasi yang lebih tinggi sebelum dilakukan proses modulasi, hal ini untuk memelihara SNR yang seragam terhadap frekuensi modulasi yang lebih tinggi dan biasa disebut *Pre-Emphasis*, kebalikan dari proses ini disebut *De-Emphasis* yang diletakan pada bagian penerima.

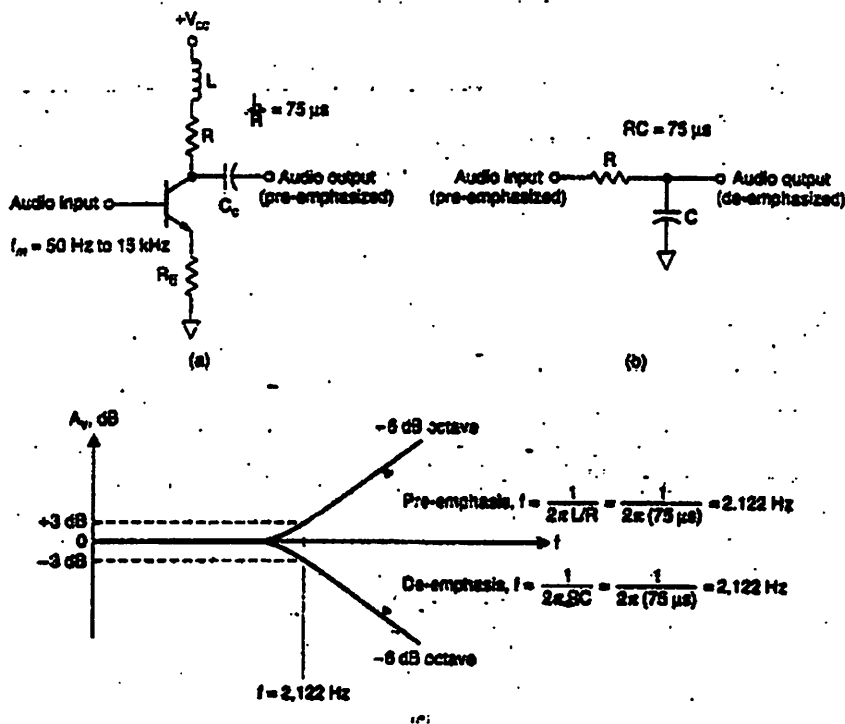
Masing-masing channel range mulai 88.1 MHz dengan $N = 201$ bin yang 107.9 MHz dengan $N = 200$. Hal ini dapat dilakukan dengan menggunakan persamaan:

$$N = 2(\gamma - 43.9)$$

deviasi sinyal carrier yang diperbolehkan adalah ± 75 kHz. perantara diperbolehkan untuk memodulasi frekuensi carrier dengan range band frekuensi dari 50 Hz ke maksimum 12 kHz. sehingga range indeks modulasinya 2 untuk f_m 12 kHz dan 1200 untuk f_m 50 Hz. sehingga kebutuhan bandwidth sebesar 120 kHz dengan 22 kHz band pada sisi atas dan bawah frekuensi carrier sehingga total bandwidth keseluruhan 200 kHz.

2.6. Pre Emphasis

Pengaruh dari noise terhadap sinyal carrier FM sebanding langsung terhadap frekuensi modulasi. Meningkatkannya frekuensi modulasi f_m menurunkan SNR (signal to noise ratio) karena informasi yang dikirirkan seperti suara dan music mempunyai frekuensi yang berubah dan disalurkan melalui band modulasi yang diberikan, sehingga perantara perlu meningkatkan level sinyal dari frekuensi modulasi yang lebih tinggi sebelum dilakukan proses modulasi. Hal ini untuk memelihara SNR yang setara terhadap frekuensi modulasi yang lebih tinggi dan bisa disebut Pre-Emphasis. Kebalikan dari proses ini disebut De-Emphasis yang dilakukan pada bagian penerima.



Gambar 2-3. Rangkaian Emphasis dengan konstanta waktu $75\mu\text{S}$ serta Respon Frekuensi⁵

Berdasarkan peraturan FCC stasiun pemancar FM broadcast untuk menyertakan rangkaian Pre-Emphasis dengan konstanta waktu $75\mu\text{S}$.

2.7. Daya pada Gelombang FM

Daya total pada gelombang FM didistribusikan pada carrier dan komponen band sisinya. Jika dijumlahkan daya pada carrier dan semua band sisinya untuk beberapa indeks modulasi, akan sama dengan daya total dari carrier tak termodulasi, sehingga dapat dinyatakan :

$$P_T = \frac{V_{Crms}^2}{R}$$

⁵ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International.Inc. 1998. USA. Hal 67

sedangkan untuk carrier yang termodulasi :

$$P_T = P_{J0} + P_{J1} + P_{J2} + P_{J3} + \dots + P_{Jn}$$
$$P_T = \frac{V_{J0}^2}{R} + \frac{V_{J1}^2}{R} + \frac{V_{J2}^2}{R} + \frac{V_{J3}^2}{R} + \dots + \frac{V_{Jn}^2}{R}$$

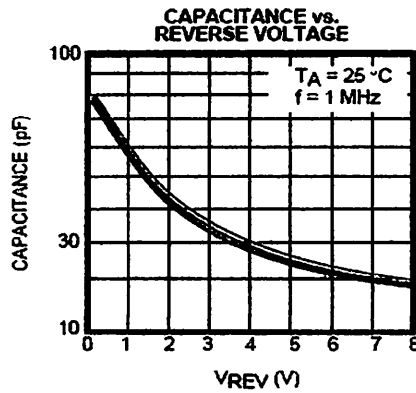
dengan P_T adalah daya total rms dari gelombang tak termodulasi, V_{Crms} adalah tegangan rms signal carrier, R adalah resistansi beban dalam hal ini 50Ω .

2.8. Modulator FM

Terdapat dua metode untuk menghasilkan signal FM : langsung dan tak langsung. Metode langsung terjadi ketika signal modulasi secara langsung digunakan untuk merubah frekuensi atau fasa dari signal carrier. Sedangkan metode tak langsung digunakan untuk merubah fasa dari signal carrier, yang secara tak langsung merubah frekuensinya.

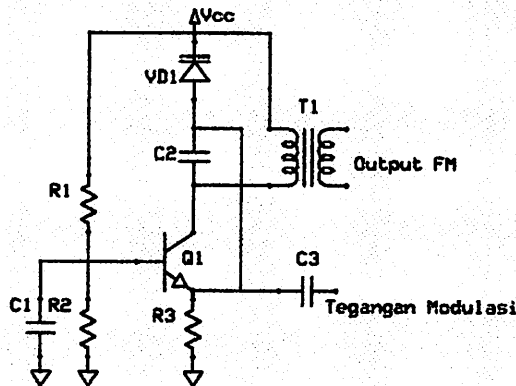
➤ Modulator Varactor

Modulator varactor menggunakan dioda varactor pada *tank circuits* untuk memperoleh signal FM langsung. Dioda varactor merupakan komponen semikonduktor yang diproduksi khusus untuk mempunyai sifat kapasitif pada saat dibias balik, yang membedakan dioda varactor dengan lainnya adalah perbandingan pengaturannya yang lebar, sebagai contoh pada gambar 2-4.



Grafik 2-2. Kurva Karakteristik Dioda Varactor⁶

Perbandingan pengaturannya dinyatakan sebagai perbandingan kapasitansi *junction* C_j yang diukur pada saat tegangan balik 1Volt dan kapasitansi *junction* C_j pada saat tegangan balik 8 volt, diperoleh perbandingan sebesar 1:3.



Gambar 2-4. Aplikasi Dioda Varactor pada Oscilator Colpitts⁷

Dioda varactor dibias oleh tegangan V_{cc} dan potensial emitor Q1, umpan balik diambilkan dari *tank circuits* dan di berikan ke emitor Q1. signal input audio memodulasi kapasitansi dioda varactor, selanjutnya frekuensi resonansi dari *tank*

⁶ Datasheet Dioda Varactor MV2109

⁷ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International.Inc. 1998. USA. Hal 69

circuits berubah dengan tegangan sesaat dari signal modulasi, sehingga dihasilkan signal FM pada output T1.

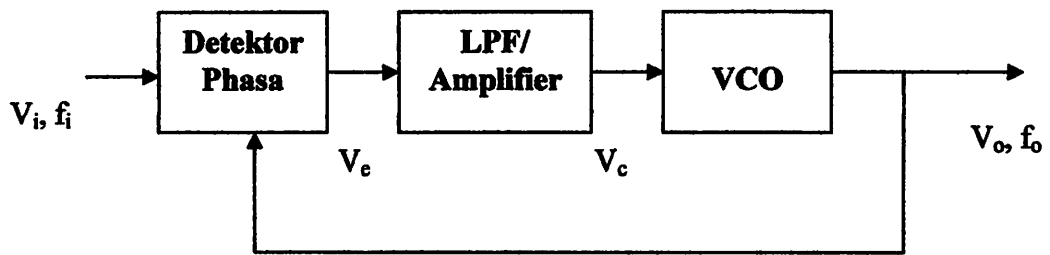
➤ Modulator Reactance

Modulator reaktansi adalah metode lain untuk menghasilkan FM secara langsung, yaitu dengan menempatkan komponen L atau C variabel pada *tank circuits* dari oscilator frekuensi carrier dan reaktansinya dibuat berubah sebagai fungsi dari signal modulasi.

2.9. PLL (*Phase Lock Loop*)

PLL merupakan sistem umpan balik elektronik yang terdiri atas detektor fasa, kombinasi tapis lolos bawah dan penguat, serta oscilator yang dikendalikan oleh tegangan atau VCO (*Voltage Controlled Oscillator*). Mengkombinasikan fungsi tersebut kedalam sistem loop tertutup membolehkan pelacakan frekuensi dan fasa. Saat hal ini terjadi VCO dikatakan dalam kondisi terkunci phasanya terhadap sinyal input.

VCO menghasilkan sinyal yang frekuensinya kira –kira sama dengan frekuensi *free-running*. Frekuensi ini merupakan frekuensi pada saat PLL tidak terkunci atau loop terbuka. VCO dirancang sehingga frekuensi outputnya lebih besar dari kebutuhan output PLL dan nilai frekuensinya dikendalikan oleh tegangan pada inputnya, bentuk dasar dari PLL dapat digambarkan sebagai berikut:



Gambar 2-5. Diagram Blok Dasar PLL⁸

Ketika signal input V_i dengan frekuensi f_i diberikan ke detektor phasa, frekuensinya dibandingkan dengan frekuensi output f_o dari VCO, hasil perbandingan tersebut menghasilkan tegangan *error* V_e yang menunjukkan beda phasa antara frekuensi input f_i dan frekuensi output f_o , tegangan ini kemudian difilter dan dikuatkan untuk menghasilkan tegangan kendali VCO, yaitu V_c . Yang membetulkan frekuensi VCO menjaga penguncian phasanya terhadap signal input.

➤ Detektor Phasa

Pada prinsipnya detektor phasa merupakan rangkaian *mixer* (pencampur) yang menghasilkan bentuk penjumlahan dan pengurangan dari signal input dan output. Jika signal input dan output dinyatakan sebagai berikut :

$$v_i = V_{in} \sin \omega_{in} t$$

$$v_o = V_{out} \sin \omega_{out} t$$

tegangan *error* sesaat dari output detektor phasa adalah :

⁸ Hioki. Warren. "Telecommunication Third Edition". Prentice-Hall International.Inc. 1998. USA. Hal 94

$$v_e = v_{in} * v_{out} = V_{in} \sin \omega_{in} t * V_{out} \sin \omega_{out} t$$

$$v_e = \frac{1}{2} V_{in} V_{out} [\cos(\omega_{in} - \omega_{out})t - \cos(\omega_{in} + \omega_{out})t]$$

Persamaan diatas terdapat dua bentuk persamaan penjumlahan dan pengurangan, dengan memfilter bentuk penjumlahan dan menguatkan bentuk pengurangan diperoleh tegangan kendali VCO.

$$V_c = \frac{1}{2} A_V V_{in} V_{out} [\cos(\omega_{in} - \omega_{out})t]$$

berdasarkan persamaan diatas diperoleh bahwa saat kondisi terkunci ($f_{in} = f_{out}$), $\omega_{in} - \omega_{out}$ adalah sama dengan nol dan tegangan kendali VCO, V_c menjadi sebuah tegangan DC tetap. level tegangan ini diperlukan PLL untuk menjaga peguncian terhadap sinyal input. Apabila frekuensi sinyal input berubah, tegangan kendali VCO juga ikut berubah dan menyebabkan frekuensi output VCO juga berubah.

➤ LPF (*Low Pass Filter*)

Rangkaian filter ini sebagaimana telah dikemukakan diatas berfungsi memfilter sinyal frekuensi tinggi dari detektor phasa agar tidak dikuatkan sehingga hanya sinyal dibawah frekuensi cutoff saja yang diteruskan.

➤ VCO (*Voltage Controlled Oscillator*)

Merupakan salah satu jenis oscilator yang dapat dirubah dengan memberikan bias tegangan, teknik yang paling sederhana untuk melakukan pengendalian ini dengan menggunakan dioda varactor.

➤ Frekuensi Referensi

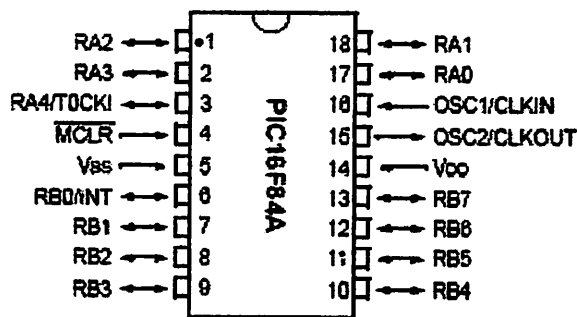
Frekuensi referensi harus mempunyai ketelitian dan kestabilan yang tinggi sehingga digunakan oscilator kristal sebagaimana diketahui kristal mempunyai nilai Q yang tinggi. Fungsi dari bagian ini adalah sebagai frekuensi inputan yang dibandingkan dengan frekuensi tinggi VCO.

➤ Divider

Fungsi rangkaian ini adalah mencacah frekuensi keluaran dari VCO sehingga sama dengan frekuensi dari oscilator referensi, rangkaian ini akan terus melakukan pencacahan sampai diperoleh frekuensi outputnya sama dengan frekuensi referensi.

2.10. Mikrokontroler PIC16F84

Merupakan salah satu mikrokontroler yang dikeluarkan oleh perusahaan Microchip.Inc dari keluarga PIC16Fxx, yang dikemas dalam bentuk *DIP (Dual in Line Package)* ,dengan menggunakan ICSP bentuk fisik dari mikrokontroler ini sebagaimana gambar berikut :



Gambar 2-6. Pin Diagram PIC16F84⁹

⁹ <http://www.microchip.com/>

➤ Teknikasi Referensi

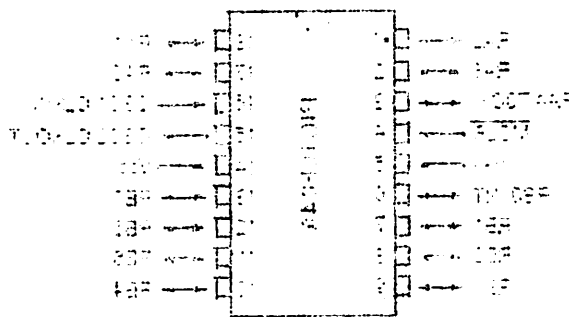
Teknikasi referensi harus mempunyai ketelitian dan kestabilan yang tinggi sehingga digunakan sebagai osilator kristal sebagaimana diketahui kristal mempunyai nilai Q yang tinggi. Fungsi dari bagian ini adalah sebagai teknikasi inpuran yang dibandingkan dengan teknikasi tinggi VCO.

➤ Deviator

Fungsi rangkaian ini adalah menaruh teknikasi keluaran dari VCO sehingga sama dengan teknikasi dari osilator referensi. rangkaian ini akan terus melakukan pencaharian sampai diperoleh teknikasi outputnya sama dengan teknikasi referensi.

2.10. Mikrokontroler PIC16F84

Merupakan salah satu mikrokontroler yang dikembangkan oleh perusahaan Microchip, Inc dari keluarga PIC16Fx yang dikemas dalam bentuk DIP (Dual in Line Package). dengan menggunakan ICSP bentuk fisik dari mikrokontroler ini sebagaimana gambar berikut :



Gambar 2-6. Pin Diagram PIC 16F84⁵

⁵ <http://www.microchip.com>

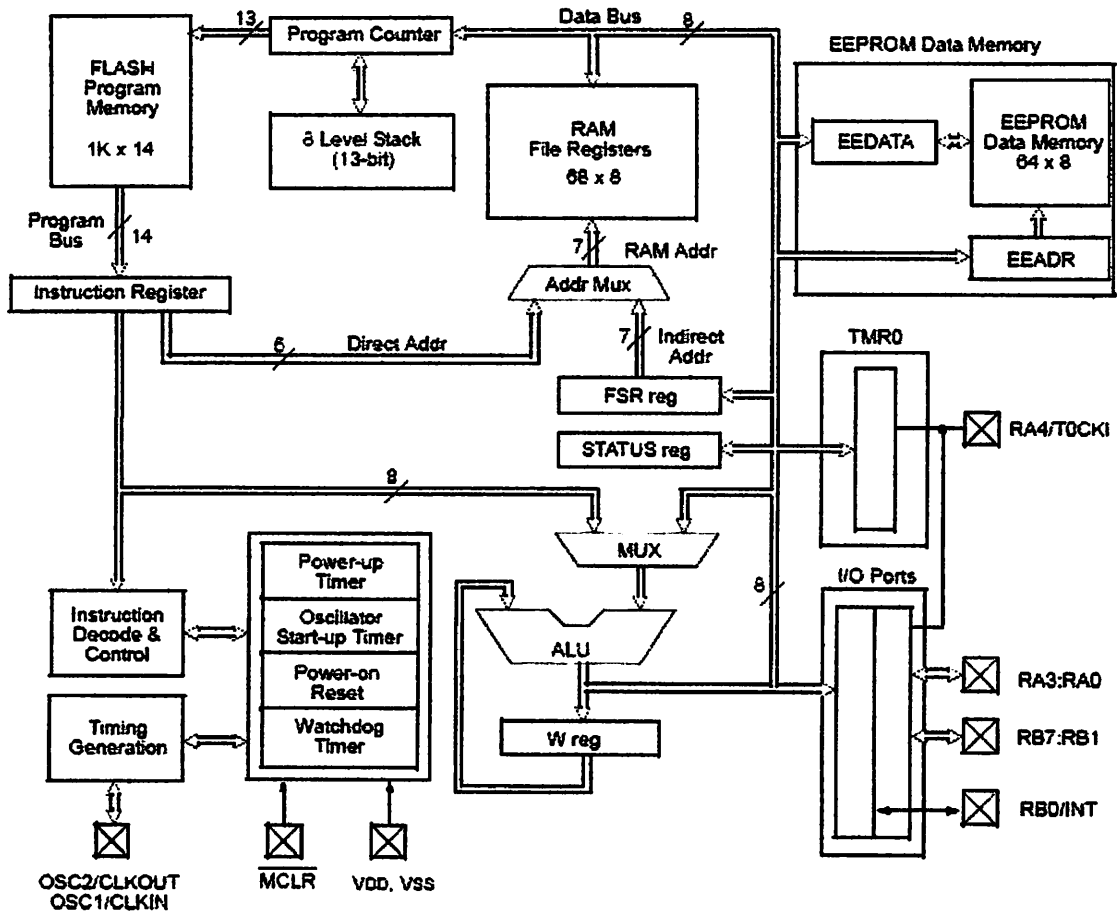
Fungsi Pin- pin pada mikrokontroler PIC16F84 :

1. OSC1/CLKIN : Input sumber clock external atau input oscilator kristal.
2. OSC2/CLKOUT : output oscilator kristal. Dihubungkan ke kristal atau resonator pada mode oscilator kristal. Pada mode RC, pin OSC2 mengeluarkan CLKOUT, yang mempunyai $\frac{1}{4}$ frekuensi OSC1 dan menyatakan kecepatan cycle instruksi.
3. MLCR : Tegangan input Master Clear / reset, aktif *low* akan mereset mikrokontroler.
4. RA0-RA4 : PortA input output dua arah, untuk RA4/TOCK1 dapat berfungsi sebagai input clock TMR0 timer / counter. Outputnya *Open Drain*.
5. RB0- RB7 : PortB input output dua arah, dapat diprogram untuk pull-up internal melalui software. RB0/INT juga berfungsi sebagai input interrupt, RB4-RB7 dapat difungsikan sebagai pin interrupt, RB6-RB7 digunakan sebagai jalur clock dan data pada komunikasi serial.
6. Vss : Ground bagi pin- pin I/O.
7. Vdd : jalur positif bagi pin- pin I/O.

2.10.1. Arsitektur mikrokontroler

Mikrokontroler PIC16Fxx merupakan mikrokontroler dari keluarga RISC (*Reduce Instruction Set Command*), yaitu mikrokontroler yang memori data dan

memori programnya mempunyai bus sendiri, hal ini sebagaimana ditunjukkan dalam Gambar berikut :



Gambar 2-7. Arsitektur MCU PIC16F84 ¹⁰

Feature dari mikrokontroler PIC16F84 :

1. 35 instruksi
2. Instruksi hanya 1 *cycle* terkecuali instruksi percabangan dan lompatan 2 *cycle*.

¹⁰ <http://www.microchip.com/>

3. 1024 memori program
4. 68 byte memori data RAM
5. 64 byte memori data EEPROM
6. lebar memori program 14 bit
7. lebar memori data 8 bit
8. mempunyai 15 SFR (*Special Function Register*)
9. 8 level stack
10. mempunyai 4 sumber interrupt :
 - a. interrupt eksternal pin RB0/ INT
 - b. overflow dari TMR0
 - c. PORTB.4 – PORTB7
 - d. Proses penulisan pada EEPROM lengkap.

2.10.2. Organisasi Memori

Pada mikrokontroler PIC terdapat dua block memori yaitu memori program dan memori data, dengan masing –masing memiliki bus tersendiri, sehingga dapat dilakukan pengaksesan secara bersamaan.

Memori data kelompokan menjadi *general perpose RAM* dan *Special Function Register(SFRs)*. Disamping itu terdapat pula memori data EEPROM yang mempunyai metode pengalamatan sendiri.

➤ Memori Program

PIC dari keluarga PIC16Fxx mempunyai 13 bit program counter sehingga mampu mengamati sampai 8Kx14 spasi memori program, untuk PIC16F84 1Kx14 pertama diimplementasikan secara khusus, pengaksesan

3. 1024 memori program
4. 68 byte memori data RAM
5. 64 byte memori data EEPROM
6. lebar memori program 14 bit
7. lebar memori data 8 bit
8. mempunyai 13 SPK (Special Function Register)
9. 8 level stack
10. mempunyai 4 sumber interrupt :
 - a. interrupt eksternal pin RINT
 - b. overflow dari TIMER
 - c. PORTB4 – PORTB7
 - d. Proses penulisan pada EEPROM lengkap.

2.10.2. Organisasi Memori

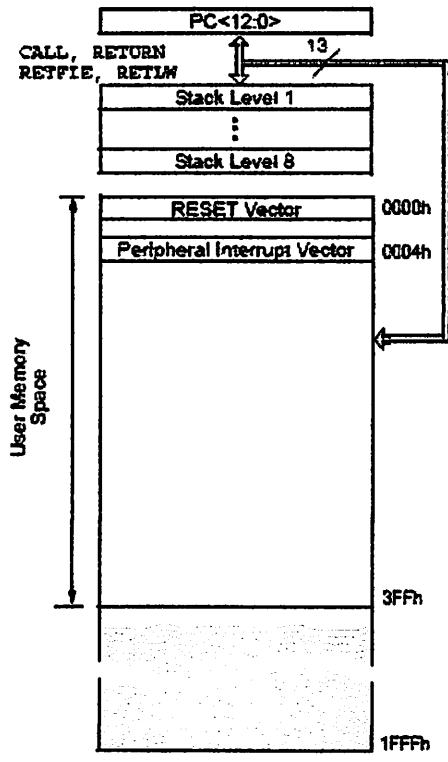
Pada mikrokontroler PIC terdapat dua block memori yaitu memori program dan memori data. dengan masing – masing memiliki bus tersendiri. sehingga dapat dilakukan pengaksesan secara bersamaan.

Memori data kelompokkan menjadi general purpose RAM dan Special Function Register(SFRs). Disamping itu terdapat pula memori data EEPROM yang mempunyai metode pengalamatan sendiri.

• Memori Program

PIC dari keluarga PIC16xx mempunyai 13 bit program counter sehingga mampu menggunakan sampai 8Kx14 spesi memori program. Untuk PIC16F84 1Kx14 program diimplementasikan secara khusus. pengaksesan

terhadap bagian ini akan menimbulkan masalah sehingga untuk lokasi 20h, 420h, 820h, c20h, 1020h, 1420h, 1820h, dan 1c20h instruksinya akan sama.



Gambar 2-7. Peta Memori Program PIC16F84¹¹

Vector Reset berada pada alamat 0000h sedangkan vector interrupt berada pada alamat 0004h.

➤ **Memori Data**

Memori data dipisahkan menjadi dua wilayah, yang pertama adalah register fungsi khusus atau SFR, dan kedua wilayah Register tujuan umum atau GPR, SFR berfungsi sebagai pengendali kerja dari perangkat.

¹¹ <http://www.microchip.com/>

File Address	Indirect addr. ⁽¹⁾	Indirect addr. ⁽¹⁾	File Address
00h	Indirect addr. ⁽¹⁾	Indirect addr. ⁽¹⁾	80h
01h	TMR0	OPTION_REG	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h	—	—	87h
08h	EEDATA	EECON1	88h
09h	EEADR	EECON2 ⁽¹⁾	89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch			8Ch
	68 General Purpose Registers (SRAM)	Mapped (accesses) in Bank 0	
4Fh			CFh
50h			D0h
7Fh			Fh
	Bank 0	Bank 1	

□ Unimplemented data memory location, read as '0'.
 Note 1: Not a physical register.

Gambar 2-8. Peta Register File PIC16F84¹²

Kapasitas memori data dibank kan untuk kedua SFR maupun GPR, wilayah GPR dibankan untuk mengijinkan lebih besar 116 byte, sedangkan wilayah bank SFR adalah untuk mengendalikan fungsi peripheral, untuk melakukannya diperlukan bit yang mengatur perpindahan antar bank yang diletakan pada register STATUS yaitu pada bit RP0.

¹² <http://www.microchip.com/>

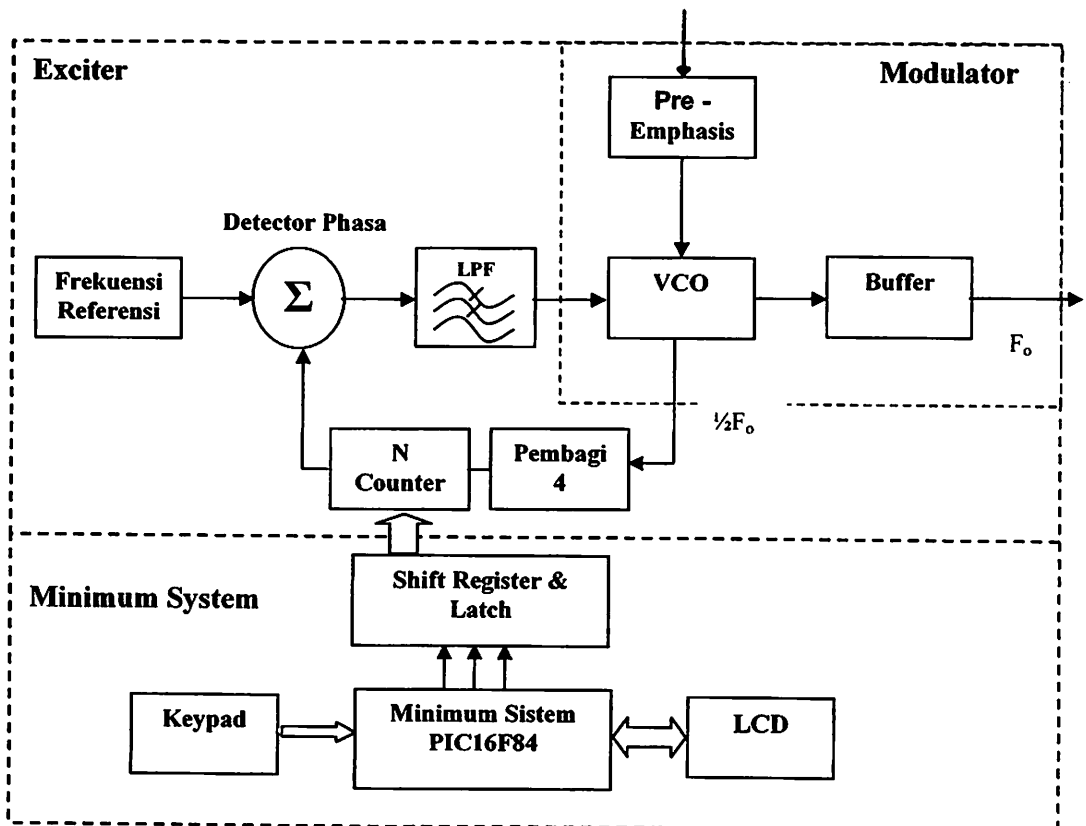
BAB III

PERENCANAAN DAN PEMBUATAN ALAT

3.1. Gambaran Umum

Alat yang dirancang berfungsi sebagai pembangkit sinyal carrier pada transmitter FM dengan kekuatan daya pancar 1 Watt menggunakan sistem pengendalian PLL berbasis mikrokontroler.

Pada bab III ini hanya membahas tentang perencanaan dan realisasinya pada sistem transmitter berbasis PLL. Adapun diagram blok dari alat yang dirancang sbb:



Gambar 3-1. Diagram Blok Exciter FM

3.2. Perancangan Alat

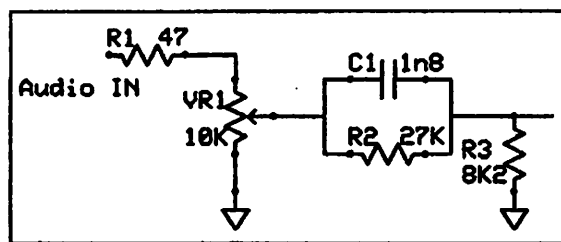
Pada transmitter ini terdapat tiga hal pokok yang hendak dirancang, yaitu : Unit RF, Unit PLL, Unit Minimum Sistem, dengan masing- masing bagian terdapat sub bagian, sebagai berikut :

1. Unit RF
 - a. Pre-Emphasis
 - b. LPF (*Low Pass Filter*)
 - c. VCO (*Voltage Controlled Oscillator*)
 - d. Penguat Penyangga / Buffer
2. Unit PLL
 - a. Oscilator Lokal
 - b. Detektor Fasa
 - c. Pembagi 4
 - d. N Counter
3. Unit Minimum Sistem PIC16F84

3.2.1. Unit RF

3.2.1.1. Pre- Emphasis

Untuk menyeragamkan level audio pada seluruh range frekuensinya diperlukan komponen yang mampu menaikkan level audio untuk frekuensi yang lebih tinggi. FCC menyatakan konstanta waktu $\tau = RC = 75\mu\text{S}$ untuk USA dan $50\mu\text{S}$ untuk Inggris.



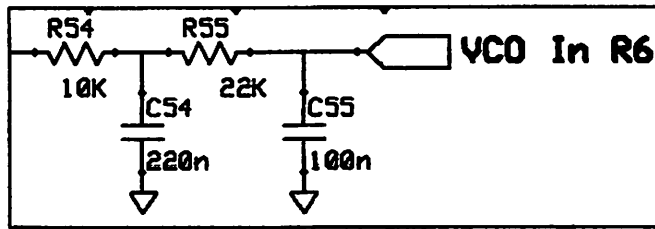
Gambar 3-2. Skematik Rangkaian Pre – Emphasis

Untuk $\tau = RC = 75\mu\text{S}$.

$$\begin{aligned}\tau &= R2 * C1 \\ &= 27.10^3 * 1,8.10^{-9} \\ &= 48,6\mu\text{S}\end{aligned}$$

3.2.1.2. LPF (*Low Pass Filter*)

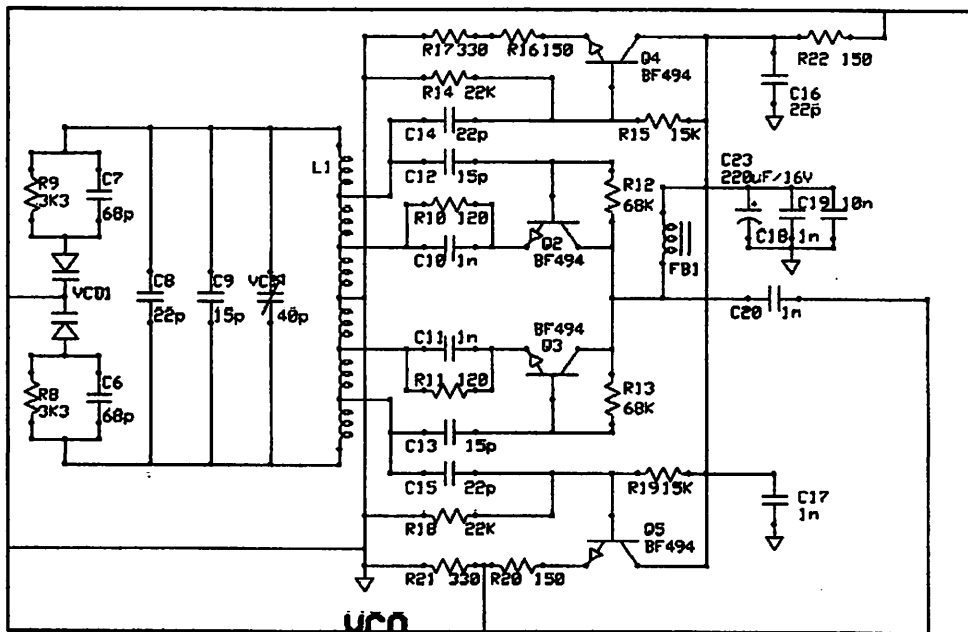
Karakteristik utama sistem PLL sepenuhnya ditentukan oleh bagian ini, dua fungsi utama filter adalah menghilangkan komponen frekuensi tinggi dan noise dari keluaran detektor fasa, LPF direncanakan menggunakan komponen passive, seperti dalam gambar 3-3.



Gambar 3-3. LPF (Low Pass Filter)

3.2.1.3. VCO (Voltage Controlled Oscillator)

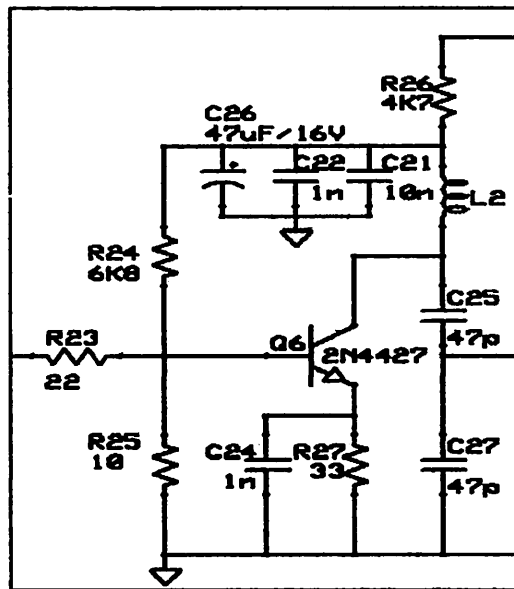
Sebelum signal audio dipancarkan terlebih dahulu harus dimodulasikan ke rangkaian modulator FM, dimana perubahan amplitudo signal informasi tersebut dirubah ke dalam bentuk perubahan frekuensi carrier. Adapun bentuk dari oscilator menggunakan jenis hartley yang berkerja secara antiphase, sehingga satu oscilator bekerja pada separuh dari frekuensi outputnya. Adapun bentuk VCO yang direncanakan :



Gambar 3-4. Rangkaian VCO

3.2.1.4. Penguat Penyangga/ Buffer

Rangkaian buffer disini berfungsi sebagai pemegang kestabilan dari osilator modulator ketika dibebani rangkaian selanjutnya. Konfigurasi rangkaian menggunakan kelas A dengan transistor 2N4427A. Tujuan digunakan rangkaian kelas A supaya signal output tetap linier. Berikut gambar rangkaian buffer:

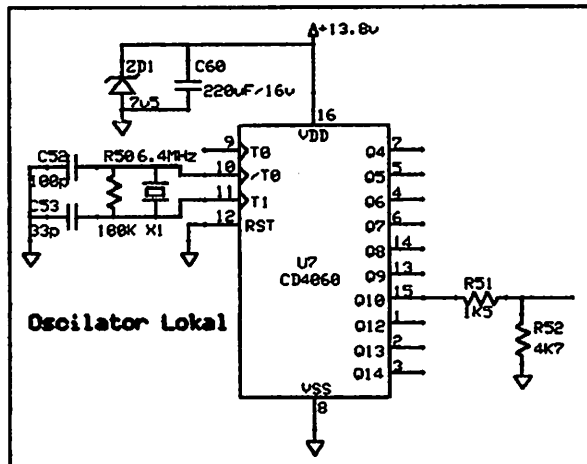


Gambar 3-5. Rangkaian Buffer

3.2.2. Unit PLL

3.2.2.1. Oscilator Lokal

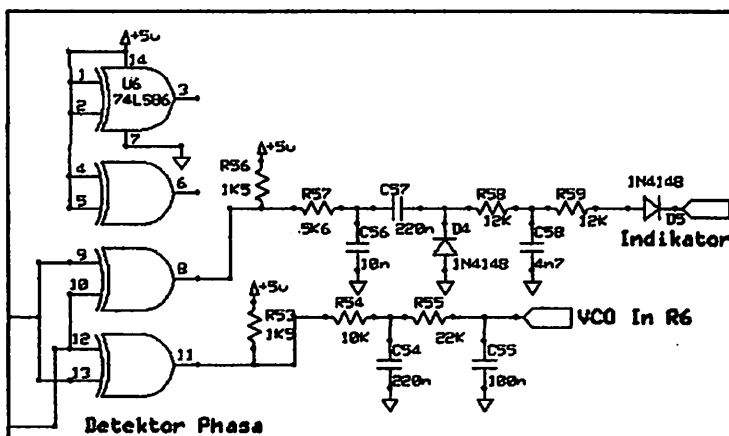
Sebelum phase detector bekerja, diperlukan osilator referensi yang dibentuk dari kristal osilator fundamental 6.4 MHz yang dibentuk dengan IC TTL agar didapat bentuk signal square. Kemudian frekuensi 6.4 MHz ini dibagi menggunakan IC CMOS HCF4060 14-Stage Ripple Counter dengan pembagi 1024 sehingga outputnya menjadi 6.25 KHz. Berikut adalah gambar rangkaian osilator referensi beserta pembaginya :



Gambar 3-5. Rangkaian Oscilator Lokal dan Pembagiya.

3.2.2.2. Detektor Fasa

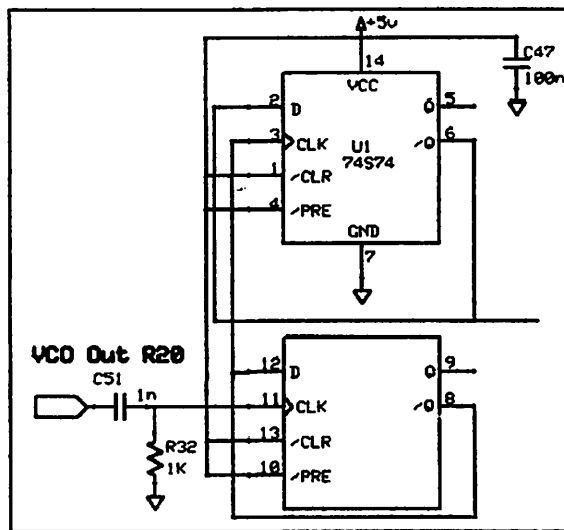
Rangkaian Detektor fasa menggunakan komponen TTL dari IC 74LS86 Quad 2-Input Exclusive OR, gerbang OR mempunyai sifat jika kedua inputnya berbeda maka outputnya *high* dan jika sama maka outputnya *low*, rangkaian menerima signal persegi dari oscillator local yang merupakan sumber frekuensi referensi dan dari N Divider yang merupakan signal dari VCO yang telah turunkan. Karena inputnya kontinu output dari rangkaian akan diperoleh signal PWM (*Pulse width modulation*) dengan mengambil level DC yang digunakan untuk tegangan koreksi VCO, berikut adalah gambar rangkaian detektor fasa:



Gambar 3-6. Rangkaian Detektor Fasa

3.2.2.3. Pembagi 4

Untuk menurunkan singal dari VCO diperlukan rangkaian pembagi yang dibentuk dari IC 74ALS74 D Flip Flop sebelum diberikan ke N Counter, untuk memperoleh pembagian sebesar 4 kali diperlukan dua Flip flop, adapun bentuk rangkaiannya seperti berikut :



Gambar 3-7. Rangkaian Pembagi 4

3.2.2.4. N Counter

Setelah oscillator carrier audio modulator dihasilkan, maka sebelum fasanya dibandingkan dibagian phase detector terlebih dahulu dibagi frekuensinya menyesuaikan besarnya frekuensi referensi phase detector agar phase output dihasilkan nilai *low* yang berarti tidak ada perbedaan fasa antara frekuensi set dan frekuensi referensi, ini berarti juga bahwa frekuensi modulator tetap terjaga. Untuk membagi frekuensi set diperlukan komponen 74LS193 BCD/ Decade Counter. Rumusnya adalah :

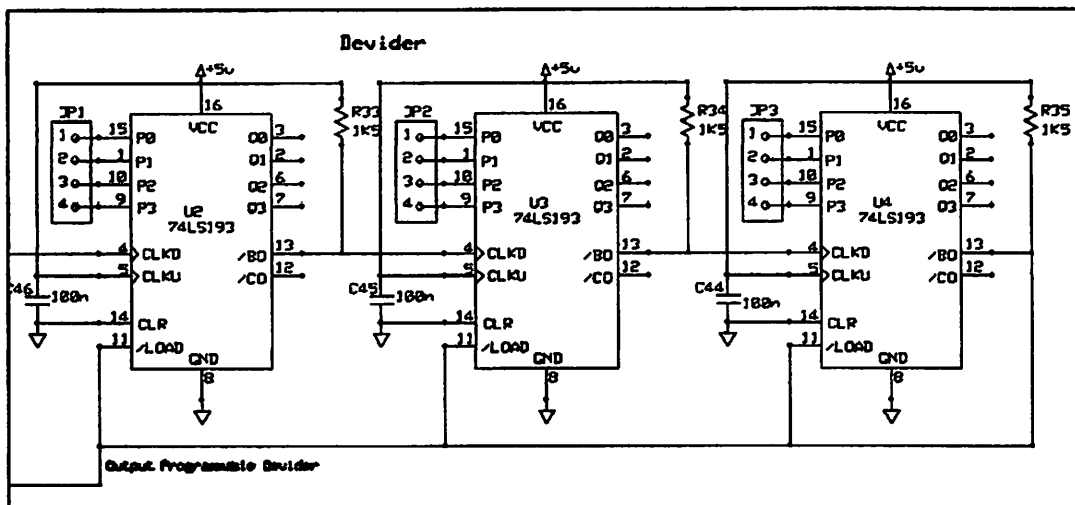
$$N_s = \frac{f_{modulator}}{f_{referensi}}$$

$$N_s = \frac{12.5 \cdot 10^6}{6.25 \cdot 10^3} = 2000$$

Sedangkan rumus untuk mendapatkan frekuensi set adalah :

$$f_s = \frac{f_{\text{modulator}}}{N_s} \quad f_s = \frac{12.5 \cdot 10^6}{2000} = 6.25 \text{ KHz}$$

Berikut adalah gambar rangkaian Programmable Divider 74LS193 :



Gambar 3-8. Rangkaian N Divider

3.2.3. Unit Minimum Sistem

Bagian ini merupakan bagian pemroses pusat, komponen utamanya menggunakan mikrokontroler PIC16F84, sebagai inputan digunakan 3 tombol push button yang berfungsi untuk menaikkan dan menurunkan nilai data biner untuk menset N counter, yang dikeluarkan melalui Pin RA1 secara serial ke IC 74HC595 shift dan latch register, data pencacahan yang dikirimkan oleh mikrokontroler kemudian dikirimkan ke LCD dan bentuk nilai frekuensinya. Adapun bentuk rangkaian keseluruhan minimum system PIC16F84 sebagai berikut :


```

        ; debounce
    endif
    if hilo ==0 ; pull up
    ifbit port,pin,exit1 ; jika satu, tombol tidak ditekan
        pausems debouncedelay ; delay 10ms
debounce

pushed1
    ifnotbit port,pin,pushed1
        pausems debouncedelay ; menunggu hingga dilepaskan dan
        goto label ; melompat ke label yang ditentukan

    exit1
    else ; pull down
    ifnotbit port,pin,exit2 ; jika nol, tombol tidak ditekan
        pausems debouncedelay ; delay 10ms untuk debounce

pushed2
    ifbit port,pin,pushed2
        pausems debouncedelay ; menunggu hingga
tombol dilepaskan
        goto label
    exit2

```

2. Rutin H595.inc²

Rutin ini menangani operasi pengiriman data dari mikro ke Shift register dan latch 74HC595, yang dikirimkan adalah data, clock, dan latch, adapun bentuk rutinya sebagai berikut :

```

hc595    macro    var,var1

    local    loop
    movlw   .8
    movwf   var1

loop     rlf     var,f

    btfss   STATUS,C
    bcf     data
    btfsc   STATUS,C

```

² <http://www.mikroe.com/>

```

bsf    data

bsf    Clock
nop
bcf    Clock

decfsz var1,f
goto   loop

bsf    latch
nop
bcf    latch
endm

```

3. Rutin LCD.inc³

Rutin ini menangani kerja pengiriman dan pembacaan dari dan ke LCD, adapun program untuk rutin ini adalah :

```

CONSTANT FUNCTSET8 = b'00110000'
CONSTANT FUNCTSET4 = b'00100000'
CONSTANT DDZERO    = b'10000000'

```

```

CONSTANT LCD2L      = b'00101000'
CONSTANT LCDCONT    = b'00001100'

```

```

CONSTANT LCDSH      = b'00101000'

```

; Data Perintah menampilkan ke LCD

```

CONSTANT LCDCLR     = b'00000001'
CONSTANT LCDCH      = b'00000010'
CONSTANT LCDCL      = b'00000100'
CONSTANT LCDCR      = b'00000110'
CONSTANT LCDSL      = b'00011000'

```

```

CONSTANT LCDSR      = b'00011100'

```

```

CONSTANT LCDL1      = b'10000000'
CONSTANT LCDL2      = b'11000000'

```

```

*****
;
; Inisialisasi LCD
*****
;

```

³ <http://www.mikroe.com/>

```

lcdinit    macro

    bank1
    clr    LCDdsport
    bank0

    call   Delay1ms
    call   Delay1ms
    call   Delay1ms
    call   Delay1ms
    movlw  FUNCTSET8
    call   SendW
    call   Delay1ms
    call   Delay1ms
    movlw  DDZERO
    call   SendW

    movlw  FUNCTSET4
    call   SendW

```

;Perintah menginisialisasi LCD

```

lcdcmd LCD2L
lcdcmd LCDCONT
lcdcmd LCDSH
lcdcmd LCDCLR
endm

```

```

;*****
;
; lcdcmd mengirim perintah ke LCD
; lcd clr berarti sama dengan lcdcmd 0x01
;*****
;

```

```

lcdcmd    macro    LCDcommand
    movlw    LCDcommand
    call     LCDcomd
endm

```

```

lcdclr    macro
    movlw    LCDCLR
    call     LCDcomd
endm

```

```

LCD_DDAdr    macro    DDRamAddress
    local    value = DDRamAddress | 0x80
    movlw    value
    call     LCDcomd

```

```

                                endm

LCDcomd    clrf    LCDbuf
            goto   LCDDwr

LCDdata    clrf    LCDbuf
            bsf    LCDbuf,RS

LCDDwr     movwf   LCDtemp
            andlw  b'11110000'
            iorwf  LCDbuf,w
            call   SendW
            swapf  LCDtemp,w
            andlw  b'11110000'
            iorwf  LCDbuf,w
            call   SendW
            return

```

```

SendW
    clrf    LCDdsport
    movwf   LCDdsport
    call    Delay1ms
    bsf    LCDdsport,EN
    bcf    LCDdsport,EN
    call    Delay1ms
    clrf    LCDdsport
    return

```

```

.....
;
; macro lcdtext mampu mencetak 16 karakter yang dinyatakan
; macro parameter. parameter 1, select, pilih baris untuk
; ditampilkan
; jika select = 0, text dicetak dari posisi cursor secara langsung
.....

```

```

lcdtext    macro    select,text
            local   Message
            local   Start
            local   Exit
            local   i=0
            goto    Start

```

```

dt text
dt 0

```

```

Start
if select ==1
    lcdcmd LCDL1
else

```

```

if select ==2
    lcdcmd LCDL2
endif
endif
while i<16
    call Message+1
    addlw 0
    bz Exit
    call LCDdata
i=i+1
endw
Exit
endm

```

```

.*****
;
; macro mencetak 1 byte ke LCD
.*****
;

```

```

lcdbyte macro arg0
    digbyte arg0

    movf Dig1,w
    btfsc STATUS,Z
    movlw 0x0f0
    addlw 0x030
    call LCDdata

    movf Dig2,w
    btfsc STATUS,Z
    movlw 0x0f0
    addlw 0x030
    call LCDdata

    movf Dig3,w
    addlw 0x030
    call LCDdata

endm

```

```

Delay1ms:
    movlw .100
    movwf LOOPcnt

```

```

Delay10us:
    nop
    nop
    nop
    nop
    nop

```

```
    nop
    nop

    decfsz LOOPcnt,f
    goto   Delay10us

    return

endif
endm
```


BAB IV

PENGUJIAN ALAT

4.1. Tujuan

Bab ini membahas tentang pengujian alat yang telah dibuat. Secara umum, pengujian ini bertujuan untuk mengetahui apakah piranti yang telah direalisasikan dapat bekerja sesuai dengan spesifikasi yang telah direncanakan. Pada tugas akhir ini pengujian dilakukan terhadap beberapa subsistem yang meliputi:

- Pengujian Pre –Emphasis
- Pengujian VCO
- Pengujian Detektor Phasa
- Pengujian Oscilator Lokal
- Pengujian PLL.

4.2. Pengujian Pre- Emphasis

4.2.1. Tujuan

Mengetahui level audio pada setiap range frekuensi audio

4.2.2. Peralatan yang digunakan

1. Oscilloscope Hewlett Packard type HP54600A 100MHz 2 Channel
2. Function Generator GW Model GFG-80206
3. Rangkaian Pre- Emphasis
4. Kabel Probe

4.2.3. Prosedur Pengujian

BAB IV PENGUJIAN ALAT

4.1. Tujuan

Bab ini membahas tentang pengujian alat yang telah dibuat. Secara umum, pengujian ini bertujuan untuk mengetahui apakah piranti yang telah direalisasikan dapat bekerja sesuai dengan spesifikasi yang telah dirumuskan. Pada tugas akhir ini pengujian dilakukan terhadap beberapa sub-sistem yang meliputi:

- > Pengujian Pre-Empbasis
- > Pengujian VCO
- > Pengujian Detektor Phasa
- > Pengujian Oscillator Lokal
- > Pengujian PLL

4.2. Pengujian Pre-Empbasis

4.2.1. Tujuan

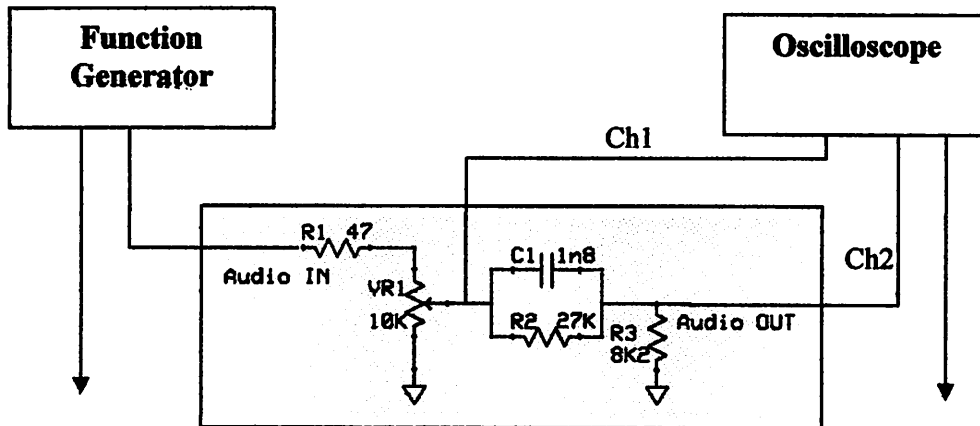
Mengetahui level audio pada setiap range frekuensi audio

4.2.2. Peralatan yang digunakan

1. Oscilloscope Hewlett Packard type HP-54000A 100MHz 2 Channel
2. Function Generator GW Model GFG-80200
3. Rangkaian Pre-Empbasis
4. Kabel Probe

4.2.3. Prosedur Pengujian

1. Merangkai Peralatan yang digunakan sesuai Gambar 4-1 berikut:



Gambar 4-1. Pengukuran Rangkaian Pre- Emphasis

2. Mengaktifkan Function Generator pada Sinus 5V_{P-P}.
3. Mengamati sinyal output pada oscilloscope dan mencatat pada Tabel 4-1.
4. Mengulangi Langkah 2 dan 3 untuk nilai frekuensi yang berbeda.

4.2.4. Hasil Pengujian

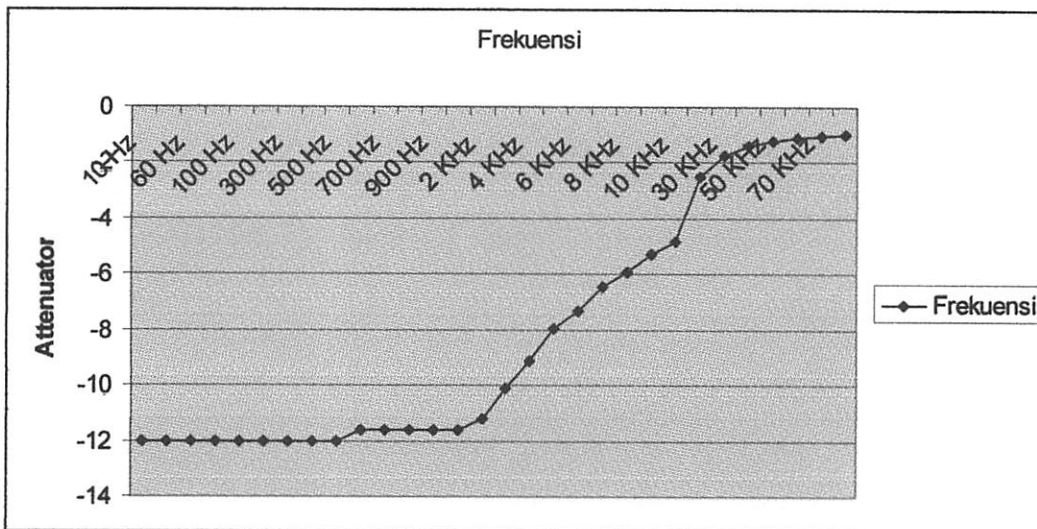
Tabel 4-1. Data Hasil Pengukuran Pre-Emphasis

No.	Frekuensi	V _{in} (V _{P-P})	Pre - Emphasis	
			V _{Out} (V _{P-P})	dB
1	10 Hz	5 V	1.250	-12.041
2	30 Hz	5 V	1.250	-12.041
3	60 Hz	5 V	1.250	-12.041
4	90 Hz	5 V	1.250	-12.041
5	100 Hz	5 V	1.250	-12.041
6	200 Hz	5 V	1.250	-12.041
7	300 Hz	5 V	1.250	-12.041
8	400 Hz	5 V	1.250	-12.041
9	500 Hz	5 V	1.250	-12.041
10	600 Hz	5 V	1.312	-11.621
11	700 Hz	5 V	1.312	-11.621
12	800 Hz	5 V	1.312	-11.621
13	900 Hz	5 V	1.312	-11.621
14	1 KHz	5 V	1.312	-11.621
15	2 KHz	5 V	1.375	-11.213

16	3 KHz	5 V	1.562	-10.106
17	4 KHz	5 V	1.750	-9.119
18	5 KHz	5 V	2	-7.959
19	6 KHz	5 V	2.156	-7.306
20	7 KHz	5 V	2.375	-6.466
21	8 KHz	5 V	2.531	-5.914
22	9 KHz	5 V	2.719	-5.291
23	10 KHz	5 V	2.875	-4.807
24	20 KHz	5 V	3.750	-2.499
25	30 KHz	5 V	4.094	-1.736
26	40 KHz	5 V	4.250	-1.412
27	50 KHz	5 V	4.344	-1.222
28	60 KHz	5 V	4.406	-1.099
29	70 KHz	5 V	4.437	-1.038
30	80 KHz	5 V	4.469	-0.975

4.2.5. Kesimpulan

1. Grafik Respon Frekuensi terhadap Attenuator dalam dB :



Grafik 4-1. Respon Frekuensi terhadap Attenuator.

2. Dari grafik diperoleh besar slope sebesar 6.33 dB / Octave

4.3. Pengujian VCO

4.3.1. Tujuan

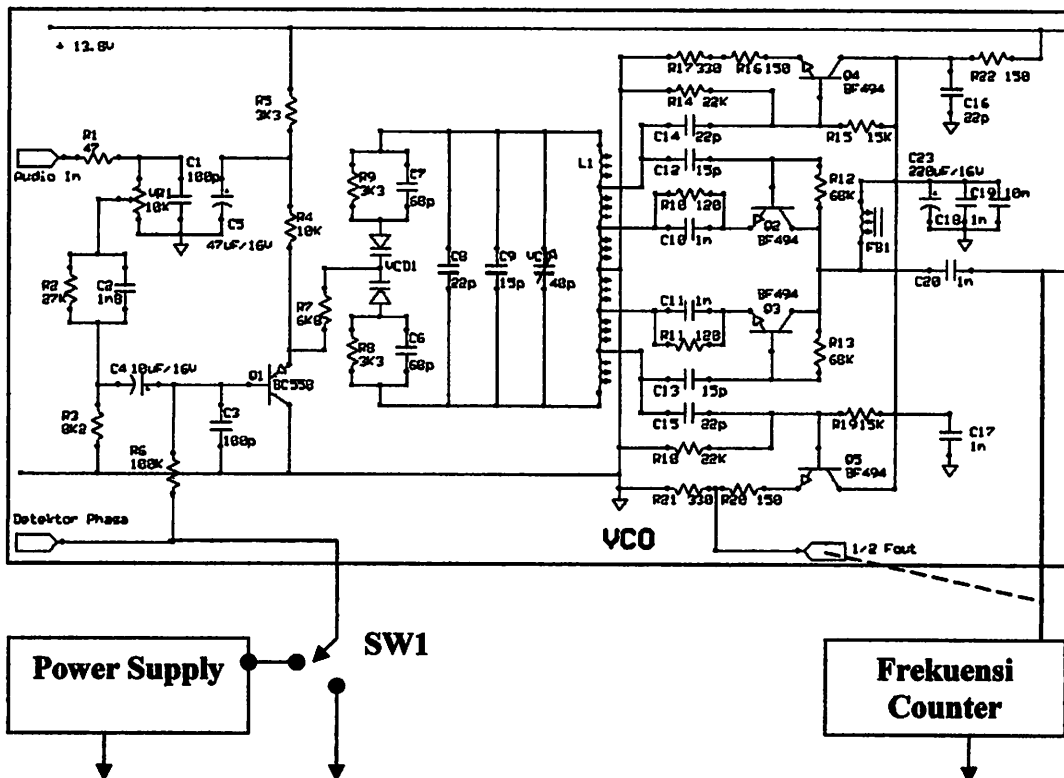
Untuk mengetahui frekuensi dasar, range frekuensi, respon frekuensi

4.3.2. Peralatan Yang Digunakan :

1. Oscilloscope Hewlett Packard type HP54600A 100MHz 2 Channel
2. Frequency Counter GW model GFC-8131
3. Power Supply ED2900
4. Rangkaian VCO
5. Kabel, Probe.

4.3.3. Prosedur Pengujian

1. Merangkai peralatan yang digunakan sesuai Gambar 4-2 berikut :



Gambar 4-2. Pengukuran VCO

4.3. Pengujian VCO

4.3.1. Tujuan

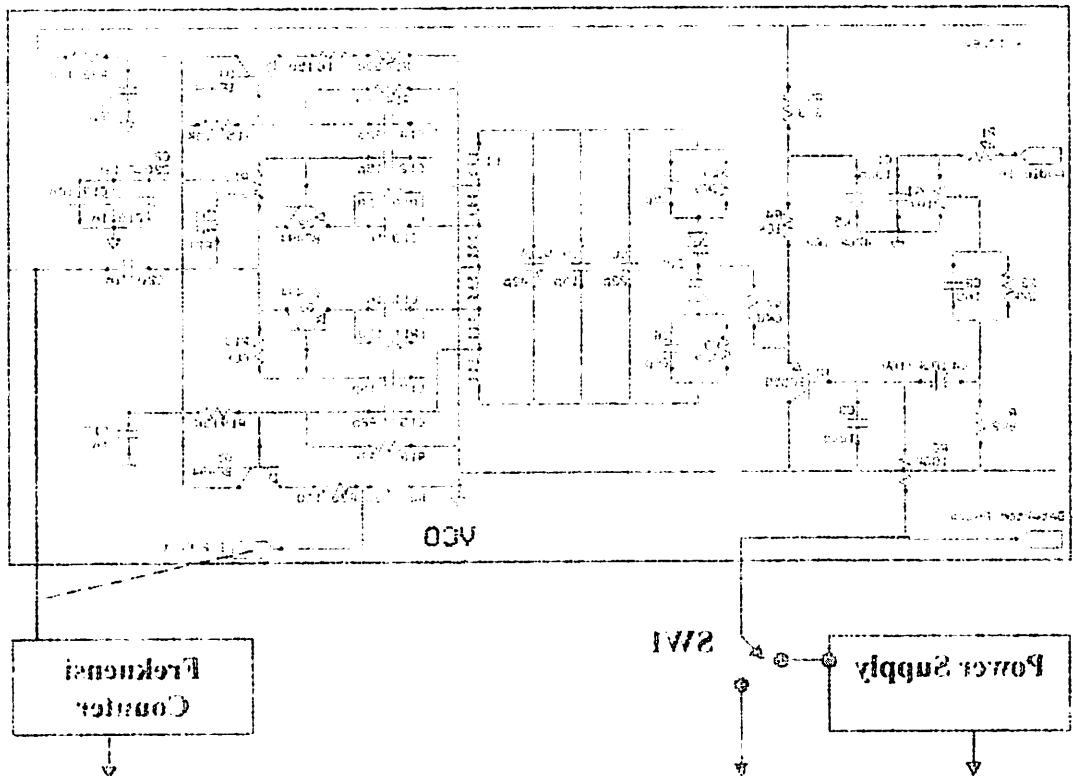
Untuk mengetahui frekuensi dasar, range frekuensi, respon frekuensi

4.3.2. Peralatan Yang Digunakan :

1. Oscilloscope Hewlett Packard type HP54600A 100MHz 2 Channel
2. Frequency Counter GW model GFC-8131
3. Power Supply BD2900
4. Rangkaian VCO
5. Kabel Probe

4.3.3. Prosedur Pengujian

1. Menangkai peralatan yang digunakan sesuai Gambar 4-2 berikut :



Gambar 4-2. Peralatan VCO

2. Mengaktifkan frekuensi counter dan VCO, switch ke ground.
3. Mengukur frekuensi pada R20 dan C20, serta mencatat hasilnya pada tabel 4-2.
4. Memindahkan Switch ke Power Supply ED-2900.
5. Menaikan Power Supply sebesar 0,1 Volt tiap stepnya
6. Mengukur Frekuensi pada R20 dan C20, mencatat nilainya pada tabel 4-2.

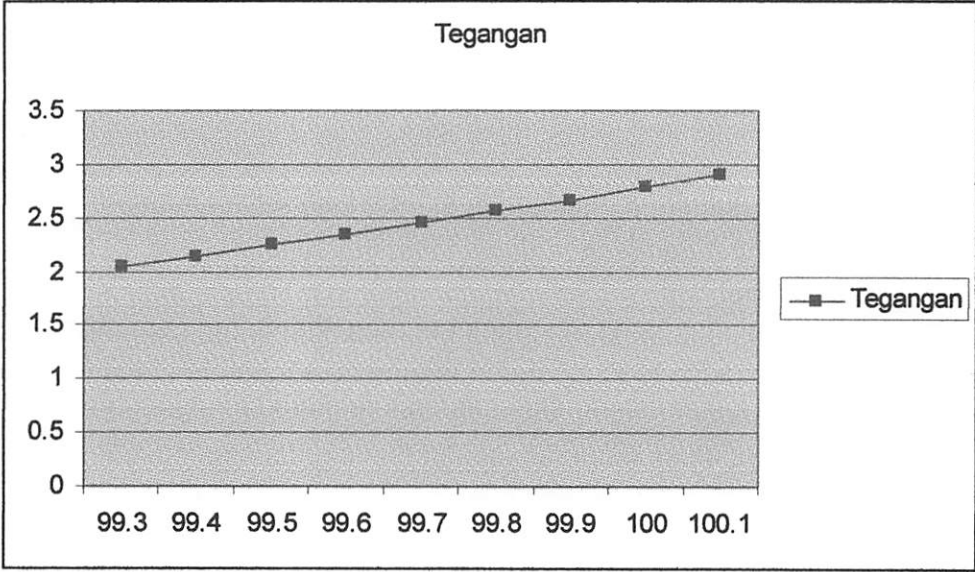
4.3.4. Hasil Pengujian

Tabel 4-2. Data Pengukuran VCO

No.	SW-Ground		SW ke Power Supply		
	F_{R20}	F_{C20}	$V_{R6}(\text{volt})$	$F_{R20}(\text{MHz})$	$F_{C20}(\text{MHz})$
1	50MHz	100MHz	2.05	99.3	49.65
2			2.15	99.4	49.7
3			2.25	99.5	49.75
4			2.35	99.6	49.8
5			2.46	99.7	49.85
6			2.56	99.8	49.9
7			2.67	99.9	49.95
8			2.79	100.0	50
9			2.91	100.1	50.05

4.3.5. Kesimpulan

1. Saat dioda varactor tidak terbias, VCO sudah mempunyai nilai frekuensi osilasi sebesar 100 MHz, hasil penjumlahan Frekuensi per oscilator 50MHz.
2. Grafik respon frekuensi output terhadap tegangan bias dc:



Grafik 4-2. Respon Frekuensi Terhadap Tegangan

4.4. Pengujian Detektor Fasa

4.4.1. Tujuan

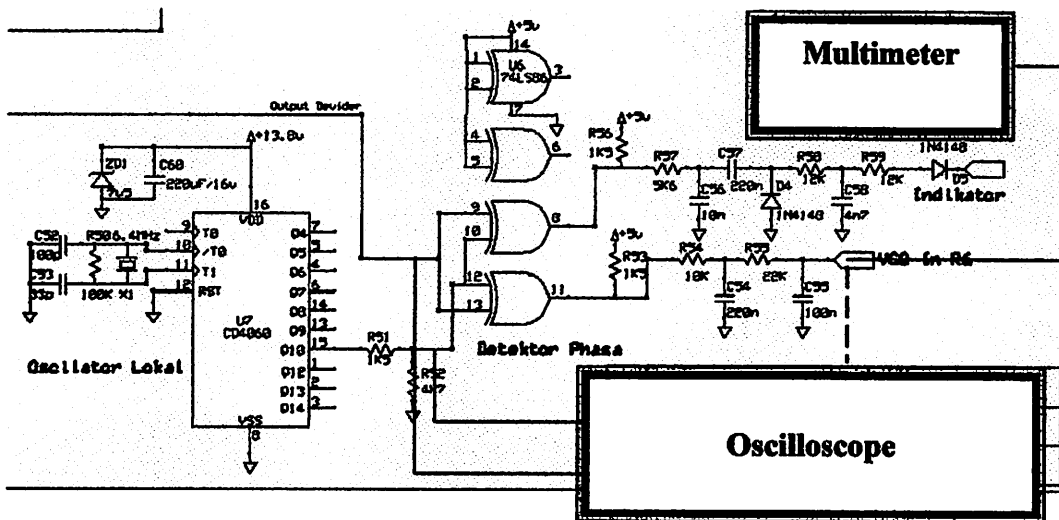
Mengetahui beda fasa dan tegangan outputnya.

4.4.2. Peralatan yang digunakan

1. Oscilloscope Hewlett Packard type HP54600A 100MHz 2 Channel
2. Multimeter Digital DT9202
3. Rangkaian Detektor Fasa
4. Power Supply
5. Kabel

4.4.3. Prosedure Pengujian

1. Merangkai peralatan yang digunakan sesuai Gambar 4-2 berikut :



Gambar 4-3. Pengukuran Rangkaian Detektor Fasa

2. Mengamati bentuk gelombang pada Oscilloscope dan mencatat nilai *Duty Cycle* saat kondisi terkunci pada tabel 4-3.

4.4. Pengujian Detektor Fasa

4.4.1. Tujuan

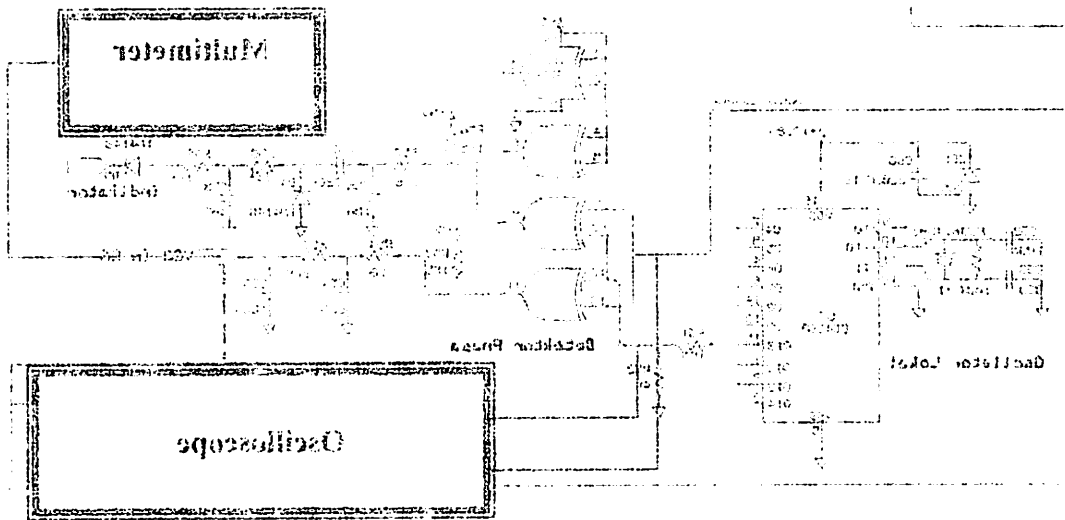
Mengetahui beda fasa dan tegangan outputnya.

4.4.2. Peralatan yang digunakan

1. Oscilloscope Model Packard tipe HP-400A 100MHz 2 Channel
2. Multimeter Digital D19202
3. Rangkaian Detektor Fasa
4. Power Supply
5. Kabel

4.4.3. Prosedur Pengujian

1. Menyalakan peralatan yang digunakan sesuai Gambar 4-2 berikut :



Gambar 4-2. Pengukuran rangkaian Detektor Fasa

2. Menganti bentuk gelombang pada Oscilloscope dan mencatat nilai

Wave Cycle and kondisi terminal pada tabel 4-3.

4.4.4. Hasil Pengujian

Tabel 4-3. Data Pengukuran Detektor Phasa

Frekuensi (MHz)	Duty Cycle (%)	Tegangan dc (Volt)
99.5	39.1	2.25
99.6	40.6	2.35
99.7	40.7	2.46
99.8	43.0	2.56
99.9	45.4	2.67
100	47.1	2.79
100.1	47.7	2.91
100.2	50.1	3.02

4.4.5. Kesimpulan

1. untuk menaikkan frekuensi maka diperlukan level tegangan DC yang naik pula, level tegangan ini diperoleh dari prosentase *dutycycle* yang semakin naik.
2. untuk kenaikan frekuensi sebesar 100KHz diperlukan kenaikan tegangan 0,1 volt

4.5. Pengujian Oscilator Lokal

4.5.1. Tujuan

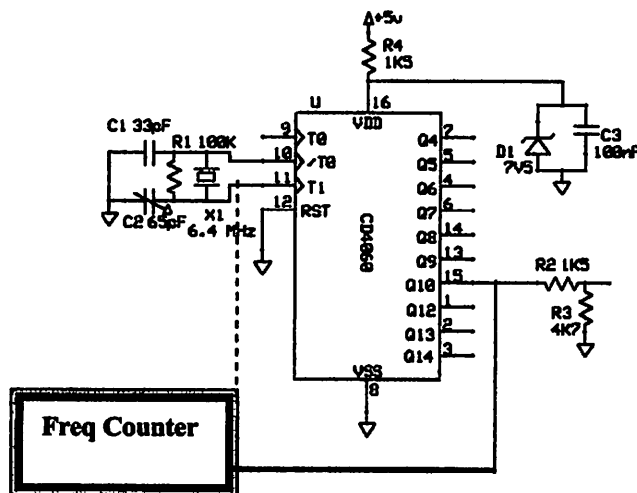
Mengetahui besar frekuensi dari oscilator lokal yang yang dijadikan frekuensi referensi.

4.5.2. Peralatan yang digunakan

1. Frequency Counter GW model GFC-8131
2. Rangkaian Oscilator Lokal
3. Power Supply
4. Kabel

4.5.3. Prosedur Pengujian

1. Merangkai peralatan yang digunakan seperti Gambar 4-4.



Gambar 4-4. Pengukuran Rangkaian Frekuensi Referensi

2. Mengaktifkan peralatan dan memberikan tegangan ke rangkaian oscilator lokal.
3. Mengukur Frekuensi pada Kristal dan frekuensi output, kemudian mencatat pada tabel 4-4.

4.5.4. Hasil Pengujian

Tabel 4-4. Data Pengukuran Oscilator Lokal

Frekuensi Kristal (MHz)	Frekuensi Referensi (KHz)
6.4	6.250

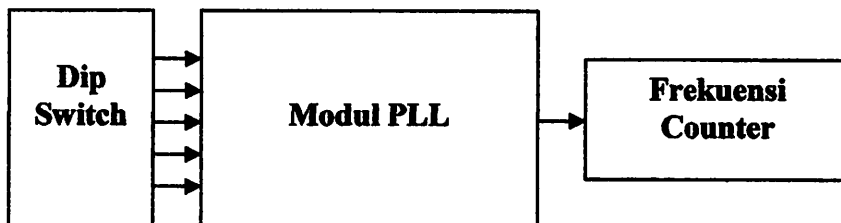
4.6. Pengukuran PLL

4.6.1. Tujuan

Mengetahui data biner terhadap frekuensi output.

4.6.2. Prosedur Pengujian

1. Merangkai peralatan yang digunakan seperti Gambar 4-5.



Gambar 4-5. Pengukuran Rangkaian Frekuensi Referensi

2. Mengaktifkan sistem keseluruhan dan memberikan data pencacahan seperti tabel 4-5.
3. Mengamati Frekuensi output dari sistem dan mencatat pada tabel 4-5.

4.6.3. Hasil Pengujian

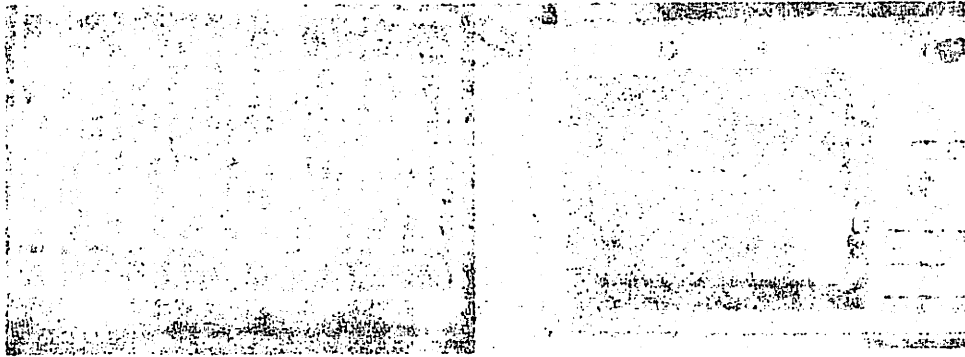
Tabel 4-5. Data Pengujian PLL

Dip Switch												F _{out}
D ₁₁	D ₁₀	D ₉	D ₈	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	(MHz)
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	ON	OFF	ON	87.5
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	ON	OFF	OFF	87.6
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	ON	87.7
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	87.8
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	87.9
ON	ON	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	88
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	ON	88.1
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	ON	OFF	88.2
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	OFF	ON	88.3
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	OFF	OFF	88.4
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	ON	ON	88.5
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	ON	OFF	88.6
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	OFF	ON	88.7
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF	88.8
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	ON	ON	88.9
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	ON	OFF	89
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF	ON	89.1
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	89.2
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	ON	ON	89.3
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	ON	OFF	89.4
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	89.5
ON	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	89.6
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	ON	ON	ON	89.7
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	ON	ON	OFF	89.8
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	ON	OFF	ON	89.9
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	ON	OFF	OFF	90
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	OFF	ON	ON	90.1
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	OFF	ON	OFF	90.2
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	OFF	OFF	ON	90.3
ON	ON	OFF	OFF	OFF	ON	ON	ON	ON	OFF	OFF	OFF	90.4
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	ON	ON	ON	90.5
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	ON	ON	OFF	90.6
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	ON	OFF	ON	90.7
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	ON	OFF	OFF	90.8
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	ON	ON	90.9
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	ON	OFF	91
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	ON	91.1
ON	ON	OFF	OFF	OFF	ON	ON	ON	OFF	OFF	OFF	OFF	91.2
ON	ON	OFF	OFF	OFF	ON	ON	OFF	ON	ON	ON	ON	91.3

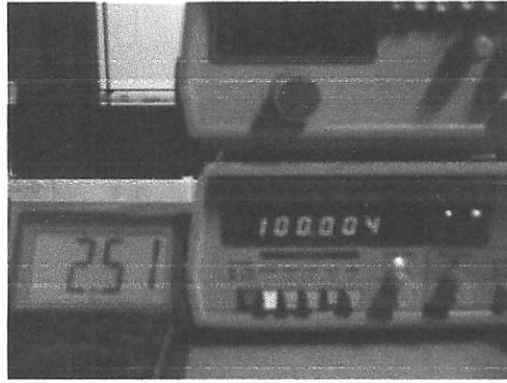
Сөмбөр 4-ө Нийт Бэлтгэсэн Нэг Тэмдэгтэй (а) Зүүнэй туйл (р) Зүүнэй Ойлог

(а)

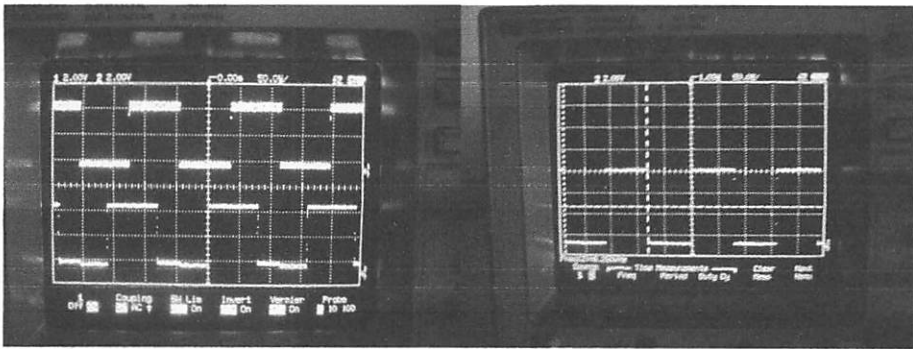
(р)



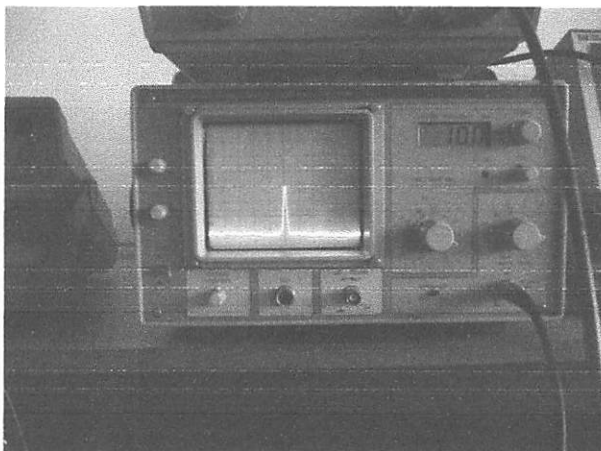
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	100
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОИ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОЕЕ	ОИ	ОЕЕ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОЕЕ	ОИ	ОИ	101 1
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОЕЕ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОИ	101 2
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОИ	ОИ	ОЕЕ	101 4
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	101 3
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	ОЕЕ	101 3
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	ОИ	101 1
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОЕЕ	101
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	ОИ	ОИ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОЕЕ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОИ	101 1
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	ОИ	ОИ	ОЕЕ	101 2
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	101 4
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОИ	101 3
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОИ	ОЕЕ	101 3
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	101 1
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	101
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	101 8
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	ОЕЕ	ОЕЕ	101 2
ОИ	ОЕЕ	ОИ	ОИ	ОИ	ОИ	ОИ	ОЕЕ	ОЕЕ	ОЕЕ	ОЕЕ	ОИ	101 2



Gambar 4-7. Hasil Pengujian VCO



Gambar 4-8. Hasil Pengujian Detektor Fasa



Gambar 4-10. Hasil Pengujian PLL

BAB V

PENUTUP

5.1 Kesimpulan

Berdasarkan hasil pengujian dan analisa alat yang telah dibuat maka dapat disimpulkan :

1. Spesifikasi alat :

- Respon frekuensi audio : 10 Hz – 15 KHz / 6 dB/octave
- Range frekuensi : 87,5 – 108 MHz
- Frekuensi step : 100 KHz /step
- Daya : 0,9 Watt

2. Hasil Pengujian :

- Respon Pre- Emphasis terhadap frekuensi audio 10 Hz – 15 KHz dengan slope pada frekuensi cut- off 6,33 dB/ octave.
- Respon frekuensi terhadap tegangan input dari VCO 0,1 Volt untuk tiap kenaikan frekuensi sebesar 100KHz.
- Tegangan output detector fasa sebesar 0,1 Volt tiap 100KHz step.
- Frekuensi referensi sebesar 6,25 KHz dari kristal 6,4MHz.
- Frekuensi output 87,5 MHz dengan data biner 001101101010, dan frekuensi 108 MHz dengan data biner 010000110111.

3. Kelebihan Alat :

- PLL menggunakan VCO dengan antiphase sehingga dengan komponen aktif frekuensi rendah dapat dihasilkan frekuensi tinggi .

- Sinyal umpan balik yang diambil dari satu sisi oscillator maka tidak diperlukan *Prescaller* yang mahal.
- Terdapat isolasi antara frekuensi output dengan frekuensi umpan balik.
-

5.2 Saran

Dalam pembuatan masih terdapat beberapa kekurangan sehingga untuk mencapai hasil yang lebih baik dan pengembangan lebih lanjut maka dapat diberikan saran – saran sebagai berikut :

1. dalam proses pembuatan PCB dipergunakan double layer untuk menghindari kapasitansi liar.
2. LPF menggunakan jenis aktif filter sehingga range tegangannya lebih lebar dan tidak perlu proses tuning.
3. Dapat dipergunakan metode *Dual Modulus Prescaller* sehingga step frekuensinya sama dengan frekuensi referensi.
4. Perlu ditambahkan Dioda Varactor pada filter output sehingga daya output flat pada semua range frekuensi.

DAFTAR PUSTAKA

1. Hioki, Warren.. "*Telecommunications Third Edition*", Prentice-Hall International,Inc. 1998. Canada.
2. Miller, Garry M, "*Modern Electronic Communication*", Prentice-Hall International,Inc. 1993. New York.
3. ARRL. "*The Radio Amateurs Handbook*", ARRL, 1983, America.
4. ARRL. "*The Radio Amateurs Handbook*", ARRL, 2005, America
5. <http://www.mikroe.com>
6. <http://educyclopedia.be/electronics>

LAMPIRAN



FORMULIR BIMBINGAN SKRIPSI

NAMA : NANANG RONI WIBOWO
 NIM : 02.17.062
 Masa Bimbingan : 09 Januari - 09 Juli 2007
 Judul Skripsi : Perencanaan dan Pembuatan PLL berbasis PIC16F84 dengan penampil LCD dan Aplikasinya sebagai Exciter FM.

No.	Tanggal	Uraian	Paraf Pembimbing
1.	4 12 06.	Konultasi judul skripsi.	
2.	29 07 07.	Konsep tgg PLL Synthesizer menggunakan PIC.	
3.	5 02 07.	Realisasi VCO dgn. parameter 2 yg. diukur sbg. object program.	
4.	21 02 07.	Bab IV, ukur fasa & output VCO yg. dpt. mengunci Freq.	
5.	27 2 07.	Bab IV, ukur perubahan freq. thd. perubahan suhu.	
6.	29 2 07.	Bab V, simpulkan freq. ref. thd. penbagi 2. Mc (PIC)	
7.	5 3 07.	Bab VI, lengkapi perencanaan am filter output VCO	
8.	8 3 07.	Bab II, Cantumkan berbagai jenis VCO utk PLL	
9.	13 3 07.	Bab I, Tinjau lagi batasan masalah & permasalahan.	
10.	14 3 07.	Cap. Skripsi selesai, siap dan ujikan.	

Malang, ...15/3...07.....
 Dosen Pembimbing I

Ir. Sidik Noertjahjono, MT
 NIP. 1028700167



FORMULIR BIMBINGAN SKRIPSI

NAMA : NANANG RONI WIBOWO
NIM : 02.17.062
Masa Bimbingan : 09 Januari – 09 Juli 2007
Judul Skripsi : Perencanaan dan Pembuatan PLL berbasis PIC16F84 dengan penampil LCD dan Aplikasinya sebagai Exciter FM.

No.	Tanggal	Uraian	Paraf Pembimbing
1.		Bab I + Bab II	
2.		Bab III	
3.		Bab IV	
4.		Bab V	
5.		Jenis	
9.			
10.			

Malang,
Dosen Pembimbing II

Ir. F. Yudi Limpraptono, MT
NIP. 1039500274



FORMULIR PERBAIKAN SKRIPSI

Dalam pelaksanaan Ujian Skripsi Jenjang Strata Satu (S-1) Jurusan Teknik Elektro Konsentrasi Teknik Elektronika, maka perlu adanya perbaikan skripsi untuk mahasiswa :

Nama : Nanang Roni Wibowo
NIM : 02.17.062
Jurusan : Teknik Elektro S-1
Konsentrasi : Teknik Elektronika
Masa Bimbingan : 09 Januari 2007 – 09 Juli 2007
Judul Skripsi : Perencanaan dan pembuatan PLL berbasis PIC16F84 dengan penampil LCD dan aplikasinya sebagai exciter FM.

Tanggal	Uraian	Paraf
17 Maret 2007	❖ Lokalisasi masing- masing bagian di skema rangkaian berdasarkan blok diagram	
	❖ Tentukan bagian exciter di blok diagram.	
	❖ Buat kesimpulan dalam format : 1. Spesifikasi alat yang dibuat. 2. Hasil pengujian. 3. Kelebihan alat.	
	❖ Analisa kebutuhan arus terhadap frekuensi dan daya output yang dikeluarkan alat. Tentukan kondisi optimum spesifikasi alat.	

Dosen Penguji

DR. Cahyo Chrysdian, MSc
NIP. 103 0400 412

Mengetahui,

Dosen Pembimbing I

Ir. Sidik Noertjahjono, MT
NIP. 102 8700 167

Dosen Pembimbing II

Ir. F. Yudi Limpraptono, MT
NIP. Y. 103 9500 274



INSTITUT TEKNOLOGI NASIONAL
FAKULTAS TEKNOLOGI INDUSTRI
JURUSAN TEKNIK ELEKTRO

Formulir Perbaiki Ujian Skripsi

Dalam pelaksanaan Ujian Skripsi Janjang Strata 1 Jurusan Teknik Elektro Konsentrasi T. Energi Listrik / T. Elektronika, maka perlu adanya perbaikan skripsi untuk mahasiswa :

NAMA : NANANG RONI WISBOWO
N.I.M : 0217062
Perbaikan meliputi :

1) Idealisasi maning beanya di ~~blok diagram~~ ^{skema}
Rangkaian berdasarkan blok diagram

2) Tentukan bagian excite di blok diagram ~~di~~

3) Buat kerangka di format

1) spec alat yg dirvas

2) flant penyupa

3) kelebihan dan

4) Analisa kelebihan dan
kekurangan frekuensi & daya output
yg di keluarkan dan

Malang, 12/3/2007


Dr. CHORO CRISTIAN, MSc.

Tentukan kondisi optimum spec operasi dan



FORMULIR PERBAIKAN SKRIPSI

Dalam pelaksanaan Ujian Skripsi Jenjang Strata Satu (S-1) Jurusan Teknik Elektro Konsentrasi Teknik Elektronika, maka perlu adanya perbaikan skripsi untuk mahasiswa :

Nama : Nanang Roni Wibowo
NIM : 02.17.062
Jurusan : Teknik Elektro S-1
Konsentrasi : Teknik Elektronika
Masa Bimbingan : 09 Januari 2007 – 09 Juli 2007
Judul Skripsi : Perencanaan dan pembuatan PLL berbasis PIC16F84 dengan penampil LCD dan aplikasinya sebagai exciter FM.

Tanggal	Uraian	Paraf
17 Maret 2007	❖ Sesuaikan alat dengan isi laporan	

Dosen Penguji

I Komang Somawirata, ST, MT
NIP. Y. 103 0100 0361

Mengetahui,

Dosen Pembimbing I

Ir. Sidik Noertjahjono, MT
NIP. 102 8700 167

Dosen Pembimbing II

Ir. F. Yudi Limpraptono, MT
NIP. Y. 103 9500 274



INSTITUT TEKNOLOGI NASIONAL
FAKULTAS TEKNOLOGI INDUSTRI
JURUSAN TEKNIK ELEKTRO

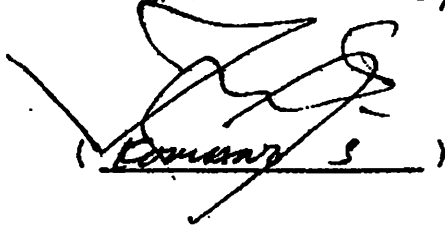
Formulir Perbaikan Ujian Skripsi

Dalam pelaksanaan Ujian Skripsi Janjang Strata 1 Jurusan Teknik Elektro Konsentrasi T. Energi Listrik / T. Elektronika, maka perlu adanya perbaikan skripsi untuk mahasiswa :

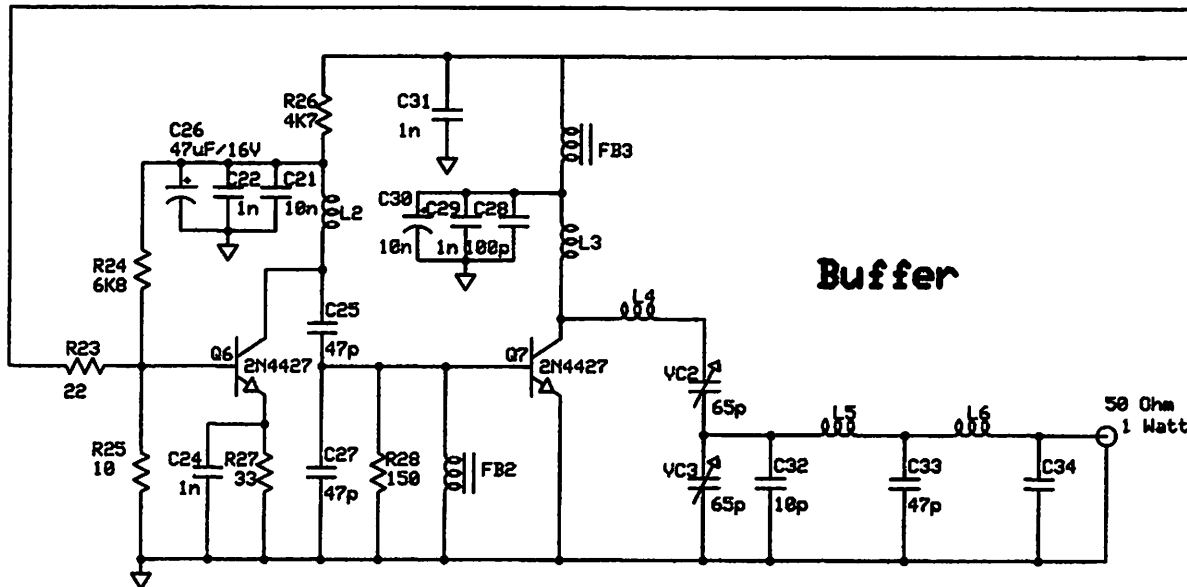
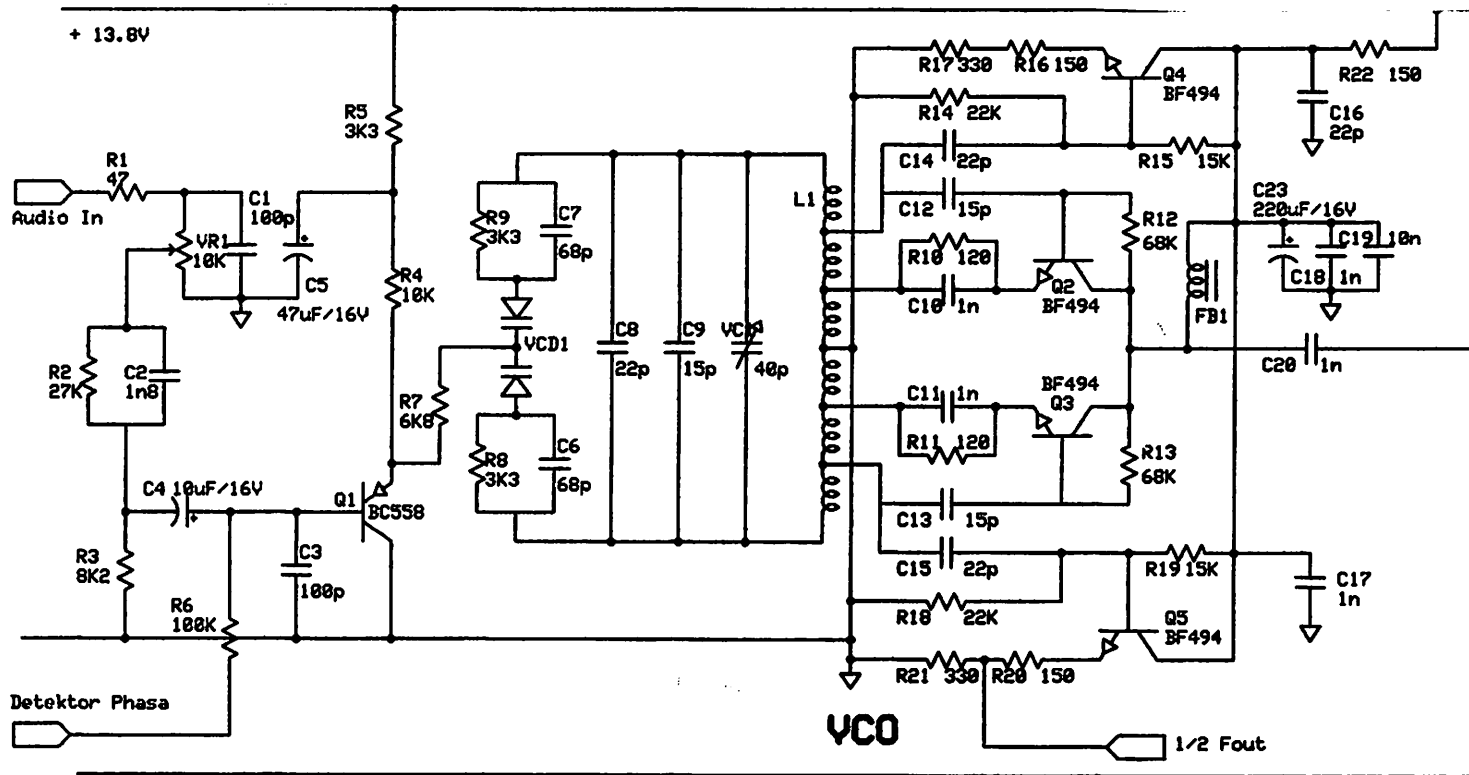
NAMA : NANANG RONI W
NIM : 02.17.062.
Perbaikan meliputi :

Selengkapnya lihat dgn lbr Laporan

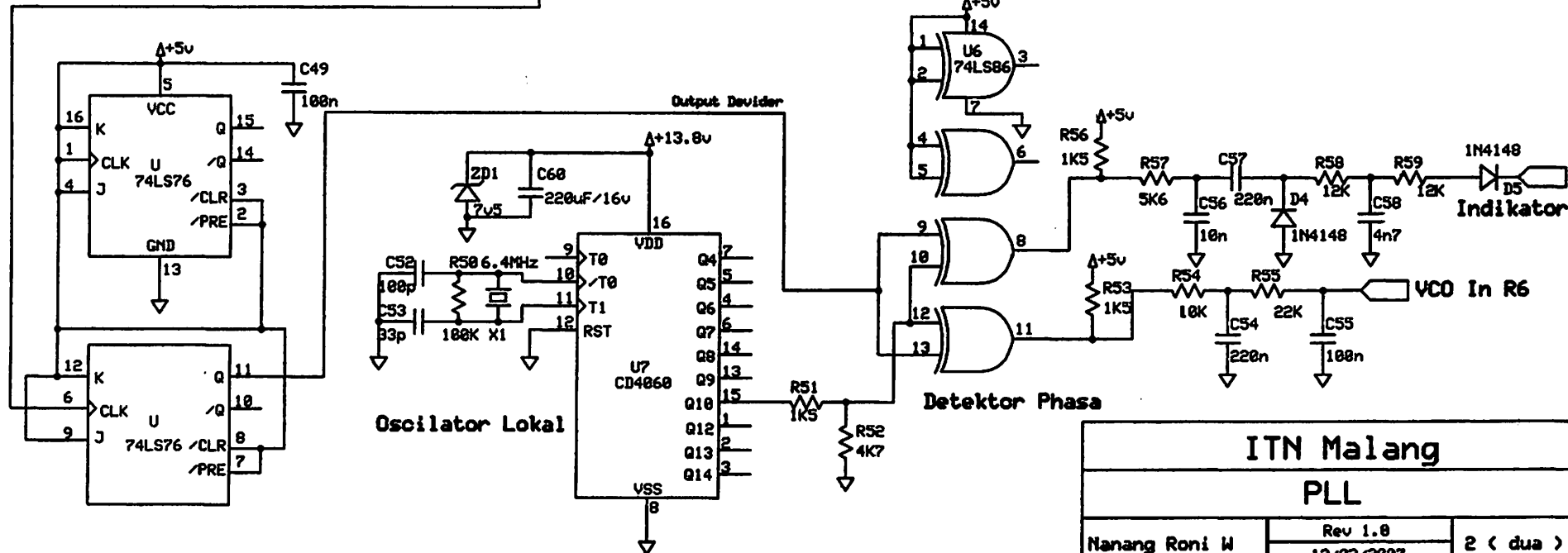
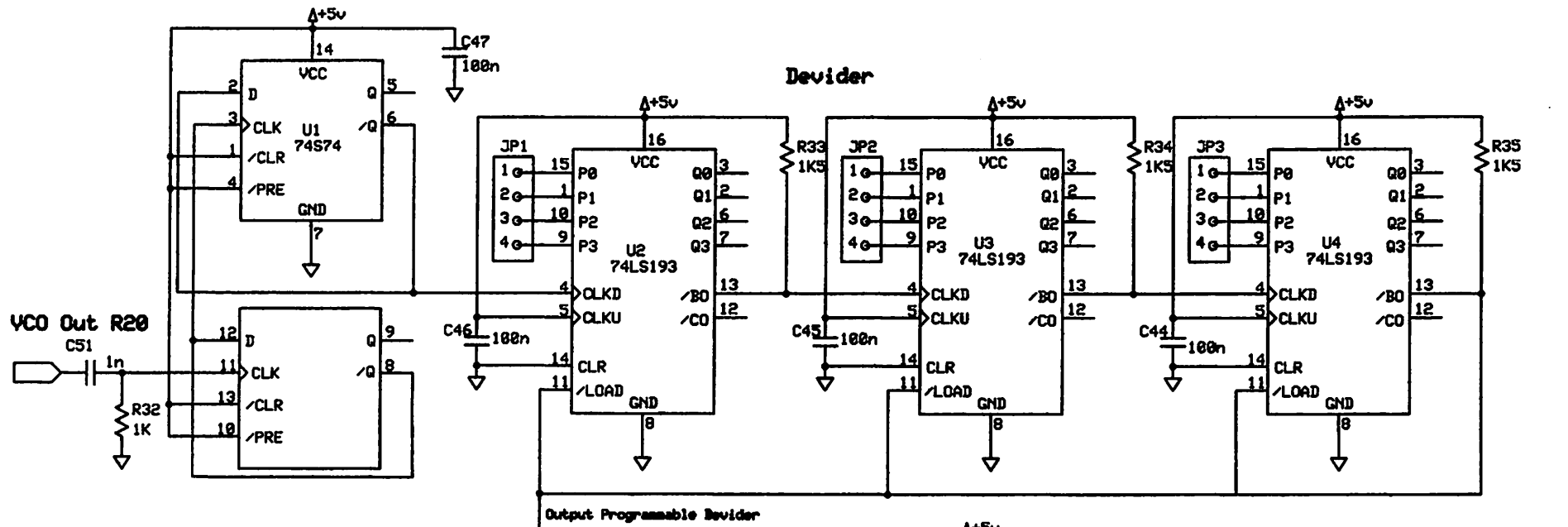
Malang, 17-03-2007


(Edwan S)

+ 13.8V



ITN Malang		
VCO dan Buffer 1 Watt		
Nanang Roni W	Rev 1.0	1 (Satu)
	12/03/2007	



MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209



ON Semiconductor™

<http://onsemi.com>

Silicon Tuning Diodes

6.8–100 pF, 30 Volts
Voltage Variable Capacitance Diodes

These devices are designed in popular plastic packages for the high volume requirements of FM Radio and TV tuning and AFC, general frequency control and tuning applications. They provide solid-state reliability in replacement of mechanical tuning methods. Also available in a Surface Mount Package up to 33 pF.

- High Q
- Controlled and Uniform Tuning Ratio
- Standard Capacitance Tolerance – 10%
- Complete Typical Design Curves

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	Vdc
Forward Current	I_F	200	mAdc
Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/°C
@ $T_A = 25^\circ\text{C}$ Derate above 25°C	MMBV21xx MV21xx LV22xx	280 2.8	
Junction Temperature	T_J	+150	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C

DEVICE MARKING

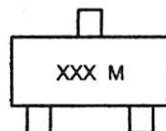
MMBV2101LT1 = M4G	MMBV2108LT1 = 4X	MV2109 = MV2109
MMBV2103LT1 = 4H	MMBV2109LT1 = 4J	LV2205 = LV2205
MMBV2105LT1 = 4U	MV2101 = MV2101	LV2209 = LV2209
MMBV2107LT1 = 4W	MV2105 = MV2105	

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

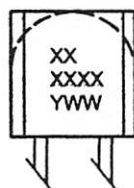
Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ($I_R = 10 \mu\text{Adc}$) MMBV21xx, MV21xx LV22xx	$V_{(BR)R}$	30 25	-	-	Vdc
Reverse Voltage Leakage Current ($V_R = 25 \text{ Vdc}$, $T_A = 25^\circ\text{C}$)	I_R	-	-	0.1	μAdc
Diode Capacitance Temperature Coefficient ($V_R = 4.0 \text{ Vdc}$, $f = 1.0 \text{ MHz}$)	TC_C	-	280	-	ppm/°C



MARKING DIAGRAM



XXX = Device Code*
M = Date Code
* See Table



XX = Device Code Line 1*
XXXX = Device Code Line 2*
M = Date Code
* See Table

Preferred devices are recommended choices for future use and best overall value.

MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209

Device	C_T , Diode Capacitance $V_R = 4.0$ Vdc, $f = 1.0$ MHz pF			Q , Figure of Merit $V_R = 4.0$ Vdc, $f = 50$ MHz	TR, Tuning Ratio C_2/C_{30} $f = 1.0$ MHz		
	Min	Nom	Max	Typ	Min	Typ	Max
MMBV2101LT1/MV2101	6.1	6.8	7.5	450	2.5	2.7	3.2
MMBV2103LT1	9.0	10	11	400	2.5	2.9	3.2
LV2205/MMBV2105LT1/MV2105	13.5	15	16.5	400	2.5	2.9	3.2
MMBV2107LT1	19.8	22	24.2	350	2.5	2.9	3.2
MMBV2108LT1	24.3	27	29.7	300	2.5	3.0	3.2
LV2209/MMBV2109LT1/MV2109	29.7	33	36.3	200	2.5	3.0	3.2

MMBV2101LT1, MMBV2103LT1, MMBV2105LT1, MMBV2107LT1 thru MMBV2109LT1, are also available in bulk. Use the device title and drop the "T1" suffix when ordering any of these devices in bulk.

PARAMETER TEST METHODS

1. C_T , DIODE CAPACITANCE

($C_T = C_C + C_j$). C_T is measured at 1.0 MHz using a capacitance bridge (Boonton Electronics Model 75A or equivalent).

2. TR, TUNING RATIO

TR is the ratio of C_T measured at 2.0 Vdc divided by C_T measured at 30 Vdc.

3. Q, FIGURE OF MERIT

Q is calculated by taking the G and C readings of an admittance bridge at the specified frequency and substituting in the following equations:

$$Q = \frac{2\pi f C}{G}$$

(Boonton Electronics Model 33AS8 or equivalent). Use Lead Length $\approx 1/16"$.

4. TCC , DIODE CAPACITANCE TEMPERATURE COEFFICIENT

TCC is guaranteed by comparing C_T at $V_R = 4.0$ Vdc, $f = 1.0$ MHz, $T_A = -65^\circ\text{C}$ with C_T at $V_R = 4.0$ Vdc, $f = 1.0$ MHz, $T_A = +85^\circ\text{C}$ in the following equation, which defines TCC :

$$TCC = \left| \frac{C_T(+85^\circ\text{C}) - C_T(-65^\circ\text{C})}{85 + 65} \right| \cdot \frac{10^6}{C_T(25^\circ\text{C})}$$

Accuracy limited by measurement of C_T to ± 0.1 pF.

MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209

TYPICAL DEVICE CHARACTERISTICS

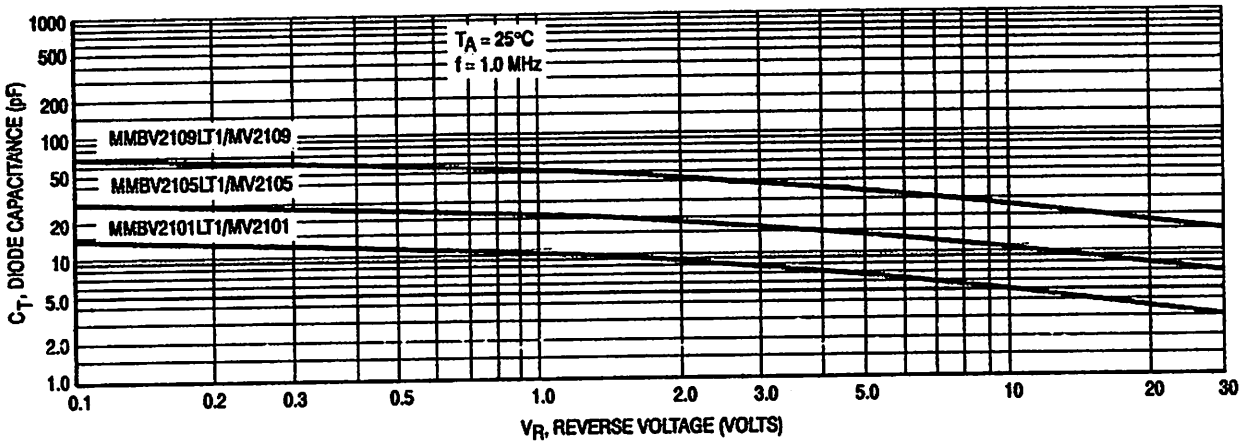


Figure 1. Diode Capacitance versus Reverse Voltage

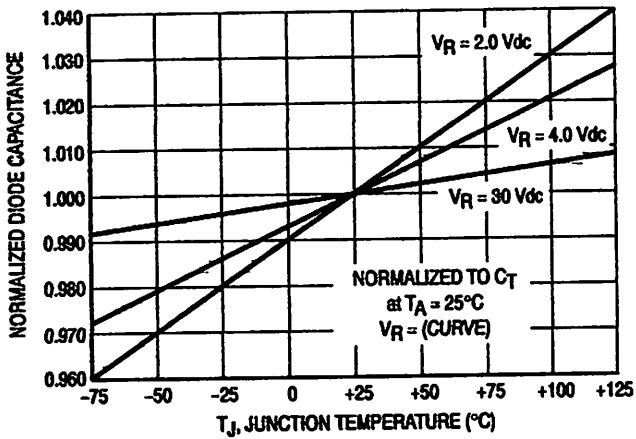


Figure 2. Normalized Diode Capacitance versus Junction Temperature

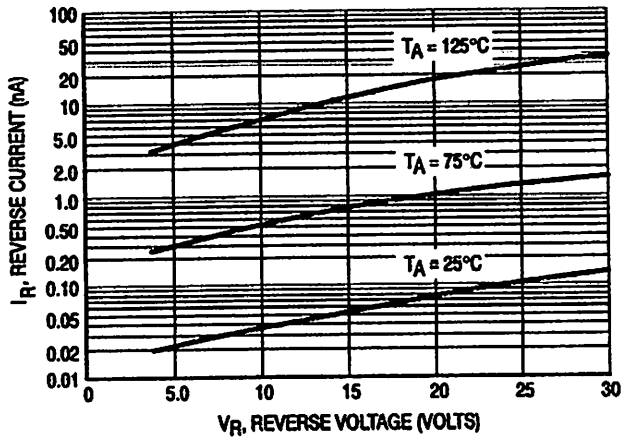


Figure 3. Reverse Current versus Reverse Bias Voltage

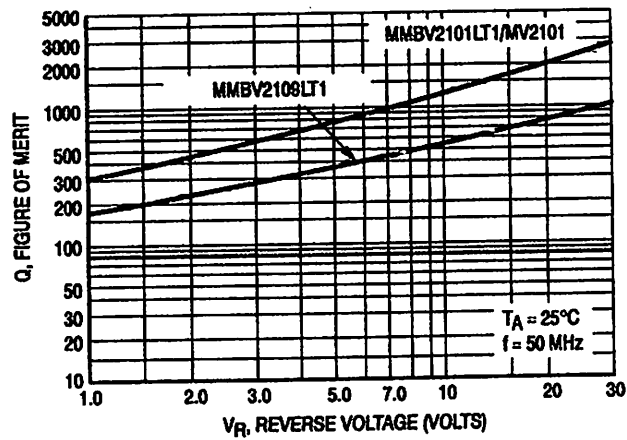


Figure 4. Figure of Merit versus Reverse Voltage

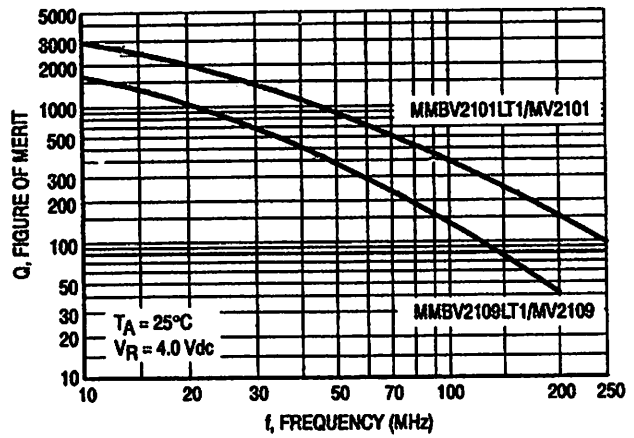
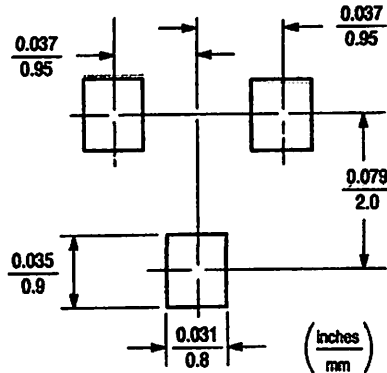


Figure 5. Figure of Merit versus Frequency

INFORMATION FOR USING THE SOT-23 SURFACE MOUNT PACKAGE
MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection

interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SOT-23

SOT-23 POWER DISSIPATION

The power dissipation of the SOT-23 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A . Using the values provided on the data sheet for the SOT-23 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 225 milliwatts.

$$P_D = \frac{150^\circ\text{C} - 25^\circ\text{C}}{556^\circ\text{C/W}} = 225 \text{ milliwatts}$$

The 556°C/W for the SOT-23 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 225 milliwatts. There are other alternatives to achieving higher power dissipation from the SOT-23 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.
- * Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

SOLDER STENCIL GUIDELINES

Prior to placing surface mount components onto a printed circuit board, solder paste must be applied to the pads. A solder stencil is required to screen the optimum amount of solder paste onto the footprint. The stencil is made of brass or stainless steel with a typical thickness of 0.008 inches.

The stencil opening size for the surface mounted package should be the same as the pad size on the printed circuit board, i.e., a 1:1 registration.

TYPICAL SOLDER HEATING PROFILE

For any given circuit board, there will be a group of control settings that will give the desired heat pattern. The operator must set temperatures for several heating zones, and a figure for belt speed. Taken together, these control settings make up a heating "profile" for that particular circuit board. On machines controlled by a computer, the computer remembers these profiles from one operating session to the next. Figure 7 shows a typical heating profile for use when soldering a surface mount device to a printed circuit board. This profile will vary among soldering systems but it is a good starting point. Factors that can affect the profile include the type of soldering system in use, density and types of components on the board, type of solder used, and the type of board or substrate material being used. This profile shows temperature versus time.

The line on the graph shows the actual temperature that might be experienced on the surface of a test board at or near a central solder joint. The two profiles are based on a high density and a low density board. The Vitronics SMD310 convection/infrared reflow soldering system was used to generate this profile. The type of solder used was 62/36/2 Tin Lead Silver with a melting point between 177-189°C. When this type of furnace is used for solder reflow work, the circuit boards and solder joints tend to heat first. The components on the board are then heated by conduction. The circuit board, because it has a large surface area, absorbs the thermal energy more efficiently, then distributes this energy to the components. Because of this effect, the main body of a component may be up to 30 degrees cooler than the adjacent solder joints.

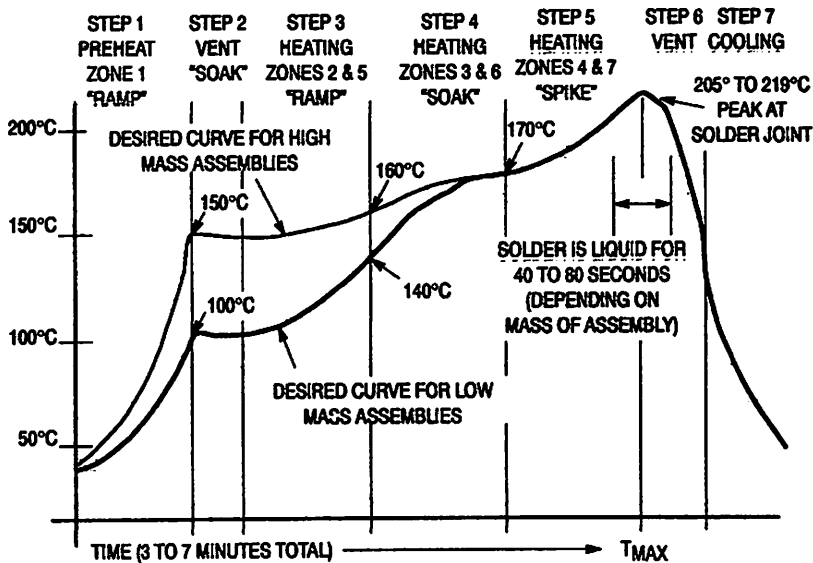
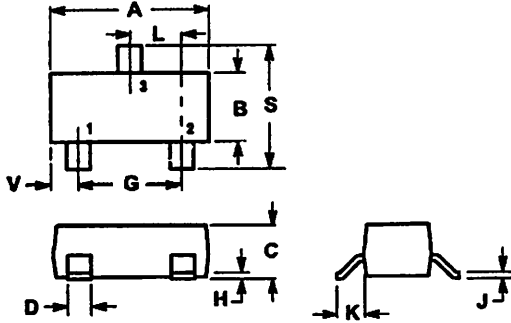


Figure 6. Typical Solder Heating Profile

MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209

PACKAGE DIMENSIONS

SOT-23 (TO-236AB) CASE 318-08 ISSUE AF



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1992.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.086	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0650	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

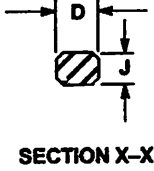
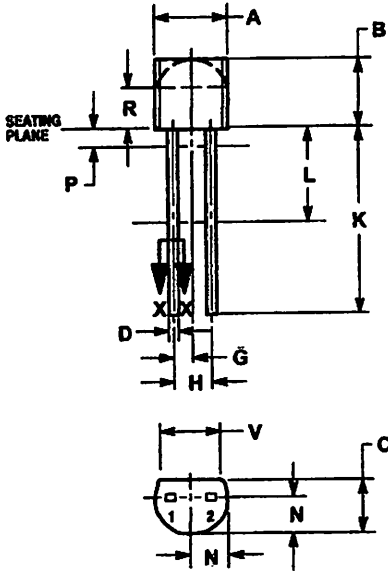
STYLE 8:

1. ANODE
2. NO CONNECTION
3. CATHODE

MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209

PACKAGE DIMENSIONS

TO-92 (TO-226AC) CASE 182-06 ISSUE L




STYLE 1:
PIN 1. ANODE
2. CATHODE

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND ZONE R IS UNCONTROLLED.
 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.21
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.050 BSC		1.27 BSC	
H	0.169 BSC		2.84 BSC	
J	0.014	0.016	0.36	0.41
K	0.500	—	12.70	—
L	0.250	—	6.35	—
N	0.060	0.105	2.93	2.66
P	—	0.050	—	1.27
R	0.115	—	2.93	—
V	0.135	—	3.43	—

MMBV2101LT1 Series, MV2105, MV2101, MV2109, LV2205, LV2209

Thermal Clad is a trademark of the Bergquist Company.

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031
Phone: 81-3-5740-2700
Email: r14525@onsemi.com

ON Semiconductor Website: <http://onsemi.com>

For additional information, please contact your local
Sales Representative.

MMBV2101LT1/D

BC556/557/558/559/560

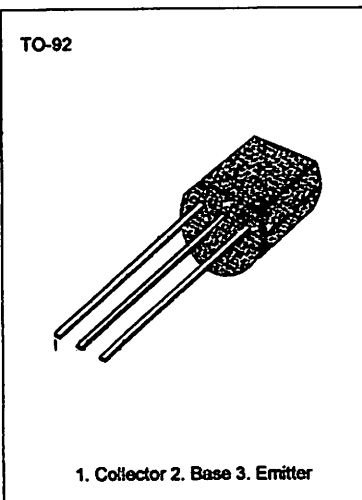
PNP EPITAXIAL SILICON TRANSISTOR

SWITCHING AND AMPLIFIER

- HIGH VOLTAGE: BC558, $V_{CE0} = -65V$
- LOW NOISE: BC559, BC560
- Complement to BC548 ... BC 550

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$)

Characteristic	Symbol	Rating	Unit
Collector-Base Capacitance	V_{CB0}	-80	V
: BC558		-50	V
: BC557/560		-30	V
Collector-Emitter Voltage	V_{CE0}	-65	V
: BC556		-45	V
: BC557/560		-30	V
Emitter-Base Voltage	V_{EB0}	-5	V
Collector Current (DC)	I_C	-100	mA
Collector Dissipation	P_C	500	mW
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature	T_{STG}	-85 ~ 150	$^\circ C$



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$)

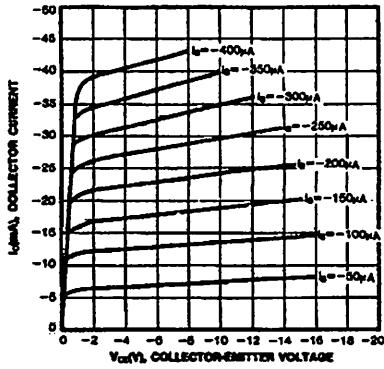
Characteristic	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-off Current	I_{CBO}	$V_{CE} = -30V, I_E = 0$			-15	nA
DC Current Gain	h_{FE}	$V_{CE} = -5V, I_C = 2mA$	110		800	
Collector Emitter Saturation Voltage	$V_{CE}(\text{sat})$	$I_C = -10mA, I_B = -0.5mA$		-90	-300	mV
		$I_C = -100mA, I_B = -5mA$		-250	-650	mV
Collector Base Saturation Voltage	$V_{BE}(\text{on})$	$I_C = -10mA, I_B = -0.5mA$		-700		mV
		$I_C = -100mA, I_B = -5mA$		-900		mV
Base Emitter On Voltage	$V_{BE}(\text{on})$	$V_{CE} = -5V, I_C = -2mA$	-600	-660	-750	mV
		$V_{CE} = -5V, I_C = -10mA$		-800		mV
Current Gain Bandwidth Product	f_T	$V_{CE} = -5V, I_C = -10mA$		150		MHz
Collector Base Capacitance	C_{CB0}	$V_{CB} = -10V, f = 1MHz$			6	pF
Noise Figure	NF	$V_{CE} = -5V, I_C = -200\mu A$		2	10	dB
		$f = 1KHz, R_G = 2K\Omega$		1	4	dB
		$V_{CE} = -5V, I_C = -200\mu A$		1.2	4	dB
		$R_G = 2K\Omega$		1.2	2	dB
		$f = 30 \sim 15000MHz$				

h_{FE} CLASSIFICATION

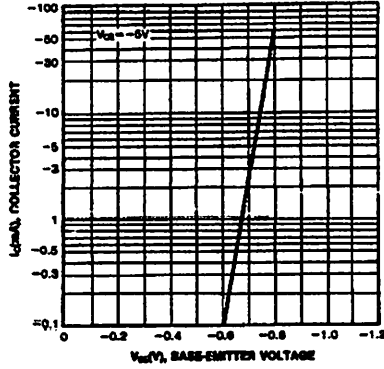
Classification	A	B	C
h_{FE}	110-220	200-450	420-800

Rev. B

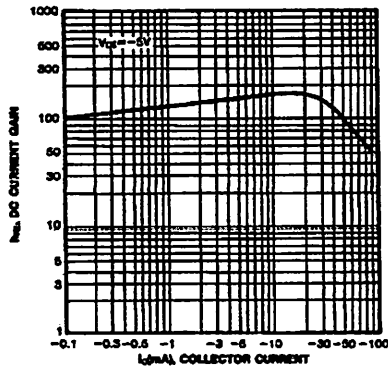
STATIC CHARACTERISTIC



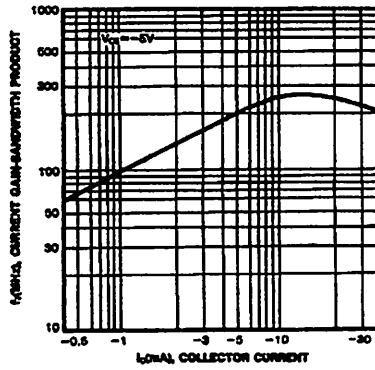
BASE-EMITTER VOLTAGE



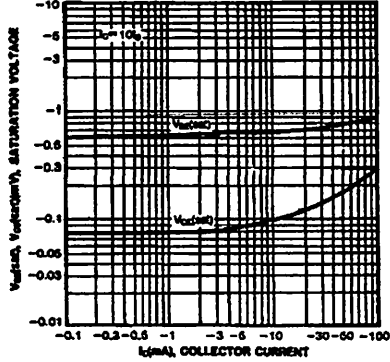
DC CURRENT GAIN



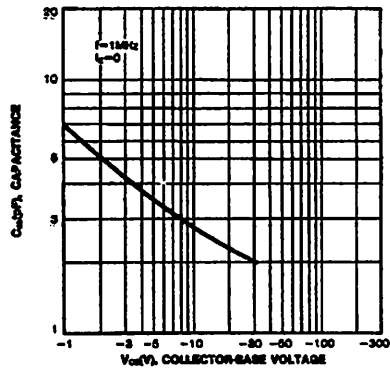
CURRENT GAIN-BANDWIDTH PRODUCT



BASE-EMITTER SATURATION VOLTAGE
COLLECTOR-EMITTER SATURATION VOLTAGE



COLLECTOR OUTPUT CAPACITANCE



TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE_x™
CoolFET™
CROSSVOLT™
E²CMOS™
FACT™
FACT Quiet Series™
FAST[®]
FAST_r™
GTO™
HiSeC™

ISOPLANAR™
MICROWIRE™
POP™
PowerTrench™
QS™
Quiet Series™
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
TinyLogic™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

NPN SILICON RF SMALL SIGNAL TRANSISTORS

MICRO ELECTRONICS

THE BF494, BF495 ARE NPN SILICON PLANAR EPITAXIAL TRANSISTORS FOR RF SMALL SIGNAL APPLICATIONS UP TO 100MHz.

CASE TO-92E



CBE

ABSOLUTE MAXIMUM RATINGS

		BF494	BF495
Collector-Base Voltage	V _{CBO}	30V	30V
Collector-Emitter Voltage	V _{CEO}	20V	20V
Emitter-Base Voltage	V _{EBO}	5V	5V
Collector Current	I _C		30mA
Total Power Dissipation (T _A ≤ 75°C)	P _{tot}		300mW
			derate 4mW/°C above 75°C
Operating Junction & Storage Temperature	T _j , T _{stg}		-55 to 150°C

ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	BF494			BF495			UNIT	TEST CONDITIONS
		MIN	TYP	MAX	MIN	TYP	MAX		
Emitter-Base Breakdown Voltage	BV _{EBO}	5			5			V	I _E =10μA I _C =0
Collector Cutoff Current	I _{CBO}			0.1			0.1	μA	V _{CB} =30V I _E =0
Collector Cutoff Current	I _{CEO}			1			1	μA	V _{CE} =20V I _B =0
Collector-Emitter Saturation Voltage	V _{CE(sat)}	0.1			0.1			V	I _C =10mA I _B =1mA
Base-Emitter Voltage	V _{BE}	.65	.68	.74	.65	.68	.74	V	I _C =1mA V _{CE} =10V
D.C. Current Gain	H _{FE}	67	115	220	36	67	125		I _C =1mA V _{CE} =10V*
Current Gain-Bandwidth Product	f _T		260			200		MHz	I _C =1mA V _{CE} =10V
Feedback Capacitance	C _{re}		.85			.85		pF	I _C =1mA V _{CE} =10V f=450KHz
Noise Figure	N _F		4			4		dB	I _C =1mA V _{CE} =10V R _G =100Ω f=100MHz
Mixing Noise Figure	N _{Fc}		2					dB	I _C =1mA V _{CE} =10V R _G =830Ω f=1MHz
	N _{Fc}					2.5		dB	I _C =1mA V _{CE} =10V R _G =670Ω f=1MHz

* HFE Grouping :

S : 100-220

C : 72-110

D : 36-80

MICRO ELECTRONICS LTD.

L.S.B.P

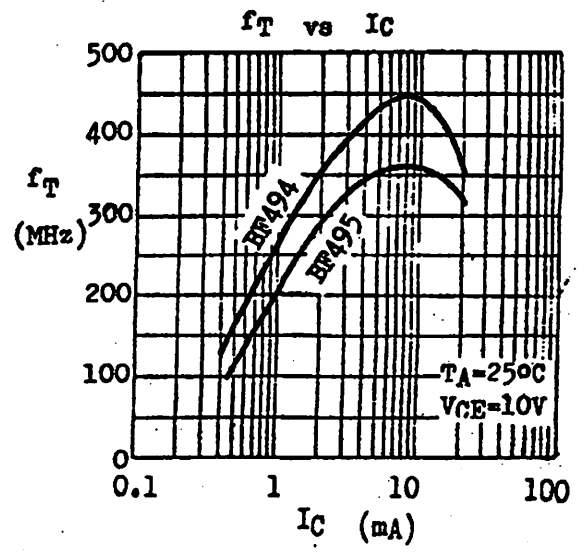
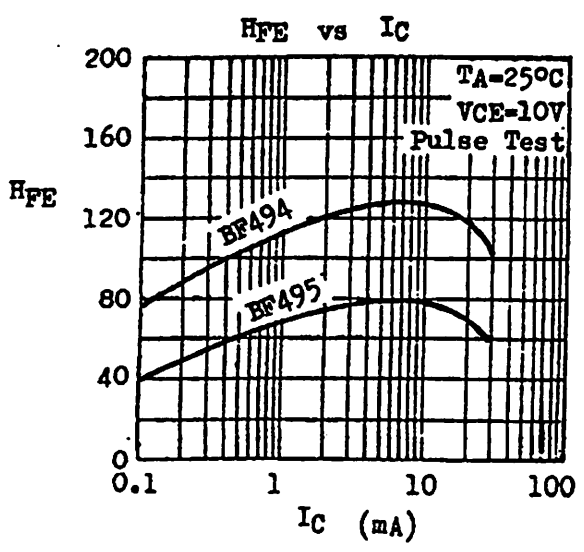
38 HUNG TO ROAD, KWUN TONG, HONG KONG.
KWUN TONG P. O. BOX 69477 CABLE ADDRESS
TELEPHONE:- 3-430181-6 3-888888.

TELEX 43510
"MICROTRON" FAX: 3-4103;
3-882424;

f = 450kHz	$\epsilon_{11} = 0.33mU$	$ y_{12} = 2.8\mu U$	$ y_{21} = 36mU$	$\epsilon_{22} = 6\mu U$
Common Emitter	$b_{11} = 0.065mU$	$-\theta_{12} = 90^\circ$	$-\theta_{21} = 0^\circ$	$b_{22} = 4.5\mu U$
	$C_{11} = 23pF$			$C_{22} = 1.6pF$
f = 10.7MHz	$\epsilon_{11} = 0.45mU$	$ y_{12} = 65\mu U$	$ y_{21} = 36mU$	$\epsilon_{22} = 8.5\mu U$
Common Emitter	$b_{11} = 1.5mU$	$-\theta_{12} = 90^\circ$	$-\theta_{21} = 10^\circ$	$b_{22} = 0.11mU$
	$C_{11} = 22pF$			$C_{22} = 1.6pF$
f = 100MHz	$\epsilon_{11} = 36mU$	$ y_{12} = 420\mu U$	$ y_{21} = 33mU$	$\epsilon_{22} = 22\mu U$
Common Base	$b_{11} = 3mU$	$-\theta_{12} = 88^\circ$	$-\theta_{21} = 146^\circ$	$b_{22} = 1.1mU$
	$C_{11} = 4.8pF$			$C_{22} = 1.75pF$

BF495 TYPICAL y-PARAMETERS AT $T_A = 25^\circ C$ $I_C = 1mA$ $V_{CE} = 10V$

f = 450kHz	$\epsilon_{11} = 0.5mU$	$ y_{12} = 2.6\mu U$	$ y_{21} = 36mU$	$\epsilon_{22} = 2.7\mu U$
Common Emitter	$b_{11} = 0.1mU$	$-\theta_{12} = 90^\circ$	$-\theta_{21} = 0^\circ$	$b_{22} = 4.5\mu U$
	$C_{11} = 32pF$			$C_{22} = 1.6pF$
f = 10.7MHz	$\epsilon_{11} = 0.6mU$	$ y_{12} = 60\mu U$	$ y_{21} = 36mU$	$\epsilon_{22} = 4.5\mu U$
Common Emitter	$b_{11} = 2mU$	$-\theta_{12} = 90^\circ$	$-\theta_{21} = 10^\circ$	$b_{22} = 0.11mU$
	$C_{11} = 30pF$			$C_{22} = 1.6pF$
f = 100MHz	$\epsilon_{11} = 38mU$	$ y_{12} = 410\mu U$	$ y_{21} = 34mU$	$\epsilon_{22} = 12\mu U$
Common Base	$b_{11} = 1mU$	$-\theta_{12} = 85^\circ$	$-\theta_{21} = 140^\circ$	$b_{22} = 1.1mU$
	$C_{11} = 1.6pF$			$C_{22} = 1.75pF$



$\alpha - 2 - \beta = ?$

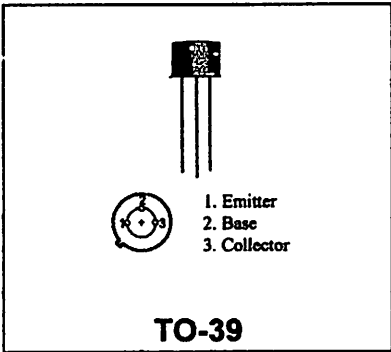
2.78.3300A

2N4427

**& MICROWAVE DISCRETE
W POWER TRANSISTORS**

Features

Silicon NPN, To-39 packaged VHF/UHF Transistor
1 Watt Minimum Power Output @ 175 MHz
500 MHz Current-Gain Bandwidth Product @ 50mA
Power Gain, $G_{PE} = 10\text{dB (Min)}$ @ 175 MHz



DESCRIPTION:

Common emitter NPN transistor, designed for VHF and UHF equipment. Applications include amplifier, pre-driver, driver, and output stages. Also suitable for oscillator and frequency-multiplier functions.

ABSOLUTE MAXIMUM RATINGS (T_{case} = 25°C)

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	20	Vdc
V _{CBO}	Collector-Base Voltage	40	Vdc
V _{EBO}	Emitter-Base Voltage	2.0	Vdc
I _c	Collector Current	400	mA

Thermal Data

P _D	Total Device Dissipation @ T _A = 25°C Derate above 25°C	1.0 5.71	Watts mW/°C
----------------	---	-------------	----------------

ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

DC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
V _{CER}	Collector-Emitter Sustaining Voltage (I _C = 5.0 mA _{dc} , R _{BE} = 10 ohms)	40	-	-	V _{dc}
V _{CEO}	Collector-Emitter Sustaining Voltage (I _C =5.0 mA _{dc} , I _B =0)	20	-	-	V _{dc}
I _{CEO}	Collector Cutoff Current (V _{CE} = 12 V _{dc} , I _B = 0)	-	-	20	μA
I _{CEX}	Collector Cutoff Current (V _{CE} = 40 V _{dc} , V _{BE} = -1.5 V _{dc})	-	-	100	μA
I _{EBO}	Emitter Cutoff Current (V _{EB} = 2.0 V _{dc} , I _C = 0)	-	-	100	μA
h _{FE}	DC Current Gain (I _C = 100 mA _{dc} , V _{CE} = 5.0 V _{dc}) (I _C = 360 mA _{dc} , V _{CE} = 5.0 V _{dc})	10 5	- -	200 -	- -
V _{CE(sat)}	Collector-Emitter Saturation Voltage (I _C = 100 mA _{dc} , I _B = 20 mA _{dc})	-	-	0.5	V _{dc}

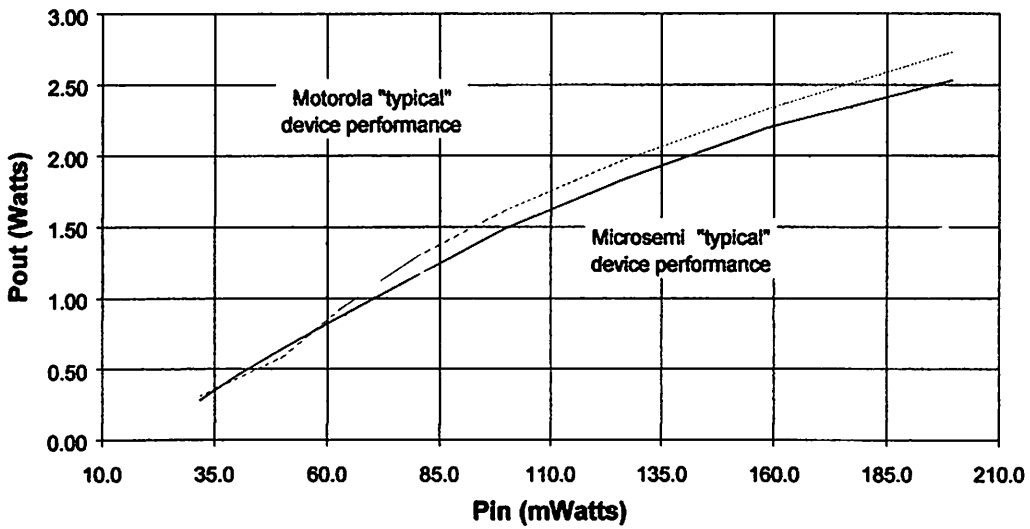
AC

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
f _T	Current-Gain - Bandwidth Product (I _C = 50 mA _{dc} , V _{CE} = 15 V _{dc} , f = 200 MHz)	500	-	-	MHz
C _{OB}	Output Capacitance (V _{CB} = 12 V _{dc} , I _E = 0, f = 1.0 MHz)	-	4.0	-	pF

2N4427

ADDITIONAL

Symbol	Test Conditions		Value			Unit
			Min.	Typ.	Max.	
G_{PE}	Power Gain	Test Circuit-Figure 1 Pin = 0.1 W, VCE = 12Vdc f = 175 MHz	10	-	-	dB
P_{out}	Output Power	Test Circuit-Figure 1 Pin = 0.1 W, VCE = 12Vdc f = 175 MHz	1.0	-	-	Watts
η_C	Collector Efficiency	Test Circuit-Figure 1 Pin = 0.1 W, VCE = 12Vdc f = 175 MHz	45	-	-	%



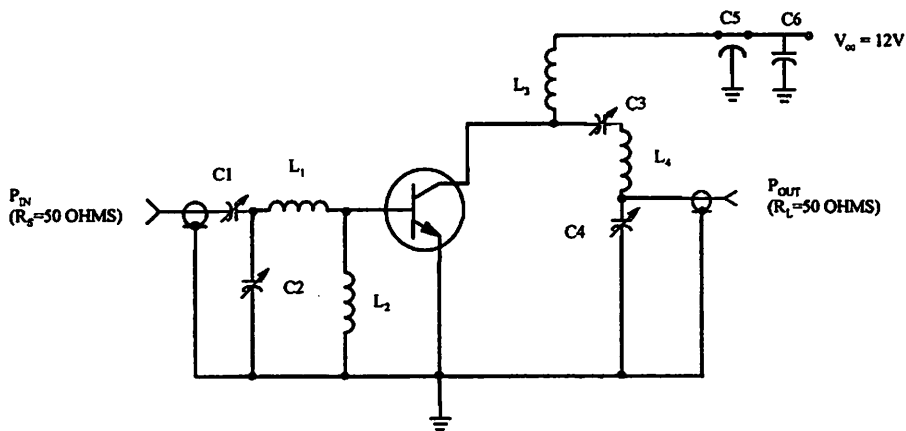


Figure 1 - 175 MHz RF AMPLIFIER CIRCUIT FOR G_{PE} , P_{OUT} , AND EFFICIENCY SPECIFICATIONS.

L_1 : 2 TURNS No. 16 wire, 3/16" ID, 1/4" long

L_2 : Ferrite choke, $Z=450$ ohms

L_3 : 2 TURNS No. 16 wire, 1/4" ID, 1/4" long

L_4 : 4 TURNS No. 16 wire, 3/8" ID, 3/8" long

Capacitor values in pF unless

Tuning capacitors are air variable otherwise indicated.

2N4427

Low Power PA, LNA, and General Purpose Discrete Selector Guide

Package	Device	Type	GPE Freq (MHz)	Pout (watts)	GPE (dB)	Efficiency (%)	GPE VCC	BVCEO	IC max (mA)
SO-8	MRF4427, R2	NPN	175	0.15	18	60	12	20	400
TO-39	2N4427	NPN	175	1	10	50	12	20	400
POWER MACRO	MRF553	NPN	175	1.5	11.5	60	12.5	16	500
POWER MACRO	MRF553T	NPN	175	1.5	11.5	50	12.5	16	500
TO-39	MRF607	NPN	175	1.75	11.5	50	12.5	16	330
TO-39	2N6255	NPN	175	3	7.8	50	12.5	18	1000
TO-72	2N5179	NPN	200		20		6	12	50
MACRO X	MRF559	NPN	512	0.5	10	65	7.5	16	150
MACRO X	MRF559	NPN	512	0.5	13	60	12.5	16	150
TO-39	2N3866A	NPN	400	1	10	45	28	30	400
SO-8	MRF3866, R1, R2	NPN	400	1	10	45	28	30	400
POWER MACRO	MRF555	NPN	470	1.5	11	50	12.5	16	400
POWER MACRO	MRF555T	NPN	470	1.5	11	50	12.5	16	400
MACRO X	MRF559	NPN	870	0.5	6.5	70	7.5	16	150
MACRO X	MRF559	NPN	870	0.5	9.5	65	12.5	16	150
SO-8	MRF8372, R1, R2	NPN	870	0.75	8	55	12.5	16	200
POWER MACRO	MRF557	NPN	870	1.5	8	55	12.5	16	400
POWER MACRO	MRF557T	NPN	870	1.5	8	55	12.5	16	400

Package	Device	Type	Freq (MHz)	NF	NF @ 1dB (mA)	NF VCE	GN (dB)	Gu Max (dB)	F1au (MHz)	Ccb(pF)	BVCEO	IC max (mA)
TO-39	2N5109	NPN	200	3	10	15		12	1200	3.5	20	400
TO-39	MRF5943C	NPN	200	3.4	30	15		11.4	1000		30	400
SO-8	MRF5943, R1, R2	NPN	200	3.4	30	15		15	1300		30	400
TO-72	2N5179	NPN	200	4.5	1.5	8		17	900	1	12	50
TO-72	2N2857	NPN	300	5.5	50	8		13	1600	1	15	40
TO-39	MRF517	NPN	300	7.5	50	15		5.6	4600	3	25	150
TO-72	MRF904	NPN	450	1.5	5	6		11	4000	1	16	30
TO-72	2N6304	NPN	450	5	2	5		14	1400	1	16	50
MACRO T	BF9D1	NPN	500	1.9	2	5	11	16.5	5000	1	12	35
MACRO T	BF996	NPN	500	2	10	10		14.5	500	2.6	16	100
SO-8	MRF5832, R1, R2	NPN	500	2	50	10	15.9	17.8	5000		16	200
MACRO X	MRF581A	NPN	500	2	10	10	14	15	5000	1	16	200
MACRO	BF990	NPN	500	2.4	2	10	15	18	5000	1	16	30
TO-72	BF990	NPN	500	2.5	2	5		20	1300		15	50
TO-72	MRF914	NPN	500	2.5	5	10		16	4500		12	40
MACRO X	MRF581	NPN	500	2.5	10	10	11	17.8	5000		16	200
TO-39	MRF586	NPN	500	3	90	15	11	14.5	4500	2.2	17	200
MACRO X	MRF951	NPN	1000	1.3	5	6	14	17	8000	0.45	10	100
MACRO X	MRF571	NPN	1000	1.5	10	8	10		8000	1	10	70
MACRO T	BF9D1	NPN	1000	2.5	2	5	8	11	5000	1	12	35
MACRO T	BF990	NPN	1000	3	2	10	10	12.5	5000	1	15	30
TO-39	MRF545	PNP						14	1400	2	70	400
TO-39	MRF544	NPN						13.5	1500		70	400

RF (Low Power PA / General Purpose) Selection Guide

RF (LNA / General Purpose) Selection Guide

Low Cost RF Plastic Package Options

PACKAGE STYLE M236

MACRO-T

ORDER CODE	ORDER CODE	ORDER CODE	ORDER CODE
A	B	C	D
175/4,43	200/5,71		
275/4,43	200/5,71		
311/6,64	239/7,68		
359/6,64	239/7,68		
437/6,64	242/7,68		
508/7,34	230/6,13		
615/8,24	245/7,68		
685/7,68			

PACKAGE STYLE M238

MACRO-X

ORDER CODE	ORDER CODE	ORDER CODE	ORDER CODE
A	B	C	D
175/4,43	200/5,71		
275/4,43	200/5,71		
311/6,64	239/7,68		
359/6,64	239/7,68		
437/6,64	242/7,68		
508/7,34	230/6,13		
615/8,24	245/7,68		
685/7,68			

PACKAGE STYLE M234

POWER MACRO

ORDER CODE	ORDER CODE	ORDER CODE	ORDER CODE
A	B	C	D
175/4,43	200/5,71		
275/4,43	200/5,71		
311/6,64	239/7,68		
359/6,64	239/7,68		
437/6,64	242/7,68		
508/7,34	230/6,13		
615/8,24	245/7,68		
685/7,68			

PACKAGE STYLE M240

SO-8

ORDER CODE	ORDER CODE	ORDER CODE	ORDER CODE
A	B	C	D
175/4,43	200/5,71		
275/4,43	200/5,71		
311/6,64	239/7,68		
359/6,64	239/7,68		
437/6,64	242/7,68		
508/7,34	230/6,13		
615/8,24	245/7,68		
685/7,68			

Macro T

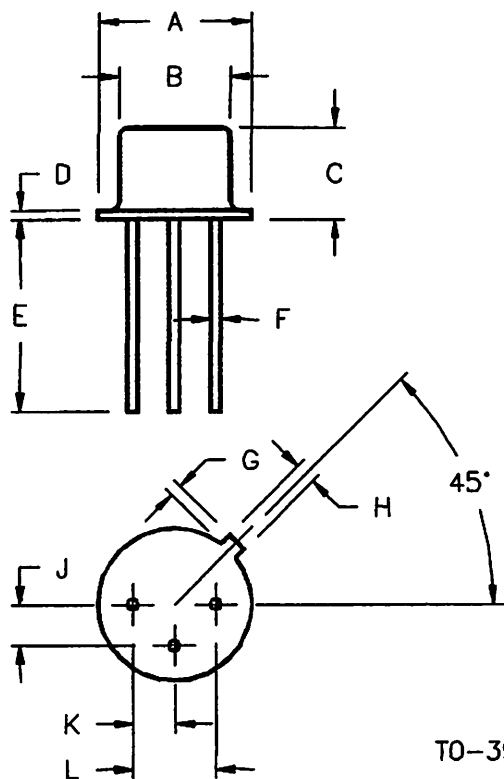
Macro X

Power

SO-8

2N4427

PACKAGE STYLE M246



TO-39

	MINIMUM INCHES/MM	MAXIMUM INCHES/MM		MINIMUM INCHES/MM	MAXIMUM INCHES/MM
A	.350/8,89	.370/9,40	J	.095/2,41	.105/2,67
B	.315/8,00	.335/8,51	K	.095/2,41	.105/2,67
C	.240/6,10	.260/6,60	L	.190/4,83	.210/5,33
D	.015/0,38	.045/1,14			
E	.500/12,70				
F	.016/0,41	.019/0,48			
G	.029/0,74	.040/1,02			
H	.028/0,71	.034/0,86			



BC546/547/548/549/550

Switching and Amplifier

- High Voltage: BC546, $V_{CE0}=65V$
- Low Noise: BC549, BC550
- Complement to BC556 ... BC560



1 TO-92
1. Collector 2. Base 3. Emitter

NPN Epitaxial Silicon Transistor

Absolute Maximum Ratings $T_a=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage : BC546	80	V
	: BC547/550	50	V
	: BC548/549	30	V
V_{CEO}	Collector-Emitter Voltage : BC548	65	V
	: BC547/550	45	V
	: BC548/549	30	V
V_{EBO}	Emitter-Base Voltage : BC546/547	6	V
	: BC548/549/550	5	V
I_C	Collector Current (DC)	100	mA
P_C	Collector Dissipation	500	mW
T_J	Junction Temperature	150	$^{\circ}C$
T_{STG}	Storage Temperature	-65 ~ 150	$^{\circ}C$

Electrical Characteristics $T_a=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
I_{CBO}	Collector Cut-off Current	$V_{CB}=30V, I_E=0$			15	nA
h_{FE}	DC Current Gain	$V_{CE}=5V, I_C=2mA$	110		800	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=10mA, I_B=0.5mA$		90	250	mV
		$I_C=100mA, I_B=5mA$		200	600	mV
$V_{BE(sat)}$	Base-Emitter Saturation Voltage	$I_C=10mA, I_B=0.5mA$		700		mV
		$I_C=100mA, I_B=5mA$		900		mV
$V_{BE(on)}$	Base-Emitter On Voltage	$V_{CE}=5V, I_C=2mA$	580	680	700	mV
		$V_{CE}=5V, I_C=10mA$			720	mV
f_T	Current Gain Bandwidth Product	$V_{CE}=5V, I_C=10mA, f=100MHz$		300		MHz
C_{ob}	Output Capacitance	$V_{CB}=10V, I_E=0, f=1MHz$		3.5	6	pF
C_{ib}	Input Capacitance	$V_{EB}=0.5V, I_C=0, f=1MHz$		9		pF
NF	Noise Figure : BC546/547/548 : BC549/550 : BC549 : BC550	$V_{CE}=5V, I_C=200\mu A$		2	10	dB
		$f=1KHz, R_G=2K\Omega$		1.2	4	dB
		$V_{CE}=5V, I_C=200\mu A$		1.4	4	dB
		$R_G=2K\Omega, f=30\sim 15000MHz$		1.4	3	dB

h_{FE} Classification

Classification	A	B	C
h_{FE}	110 ~ 220	200 ~ 450	420 ~ 800

BC546/547/548/549/550

Typical Characteristics

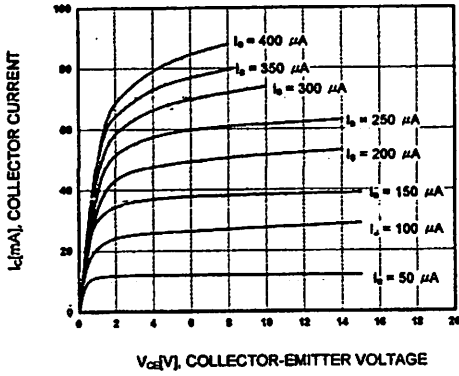


Figure 1. Static Characteristic

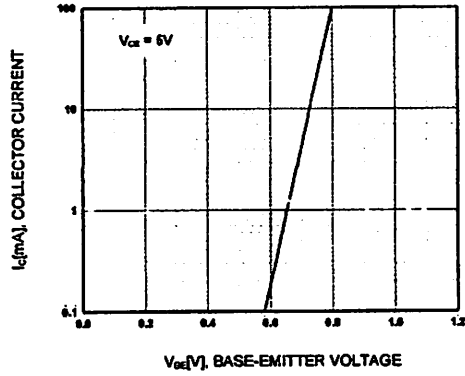


Figure 2. Transfer Characteristic

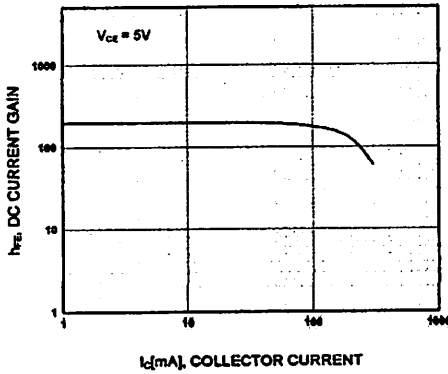


Figure 3. DC current Gain

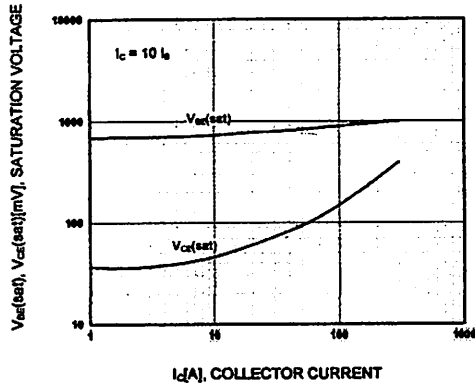


Figure 4. Base-Emitter Saturation Voltage
Collector-Emitter Saturation Voltage

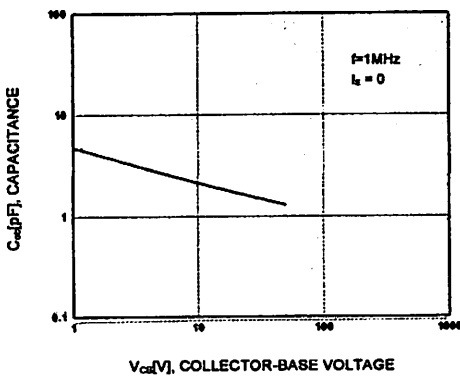


Figure 5. Output Capacitance

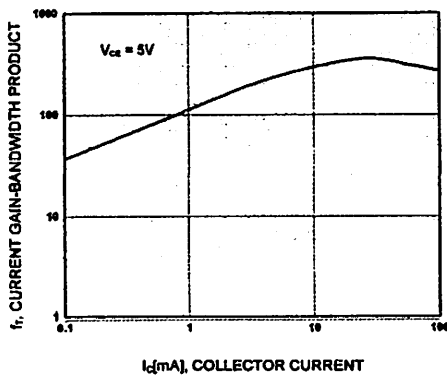
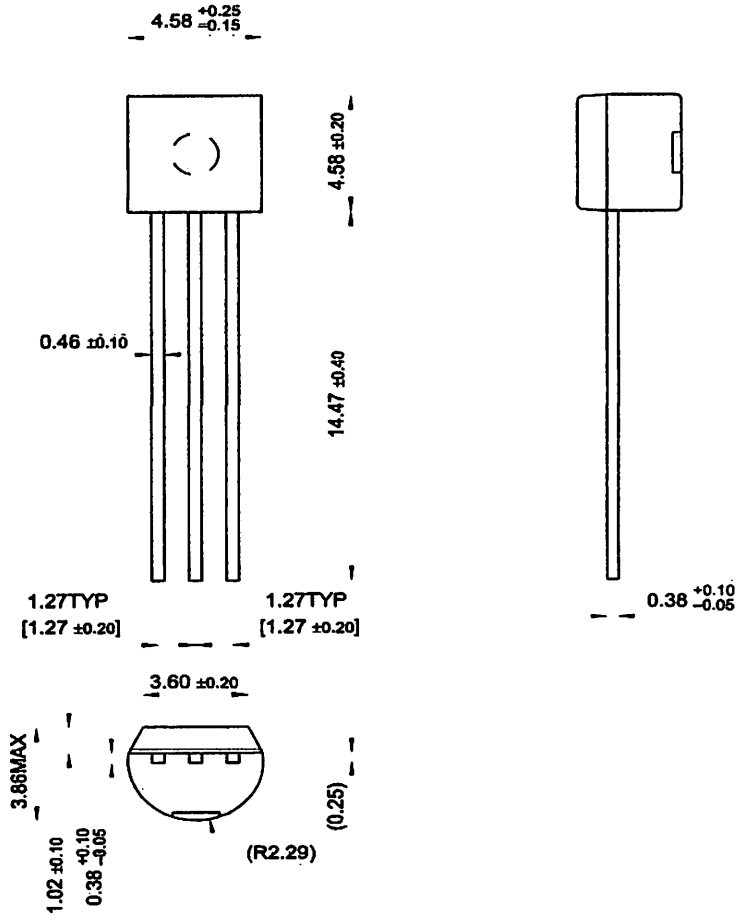


Figure 6. Current Gain Bandwidth Product

Package Dimensions

TO-92



Dimensions in Millimeters

BC546/547/548/549/550

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE_x™
 Bottomless™
 CoolFET™
 CROSSVOLT™
 E²C_{MOS}™
 FACT™
 FACT Quiet Series™
 FAST®
 FAST_r™
 GTO™

HiSeC™
 ISOPLANAR™
 MICROWIRE™
 POP™
 PowerTrench®
 QFET™
 QS™
 Quiet Series™
 SuperSOT™-3
 SuperSOT™-6

SuperSOT™-8
 SyncFET™
 TinyLogic™
 UHC™
 VCX™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR INTERNATIONAL.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

SN74LS76A

Dual JK Flip-Flop with Set and Clear

The SN74LS76A offers individual J, K, Clock Pulse, Direct Set and Direct Clear inputs. These dual flip-flops are designed so that when the clock goes HIGH, the inputs are enabled and data will be accepted. The Logic Level of the J and K inputs will perform according to the Truth Table as long as minimum set-up times are observed. Input data is transferred to the outputs on the HIGH-to-LOW clock transitions.

MODE SELECT - TRUTH TABLE

OPERATING MODE	INPUTS				OUTPUTS	
	\bar{S}_D	\bar{C}_D	J	K	Q	\bar{Q}
Set	L	H	X	X	H	L
Reset (Clear)	H	L	X	X	L	H
*Undetermined	L	L	X	X	H	H
Toggle	H	H	h	h	\bar{q}	q
Load "0" (Reset)	H	H	l	h	L	H
Load "1" (Set)	H	H	h	l	H	L
Hold	H	H	l	l	q	\bar{q}

* Both outputs will be HIGH while both \bar{S}_D and \bar{C}_D are LOW, but the output states are unpredictable if \bar{S}_D and \bar{C}_D go HIGH simultaneously.

H, h = HIGH Voltage Level

L, l = LOW Voltage Level

X = Immaterial

l, h (q) = Lower case letters indicate the state of the referenced input

(or output) one setup time prior to the HIGH-to-LOW clock transition



ON Semiconductor

Formerly a Division of Motorola

<http://onsemi.com>

**LOW
POWER
SCHOTTKY**



**PLASTIC
N SUFFIX
CASE 648**



**SOIC
D SUFFIX
CASE 751B**

GUARANTEED OPERATING RANGES

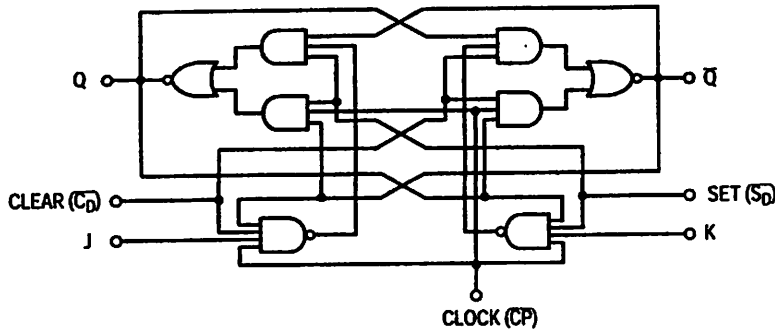
Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current - High			-0.4	mA
I_{OL}	Output Current - Low			8.0	mA

ORDERING INFORMATION

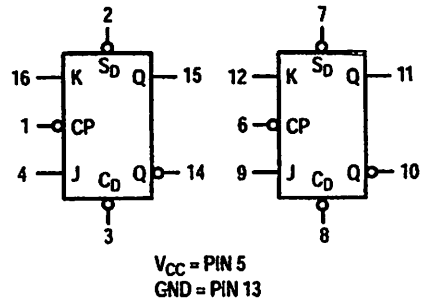
Device	Package	Shipping
SN74LS76AN	16 Pin DIP	2000 Units/Box
SN74LS76AD	16 Pin	2500/Tape & Reel

SN74LS76A

LOGIC DIAGRAM



LOGIC SYMBOL



DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter		Limits			Unit	Test Conditions
			Min	Typ	Max		
V _{IH}	Input HIGH Voltage		2.0			V	Guaranteed Input HIGH Voltage for All Inputs
V _{IL}	Input LOW Voltage				0.8	V	Guaranteed Input LOW Voltage for All Inputs
V _{IK}	Input Clamp Diode Voltage			-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage		2.7	3.5		V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table
V _{OL}	Output LOW Voltage			0.25	0.4	V	V _{CC} = V _{CC} MIN, V _{IN} = V _{IL} or V _{IH} per Truth Table
				0.35	0.5	V	
I _{IH}	Input HIGH Current	J, K Clear Clock			20 60 80	μA	V _{CC} = MAX, V _{IN} = 2.7 V
		J, K Clear Clock			0.1 0.3 0.4	mA	V _{CC} = MAX, V _{IN} = 7.0 V
I _{IL}	Input LOW Current	J, K Clear, Clock			-0.4 -0.8	mA	V _{CC} = MAX, V _{IN} = 0.4 V
I _{OS}	Short Circuit Current (Note 1)		-20		-100	mA	V _{CC} = MAX
I _{CC}	Power Supply Current				6.0	mA	V _{CC} = MAX

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter		Limits			Unit	Test Conditions
			Min	Typ	Max		
f _{MAX}	Maximum Clock Frequency		30	45		MHz	V _{CC} = 5.0 V C _L = 15 pF
t _{PLH} t _{PHL}	Clock, Clear, Set to Output			15	20	ns	
				15	20	ns	

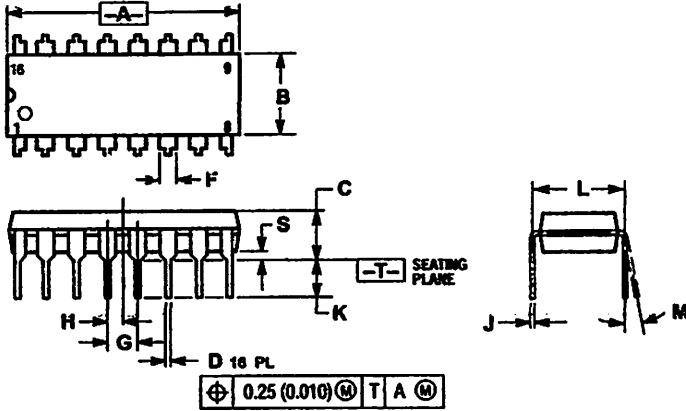
AC SETUP REQUIREMENTS (T_A = 25°C)

Symbol	Parameter		Limits			Unit	Test Conditions
			Min	Typ	Max		
t _w	Clock Pulse Width High		20			ns	V _{CC} = 5.0 V
t _w	Clear Set Pulse Width		25			ns	
t _s	Setup Time		20			ns	
t _h	Hold Time		0			ns	

SN74LS76A

PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 648-08 ISSUE R

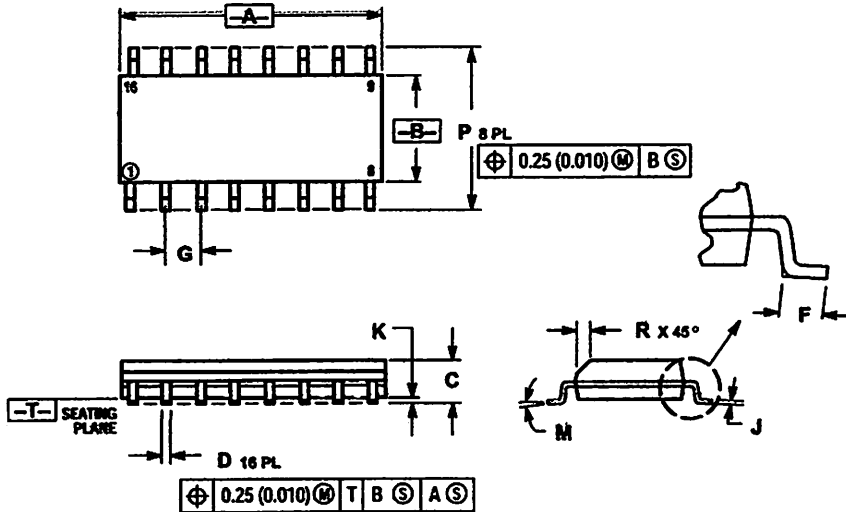


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J




NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.90	10.00	0.394	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.069
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SN74LS76A

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

North America Literature Fulfillment:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor – European Support

German Phone: (+1) 303-308-7140 (M-F 2:30pm to 5:00pm Munich Time)
Email: ONlit-german@hibbertco.com
French Phone: (+1) 303-308-7141 (M-F 2:30pm to 5:00pm Toulouse Time)
Email: ONlit-french@hibbertco.com
English Phone: (+1) 303-308-7142 (M-F 1:30pm to 5:00pm UK Time)
Email: ONlit@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time)
Toll Free from Hong Kong 800-4422-3781
Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center

4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-8549
Phone: 81-3-5487-8345
Email: r14153@onsemi.com

Fax Response Line: 303-675-2167
800-344-3810 Toll Free USA/Canada

ON Semiconductor Website: <http://onsemi.com>

For additional information, please contact your local Sales Representative.

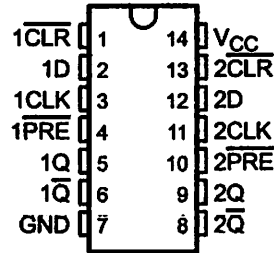
SN74LS76A/D

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

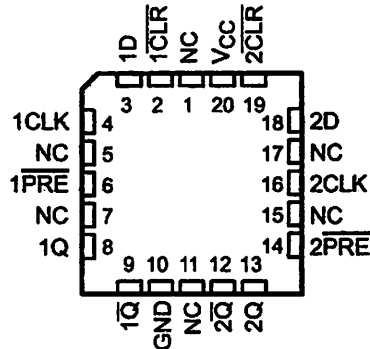
SDAS143C - APRIL 1982 - REVISED AUGUST 1985

- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

SN54ALS74A, SN54AS74A ... J PACKAGE
SN74ALS74A, SN74AS74A ... D OR N PACKAGE
(TOP VIEW)



SN54ALS74A, SN54AS74A ... FK PACKAGE
(TOP VIEW)



NC - No internal connection

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY (C _L = 50 pF) (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS74A	50	6
'AS74A	134	26

description

These devices contain two independent positive-edge-triggered D-type flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The SN54ALS74A and SN54AS74A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS74A and SN74AS74A are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS				OUTPUTS	
PRE	CLR	CLK	D	Q	Q-bar
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H†	H†
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q ₀	Q ₀ -bar

† The output levels in this configuration are not specified to meet the minimum levels for V_{OH} if the lows at PRE and CLR are near V_{IL} maximum. Furthermore, this configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



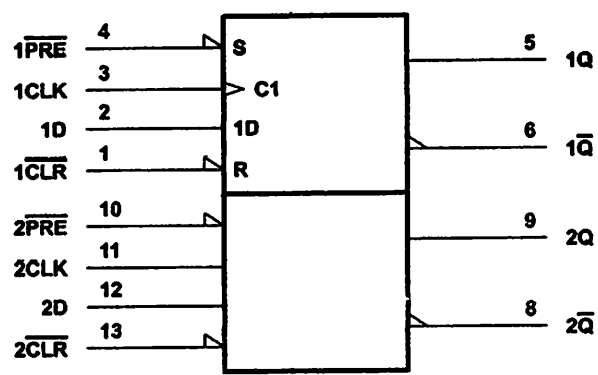
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 1995, Texas Instruments Incorporated

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A
DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH CLEAR AND PRESET

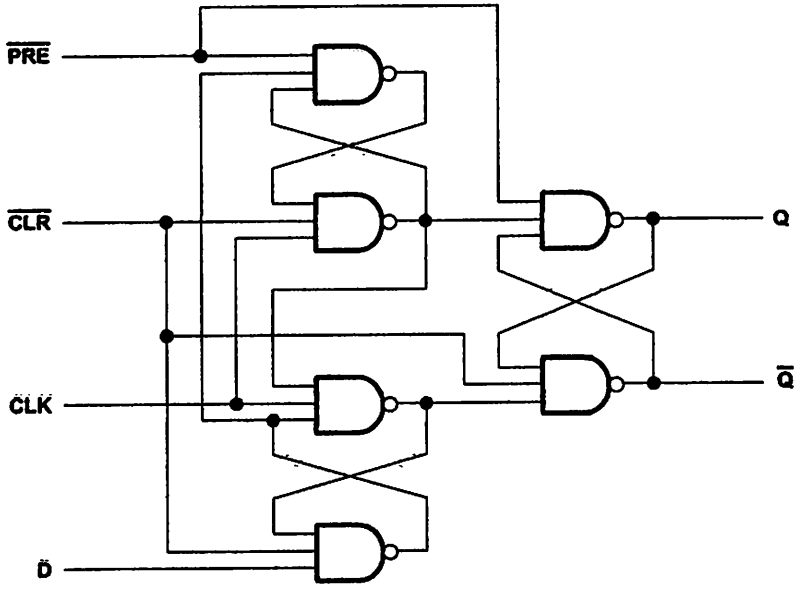
SDAS143C - APRIL 1982 - REVISED AUGUST 1995

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54ALS74A	-55°C to 125°C
SN74ALS74A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SDAS143C - APRIL 1982 - REVISED AUGUST 1995

recommended operating conditions

		SN54ALS74A			SN74ALS74A			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
V _{IH}	High-level input voltage	2			2			V	
V _{IL}	Low-level input voltage			0.7			0.8	V	
I _{OH}	High-level output current			-0.4			-0.4	mA	
I _{OL}	Low-level output current			4			8	mA	
f _{clock}	Clock frequency	0		25	0		34	MHz	
t _w	Pulse duration	PRE or CLR low		15			15	ns	
		CLK high		17.5			14.5		
		CLK low		17.5			14.5		
t _{su}	Setup time before CLK↑	Data		16			15	ns	
		PRE or CLR inactive		10			10		
t _h	Hold time after CLK↑	Data		2			0	ns	
T _A	Operating free-air temperature			-55		125	0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS74A		SN74ALS74A		UNIT		
				MIN	TYP†	MAX	MIN		TYP†	MAX
V _{IK}		V _{CC} = 4.5 V,	I _I = -18 mA			-1.5		-1.5	V	
V _{OH}		V _{CC} = 4.5 V to 5.5 V,	I _{OH} = -2 mA	V _{CC} -2			V _{CC} -2		V	
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 4 mA	0.25	0.4		0.25	0.4	V	
			I _{OL} = 8 mA				0.35	0.5		
I _I	CLK or D	V _{CC} = 4.5 V,	V _I = 7 V			0.1		0.1	mA	
	PRE or CLR					0.2		0.2		
I _{IH}	CLK or D	V _{CC} = 4.5 V,	V _I = 2.7 V			20		20	μA	
	PRE or CLR					40		40		
I _{IL}	CLK or D	V _{CC} = 4.5 V,	V _I = 0.4 V			-0.2		-0.2	mA	
	PRE or CLR					-0.4		-0.4		
I _{O‡}		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112		-112	mA	
I _{CC}		V _{CC} = 5.5 V,	See Note 1		2.4	4		2.4	4	mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

NOTE 1: I_{CC} is measured with D, CLK, and PRE grounded, then with D, CLK, and CLR grounded.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS

WITH CLEAR AND PRESET

DAS143C - APRIL 1982 - REVISED AUGUST 1985

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54ALS74A		SN74ALS74A		
			MIN	MAX	MIN	MAX	
f _{max}			25		34	MHz	
t _{PLH}	PRE or CLR	Q or Q̄	3	18	3	13	ns
t _{PHL}			5	17	5	15	
t _{PLH}	CLK	Q or Q	5	23	5	16	ns
t _{PHL}			5	20	5	18	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54AS74A	-55°C to 125°C
SN74AS74A	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS74A			SN74AS74A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{OH}	High-level output current			-2			-2	mA
I _{OL}	Low-level output current			20			20	mA
f _{clock} *	Clock frequency	0		90	0		105	MHz
t _w *	Pulse duration	PRE or CLR low		4		4		ns
		CLK high		4		4		
		CLK low		5.5		5.5		
t _{su} *	Setup time before CLK↑	Data		4.5		4.5		ns
		PRE or CLR inactive		2		2		
t _h *	Hold time after CLK↑	Data		0		0		ns
T _A	Operating free-air temperature	-55		125	0		70	°C

* On products compliant to MIL-STD-883C, Class B, this parameter is based on characterization data but is not production tested.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SDAS143C - APRIL 1982 - REVISED AUGUST 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54AS74A			SN74AS74A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$,	$I_I = -18 \text{ mA}$			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$,	$I_{OH} = -2 \text{ mA}$	$V_{CC}-2$			$V_{CC}-2$			V
V_{OL}	$V_{CC} = 4.5 \text{ V}$,	$I_{OL} = 20 \text{ mA}$	0.25	0.5		0.25	0.5		V
I_I	$V_{CC} = 5.5 \text{ V}$,	$V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH}	CLK or D	$V_{CC} = 5.5 \text{ V}$,	$V_I = 2.7 \text{ V}$			20		20	μA
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$					40		40	
I_{IL}	CLK or D	$V_{CC} = 5.5 \text{ V}$,	$V_I = 0.4 \text{ V}$			-0.5		-0.5	mA
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$					-1.8		-1.8	
$I_{O\ddagger}$	$V_{CC} = 5.5 \text{ V}$,	$V_O = 2.25 \text{ V}$	-30	-112		-30	-112		mA
I_{CC}	$V_{CC} = 5.5 \text{ V}$,	See Note 1	10.5	16		10.5	16		mA

† All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

NOTE 1: I_{CC} is measured with D, CLK, and $\overline{\text{PRE}}$ grounded, then with D, CLK, and $\overline{\text{CLR}}$ grounded.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $C_L = 50 \text{ pF}$, $R_L = 500 \Omega$, $T_A = \text{MIN to MAX}\S$				UNIT
			SN54AS74A		SN74AS74A		
			MIN	MAX	MIN	MAX	
f_{max}^*			90		105	MHz	
t_{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or \overline{Q}	2	9	2	7.5	ns
t_{PHL}			2.5	11.5	2.5	10.5	
t_{PLH}	CLK	Q or \overline{Q}	2.5	10	3	8	ns
t_{PHL}			3.5	10.5	3	9	

* On products compliant to MIL-STD-883C, Class B, this parameter is based on characterization data but is not production tested.

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

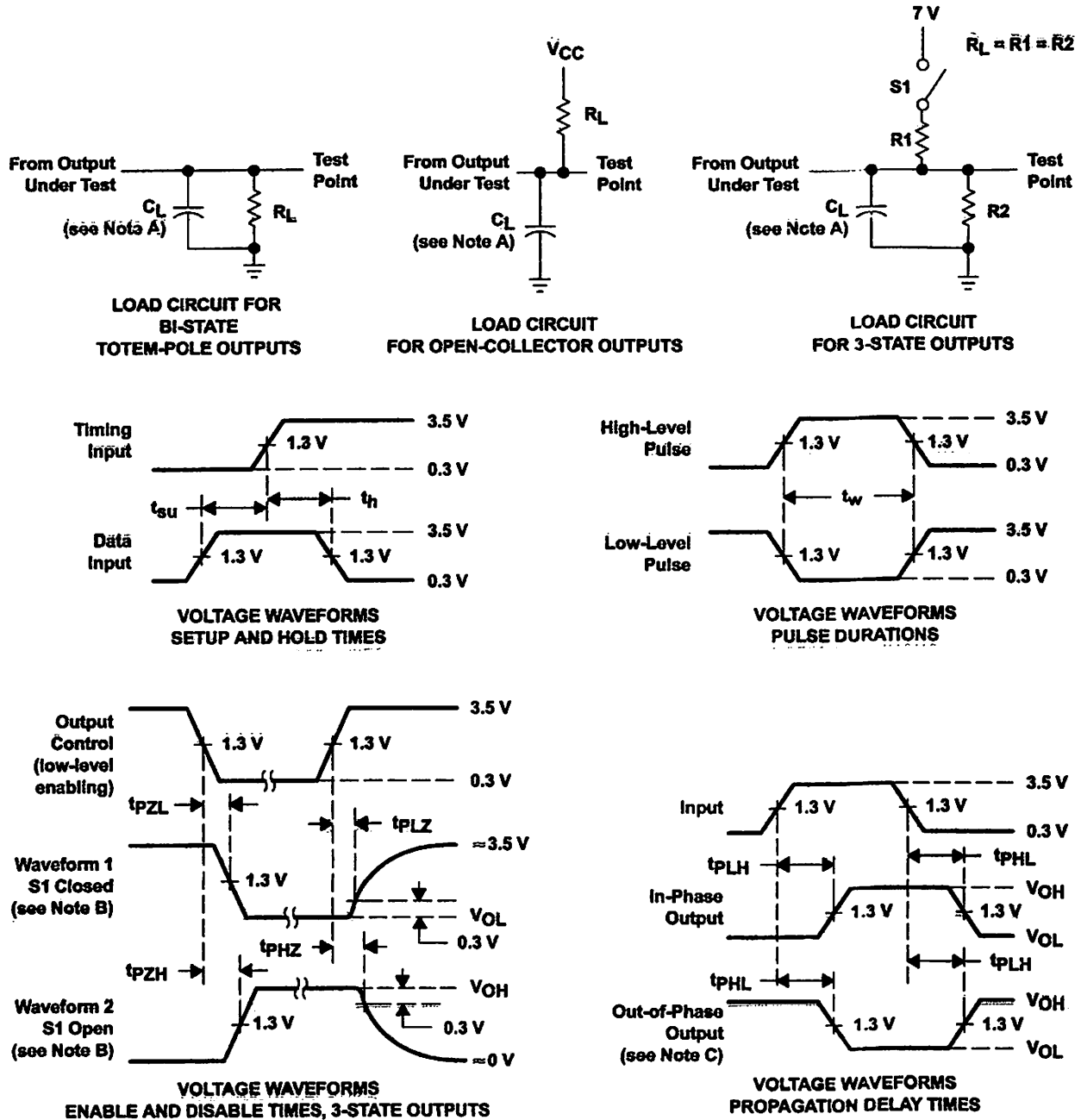


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A
DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS
WITH CLEAR AND PRESET

SDAS143C - APRIL 1982 - REVISED AUGUST 1995

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES:**
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

DM74LS86

Quad 2-Input Exclusive-OR Gate

General Description

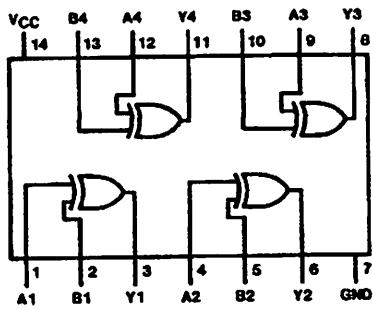
This device contains four independent gates each of which performs the logic exclusive-OR function.

Ordering Code:

Order Number	Package Number	Package Description
DM74LS86M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
DM74LS86SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
DM74LS86N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram



Function Table

$$Y = A \oplus B = \bar{A}B + A\bar{B}$$

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

H = HIGH Logic Level
L = LOW Logic Level

DM74LS86 Quad 2-Input Exclusive-OR Gate

Absolute Maximum Ratings(Note 1)

Supply Voltage	7V
Input Voltage	7V
Operating Free Air Temperature Range	0°C to +70°C
Storage Temperature Range	-65°C to +150°C

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Recommended Operating Conditions

Symbol	Parameter	Min	Nom	Max	Units
V _{CC}	Supply Voltage	4.75	5	5.25	V
V _{IH}	HIGH Level Input Voltage	2			V
V _{IL}	LOW Level Input Voltage			0.8	V
I _{OH}	HIGH Level Output Current			-0.4	mA
I _{OL}	LOW Level Output Current			8	mA
T _A	Free Air Operating Temperature	0		70	°C

Electrical Characteristics

over recommended operating free air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ (Note 2)	Max	Units
V _I	Input Clamp Voltage	V _{CC} = Min, I _I = -18 mA			-1.5	V
V _{OH}	HIGH Level Output Voltage	V _{CC} = Min, I _{OH} = Max, V _{IL} = Max, V _{IH} = Min	2.7	3.4		V
V _{OL}	LOW Level Output Voltage	V _{CC} = Min, I _{OL} = Max, V _{IL} = Max, V _{IH} = Min I _{OL} = 4 mA, V _{CC} = Min		0.35	0.5	V
I _I	Input Current @ Max Input Voltage	V _{CC} = Max, V _I = 7V			0.2	mA
I _{IH}	HIGH Level Input Current	V _{CC} = Max, V _I = 2.7V			40	μA
I _{IL}	LOW Level Input Current	V _{CC} = Max, V _I = 0.4V			-0.6	mA
I _{OS}	Short Circuit Output Current	V _{CC} = Max (Note 3)	-20		-100	mA
I _{CC}	Supply Current with Outputs HIGH	V _{CC} = Max (Note 4)		6.1	10	mA
I _{CC}	Supply Current with Outputs LOW	V _{CC} = Max (Note 5)		9	15	mA

Note 2: All typicals are at V_{CC} = 5V, T_A = 25°C.

Note 3: Not more than one output should be shorted at a time, and the duration should not exceed one second.

Note 4: I_{CC} is measured with all outputs OPEN, one input at each gate at 4.5V, and the other inputs grounded.

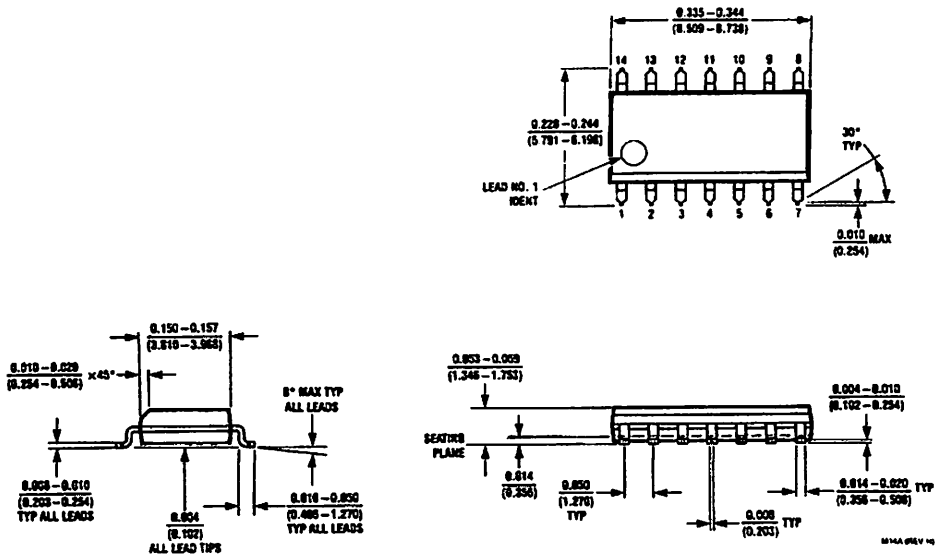
Note 5: I_{CC} is measured with all outputs OPEN and all inputs grounded.

Switching Characteristics

at V_{CC} = 5V and T_A = 25°C

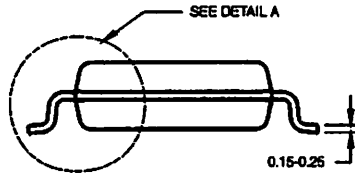
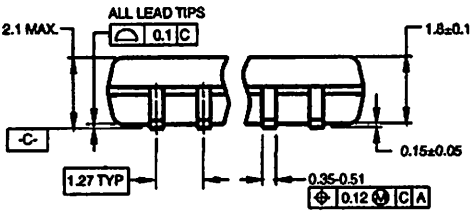
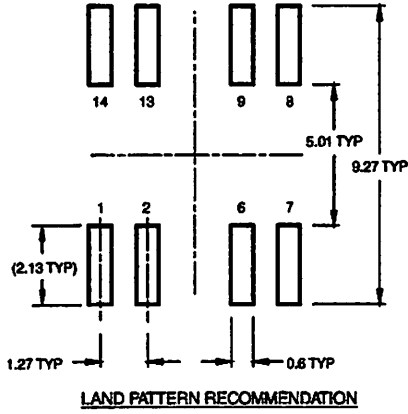
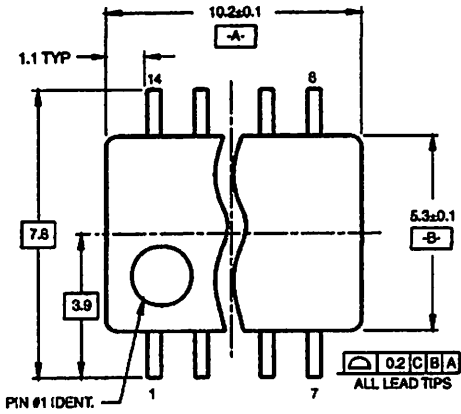
Symbol	Parameter	Conditions	R _L = 2 kΩ				Units
			C _L = 15 pF		C _L = 50 pF		
			Min	Max	Min	Max	
t _{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Other Input Low		18		23	ns
t _{PHL}	Propagation Delay Time HIGH-to-LOW Level Output			17		21	ns
t _{PLH}	Propagation Delay Time LOW-to-HIGH Level Output	Other Input High		10		15	ns
t _{PHL}	Propagation Delay Time HIGH-to-LOW Level Output			12		15	ns

Physical Dimensions Inches (millimeters) unless otherwise noted



14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow Package Number M14A

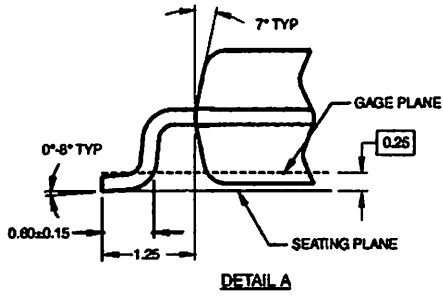
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

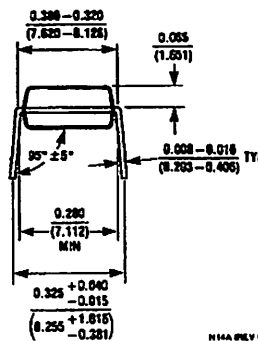
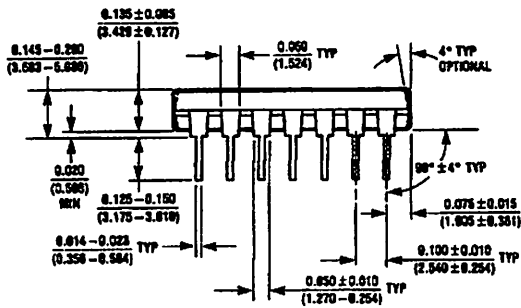
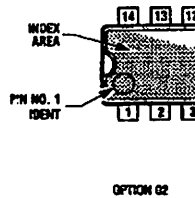
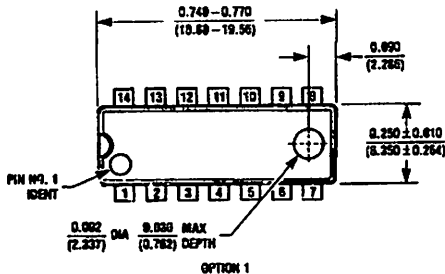
- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1988.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND THE BAR EXTRUSIONS.

M14DRevB1



**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
 Package Number M14D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N14A

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

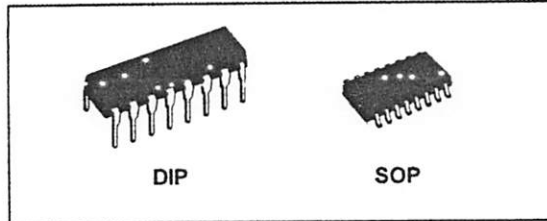
www.fairchildsemi.com



HCF4060B

14-STAGE RIPPLE CARRY BINARY COUNTER/DIVIDER AND OSCILLATOR

- MEDIUM-SPEED OPERATION
- COMMON RESET
- FULLY STATIC OPERATION
- BUFFERED INPUTS AND OUTPUTS
- QUIESCENT CURRENT SPECIFIED UP TO 20V
- 5V, 10V AND 15V PARAMETRIC RATINGS
- INPUT LEAKAGE CURRENT
 $I_l = 100\text{nA (MAX) AT } V_{DD} = 18\text{V } T_A = 25^\circ\text{C}$
- 100% TESTED FOR QUIESCENT CURRENT
- MEETS ALL REQUIREMENTS OF JEDEC JESD13B "STANDARD SPECIFICATIONS FOR DESCRIPTION OF B SERIES CMOS DEVICES"



ORDER CODES

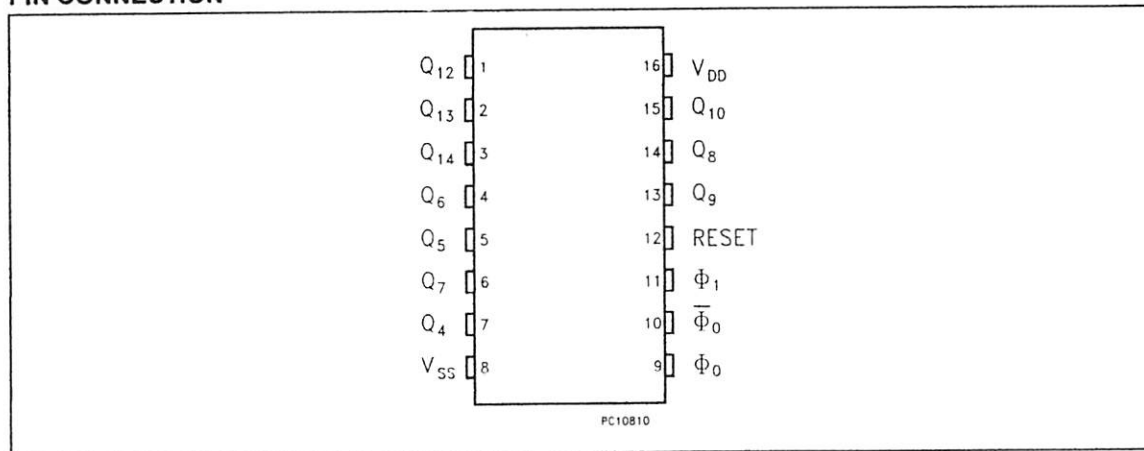
PACKAGE	TUBE	T & R
DIP	HCF4060BEY	
SOP	HCF4060BM1	HCF4060M013TR

DESCRIPTION

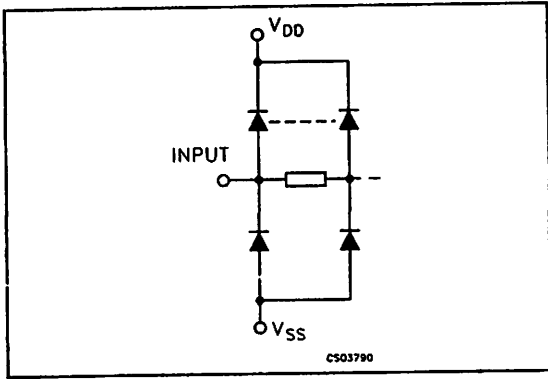
The HCF4060B is a monolithic integrated circuit fabricated in Metal Oxide Semiconductor technology available in DIP and SOP packages. The HCF4060B consists of an oscillator section and 14 ripple carry binary counter stages. The oscillator configuration allows design of either RC or crystal oscillator circuits. A RESET input is provided which reset the counter to the all 0's

state and disable oscillator. A high level on the RESET line accomplishes the reset function. All counter stages are master slave flip-flops. The state of the counter is advanced one step in binary order on the negative transition of ϕ_1 (and ϕ_0). All inputs and outputs are fully buffered. Schmitt trigger action on the clock pin permits unlimited clock rise and fall time.

PIN CONNECTION



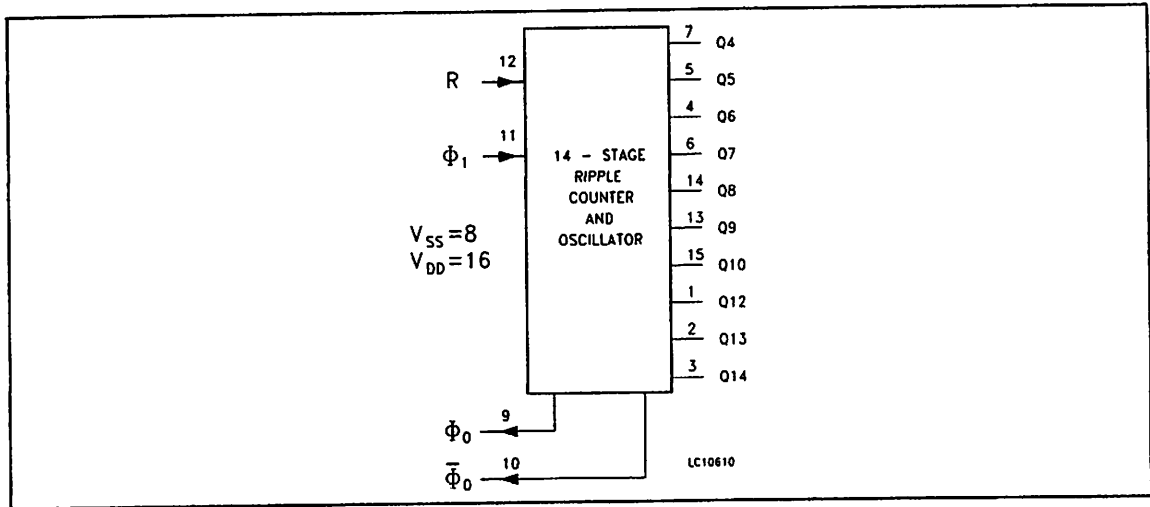
INPUT EQUIVALENT CIRCUIT



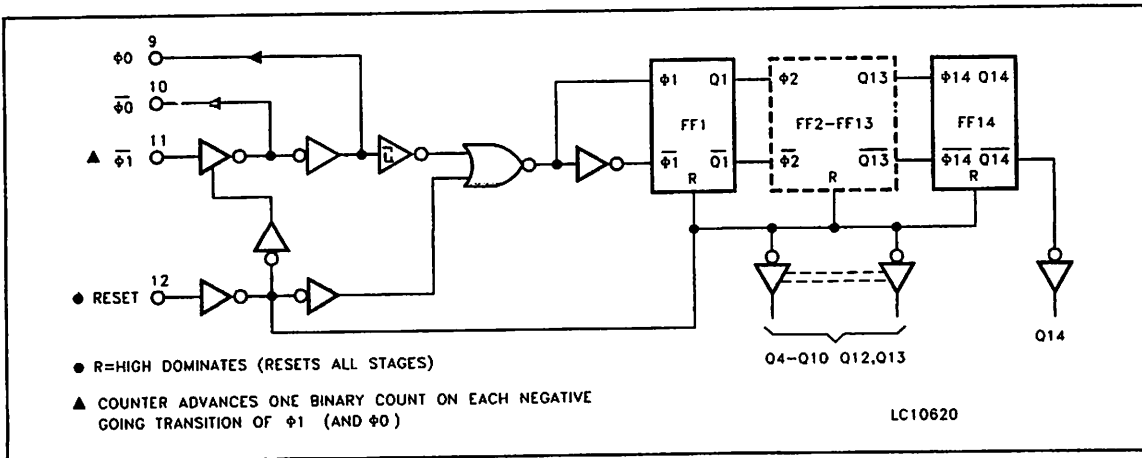
PIN DESCRIPTION

PIN No	SYMBOL	NAME AND FUNCTION
1, 2, 3, 4, 5, 6, 7, 13, 14, 15	$Q_{12}, Q_{13}, Q_{14}, Q_6, Q_5, Q_7, Q_4, Q_9, Q_8, Q_{10}$	Outputs
9, 10, 11	$\Phi_0, \bar{\Phi}_0, \Phi_1$	Oscillator Input
12	RESET	Reset
8	V_{SS}	Negative Supply Voltage
16	V_{DD}	Positive Supply Voltage

FUNCTIONAL DIAGRAM



LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{DD}	Supply Voltage	-0.5 to +22	V
V_I	DC Input Voltage	-0.5 to $V_{DD} + 0.5$	V
I_I	DC Input Current	± 10	mA
P_D	Power Dissipation per Package	200	mW
	Power Dissipation per Output Transistor	100	mW
T_{op}	Operating Temperature	-55 to +125	°C
T_{stg}	Storage Temperature	-65 to +150	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied.

All voltage values are referred to V_{SS} pin voltage.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Value	Unit
V_{DD}	Supply Voltage	3 to 20	V
V_I	Input Voltage	0 to V_{DD}	V
T_{op}	Operating Temperature	-55 to 125	°C

DC SPECIFICATIONS

Symbol	Parameter	Test Condition				Value						Unit	
		V _I (V)	V _O (V)	I _O (μ A)	V _{DD} (V)	T _A = 25°C			-40 to 85°C		-55 to 125°C		
						Min.	Typ.	Max.	Min.	Max.	Min.		Max.
I _L	Quiescent Current	0/5			5		0.04	5		5		150	μ A
		0/10			10		0.04	10		10		300	
		0/15			15		0.04	20		20		600	
		0/20			20		0.08	100		100		3000	
V _{OH}	High Level Output Voltage	0/5		<1	5	4.95			4.95		4.95		V
		0/10		<1	10	9.95			9.95		9.95		
		0/15		<1	15	14.95			14.95		14.95		
V _{OL}	Low Level Output Voltage	5/0		<1	5		0.05			0.05		0.05	V
		10/0		<1	10		0.05			0.05		0.05	
		15/0		<1	15		0.05			0.05		0.05	
V _{IH}	High Level Input Voltage		0.5/4.5	<1	5	3.5			3.5		3.5		V
			1/9	<1	10	7			7		7		
			1.5/13.5	<1	15	11			11		11		
V _{IL}	Low Level Input Voltage		4.5/0.5	<1	5		1.5		1.5		1.5		V
			9/1	<1	10		3		3		3		
			13.5/1.5	<1	15		4		4		4		
I _{OH}	Output Drive Current	0/5	2.5	<1	5	-1.36	-3.2		-1.15		-1.1		mA
		0/5	4.6	<1	5	-0.44	-1		-0.36		-0.36		
		0/10	9.5	<1	10	-1.1	-2.6		-0.9		-0.9		
		0/15	13.5	<1	15	-3.0	-6.8		-2.4		-2.4		
I _{OL}	Output Sink Current	0/5	0.4	<1	5	0.44	1		0.36		0.36		mA
		0/10	0.5	<1	10	1.1	2.6		0.9		0.9		
		0/15	1.5	<1	15	3.0	6.8		2.4		2.4		
I _I	Input Leakage Current	0/18	Any Input	18		$\pm 10^{-5}$	± 0.3		± 0.3		± 1	μ A	
C _I	Input Capacitance		Any Input			5	7.5					pF	

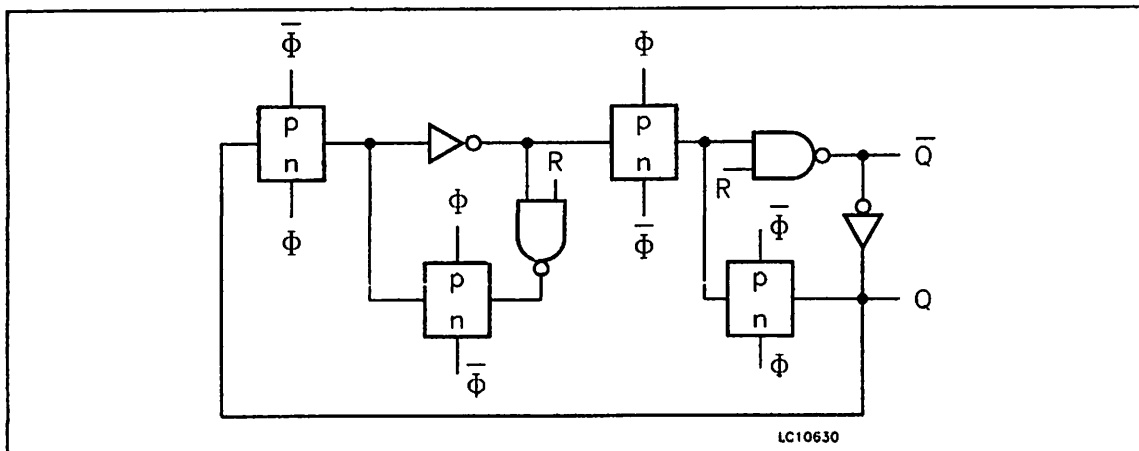
The Noise Margin for both "1" and "0" level is: 1V min. with V_{DD}=5V, 2V min. with V_{DD}=10V, 2.5V min. with V_{DD}=15V

DYNAMIC ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$, $C_L = 50\text{pF}$, $R_L = 200\text{K}\Omega$, $t_r = t_f = 20\text{ ns}$)

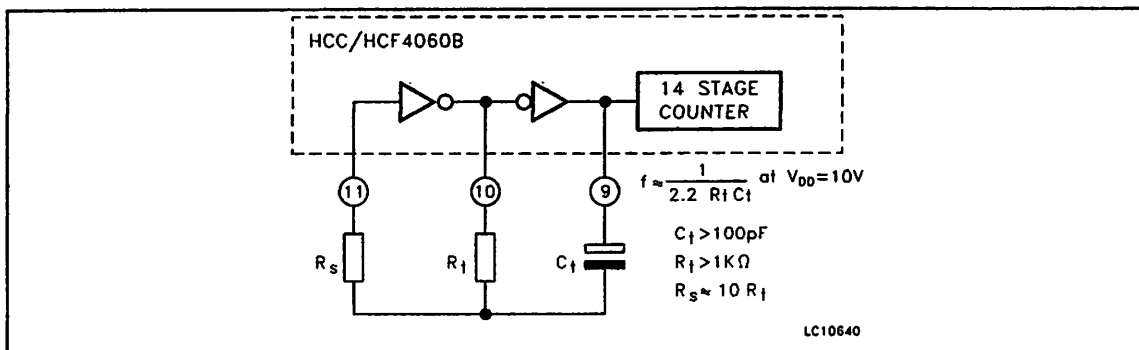
Symbol	Parameter	Test Condition		Value (*)			Unit
		V_{DD} (V)		Min.	Typ.	Max.	
t_{TLH} t_{THL}	Output Transition Time	5			100	200	ns
		10			50	100	
		15			40	80	
t_{PLH} t_{PHL}	Propagation Delay Time (ϕ to Q_4 out)	5			370	740	ns
		10			150	300	
		15			100	200	
t_{PLH} t_{PHL}	Propagation Delay Time (Q_n to Q_{n+1})	5			100	200	ns
		10			50	100	
		15			40	80	
t_w	Input Pulse Width	5	$f = 100\text{ KHz}$		50	100	ns
		10			20	40	
		15			15	30	
t_r t_f	Input Pulse Rise and Fall Time	5		Unlimited			μs
		10					
		15					
f_{max}	Maximum Clock Input Frequency	5		3.5	7		MHz
		10		8	16		
		15		12	24		
RESET OPERATION							
t_{PHL}	Propagation Delay Time	5			180	360	ns
		10			80	160	
		15			50	100	
t_w	Input Pulse Width	5			60	120	ns
		10			30	60	
		15			20	40	
RC OPERATION							
	Variation of Frequency (Unit-to-Unit)	5	$C_X = 200\text{pF}$, $R_S = 560\text{K}\Omega$, $R_X = 50\text{K}\Omega$	18	21.5	25	KHz
		10		20	23	26	
		15		21.1	24	27	
	Variation of Frequency With Voltage Change (Same Unit)	5 to 10	$C_X = 200\text{pF}$, $R_S = 560\text{K}\Omega$, $R_X = 50\text{K}\Omega$			2	KHz
		10 to 15				1	
R_X		5	$C_X = 10\mu\text{F}$			20	$\text{M}\Omega$
		10	$C_X = 50\mu\text{F}$			20	
		15	$C_X = 10\mu\text{F}$			10	
C_X		5	$R_X = 500\text{K}\Omega$			1000	μF
		10	$R_X = 300\text{K}\Omega$			50	
		15	$R_X = 300\text{K}\Omega$			50	
	Maximum Oscillator Frequency (**)	10	$R_X = 5\text{K}\Omega$, $C_X = 15\text{pF}$	530	650	810	KHz
		15		690	800	940	

(*) Typical temperature coefficient for all V_{DD} values is 0.3%/°C, all input rise and fall times= 20 ns.(**) RC Oscillator applications are not recommended at supply voltages below 7V for $R_X < 50\text{K}\Omega$

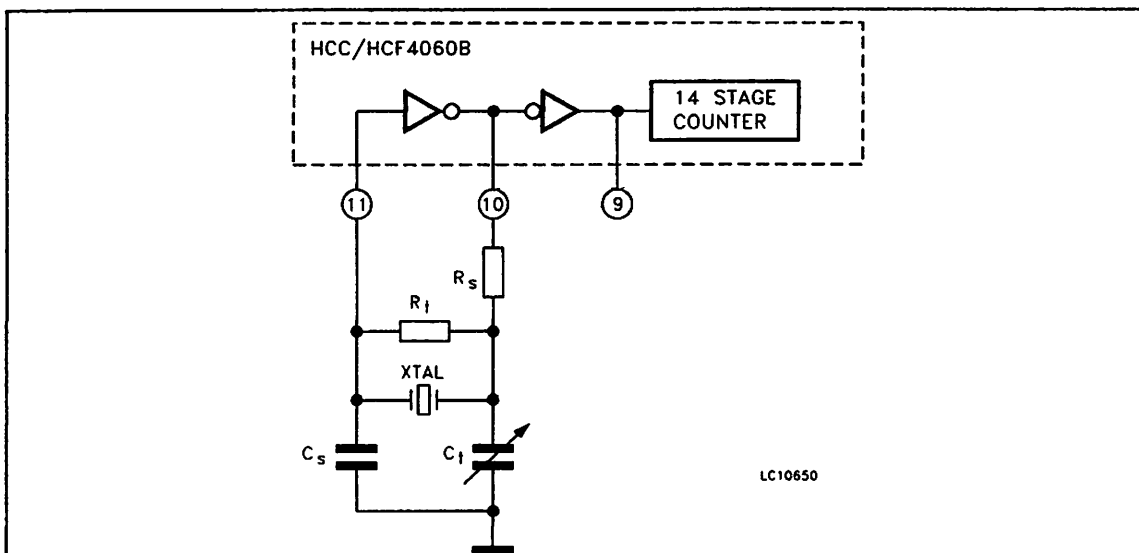
DETAIL OF TYPICAL FLIP-FLOP STAGE



TYPICAL RC OSCILLATOR CIRCUIT

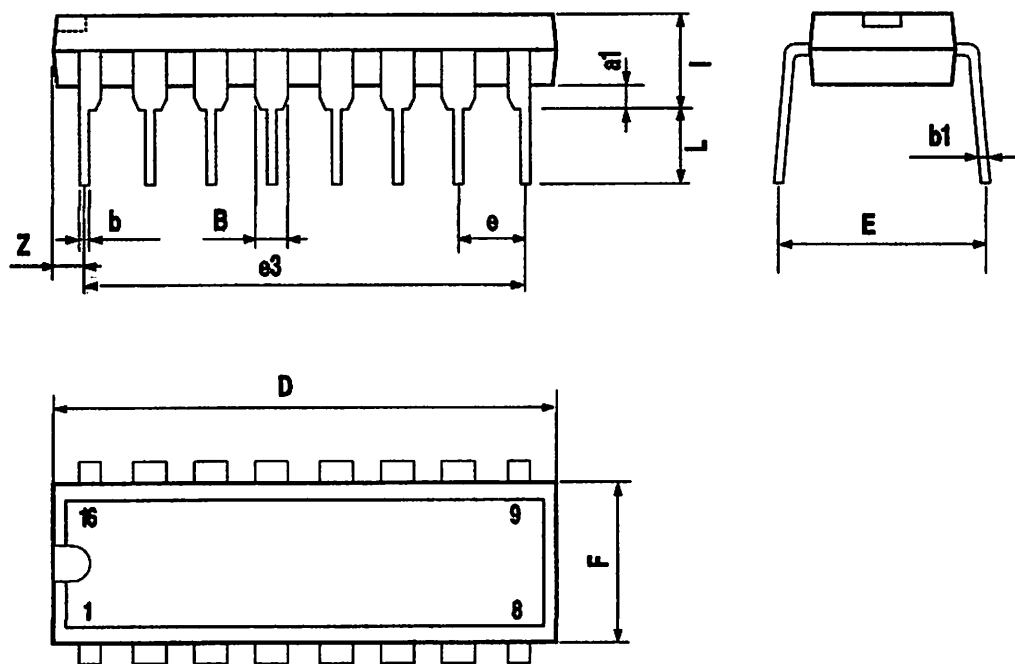


TYPICAL CRYSTAL OSCILLATOR CIRCUIT



Plastic DIP-16 (0.25) MECHANICAL DATA

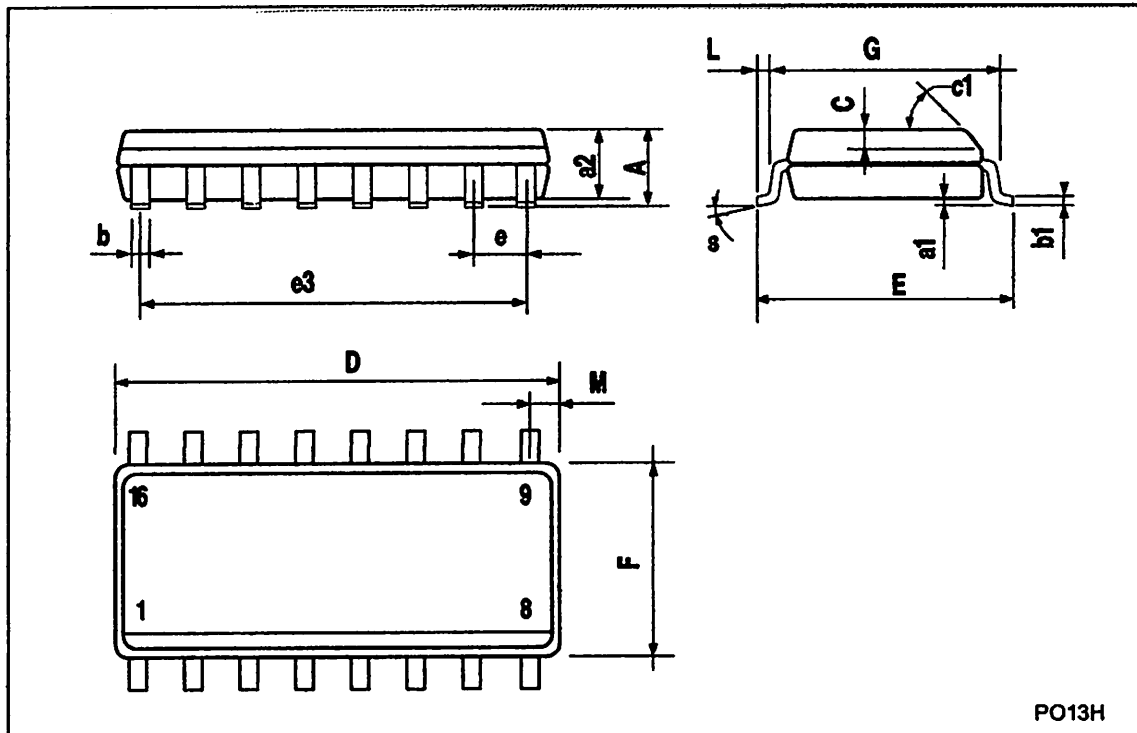
DIM.	mm.			Inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
l			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



P001C

SO-16 MECHANICAL DATA

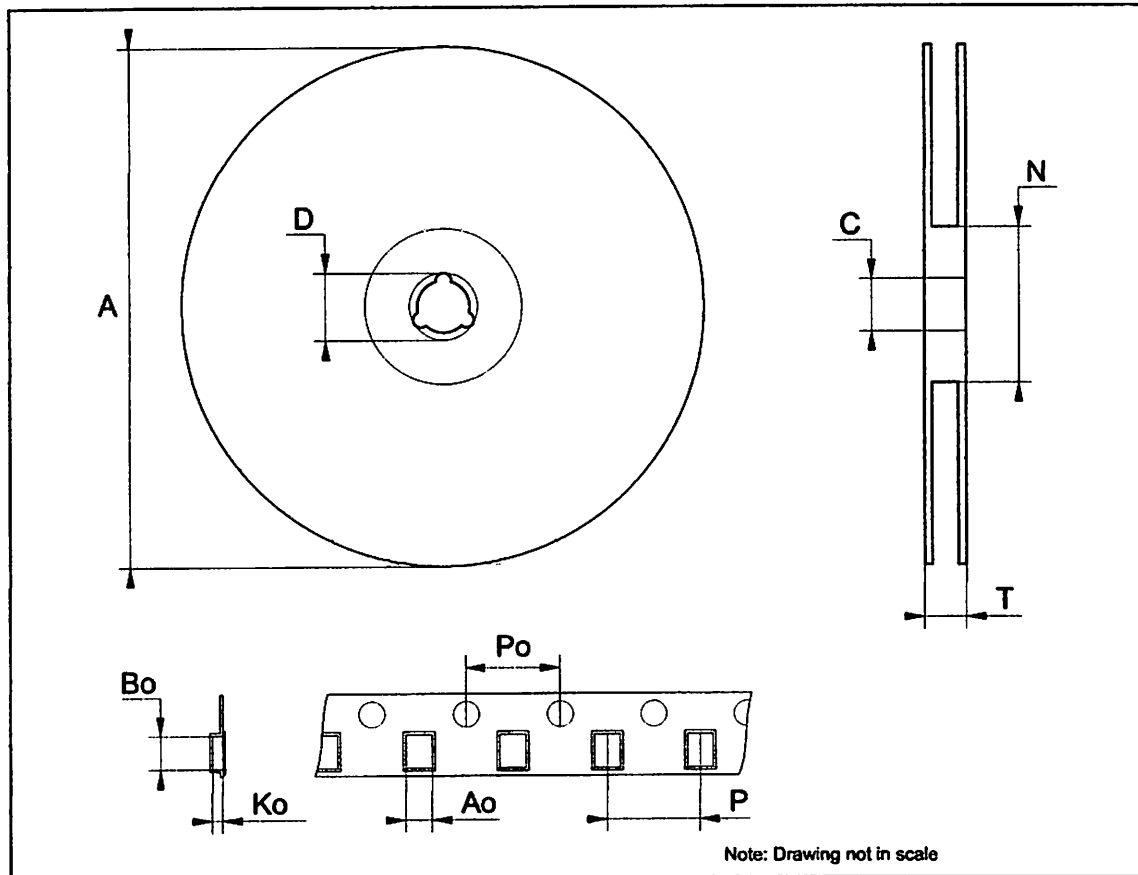
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.004		0.008
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S	8			° (max.)		



PO13H

Tape & Reel SO-16 MECHANICAL DATA

DIM.	mm.			Inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.45		6.65	0.254		0.262
Bo	10.3		10.5	0.406		0.414
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

© The ST logo is a registered trademark of STMicroelectronics

© 2003 STMicroelectronics - Printed in Italy - All Rights Reserved
STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco
Singapore - Spain - Sweden - Switzerland - United Kingdom - United States.

© <http://www.st.com>



PRESETTABLE BCD/DECADE UP/DOWN COUNTER

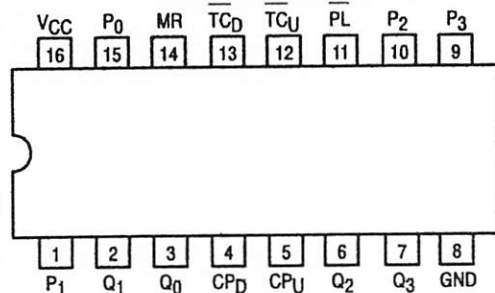
PRESETTABLE 4-BIT BINARY UP/DOWN COUNTER

The SN54/74LS192 is an UP/DOWN BCD Decade (8421) Counter and the SN54/74LS193 is an UP/DOWN MODULO-16 Binary Counter. Separate Count Up and Count Down Clocks are used and in either counting mode the circuits operate synchronously. The outputs change state synchronous with the LOW-to-HIGH transitions on the clock inputs.

Separate Terminal Count Up and Terminal Count Down outputs are provided which are used as the clocks for a subsequent stages without extra logic, thus simplifying multistage counter designs. Individual preset inputs allow the circuits to be used as programmable counters. Both the Parallel Load (PL) and the Master Reset (MR) inputs asynchronously override the clocks.

- Low Power . . . 95 mW Typical Dissipation
- High Speed . . . 40 MHz Typical Count Frequency
- Synchronous Counting
- Asynchronous Master Reset and Parallel Load
- Individual Preset Inputs
- Cascading Circuitry Internally Provided
- Input Clamp Diodes Limit High Speed Termination Effects

CONNECTION DIAGRAM DIP (TOP VIEW)



NOTE:
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

PIN NAMES

CP _U	Count Up Clock Pulse Input
CP _D	Count Down Clock Pulse Input
MR	Asynchronous Master Reset (Clear) Input
PL	Asynchronous Parallel Load (Active LOW) Input
P _n	Parallel Data Inputs
Q _n	Flip-Flop Outputs (Note b)
TC _D	Terminal Count Down (Borrow) Output (Note b)
TC _U	Terminal Count Up (Carry) Output (Note b)

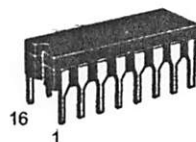
LOADING (Note a)

	HIGH	LOW
CP _U	0.5 U.L.	0.25 U.L.
CP _D	0.5 U.L.	0.25 U.L.
MR	0.5 U.L.	0.25 U.L.
PL	0.5 U.L.	0.25 U.L.
P _n	0.5 U.L.	0.25 U.L.
Q _n	10 U.L.	5 (2.5) U.L.
TC _D	10 U.L.	5 (2.5) U.L.
TC _U	10 U.L.	5 (2.5) U.L.

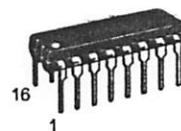
NOTES:
a. 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.
b. The Output LOW drive factor is 2.5 U.L. for Military (54) and 5 U.L. for Commercial (74) Temperature Ranges.

SN54/74LS192 SN54/74LS193

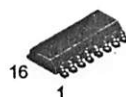
PRESETTABLE BCD/DECADE
UP/DOWN COUNTER
PRESETTABLE 4-BIT BINARY
UP/DOWN COUNTER
LOW POWER SCHOTTKY



J SUFFIX
CERAMIC
CASE 620-08



N SUFFIX
PLASTIC
CASE 648-08

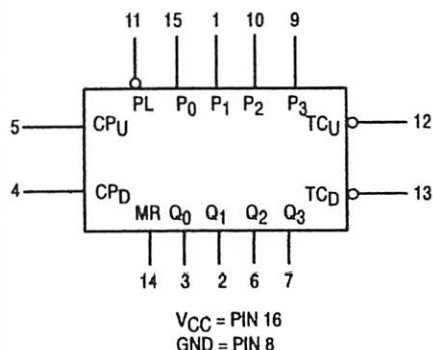


D SUFFIX
SOIC
CASE 751B-03

ORDERING INFORMATION

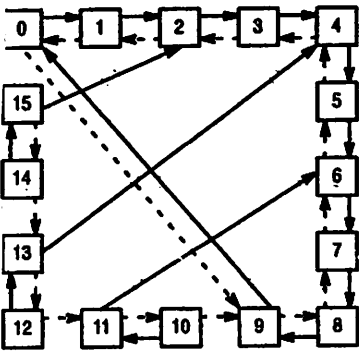
SN54LSXXXJ	Ceramic
SN74LSXXXN	Plastic
SN74LSXXXD	SOIC

LOGIC SYMBOL



SN54/74LS192 • SN54/74LS193

STATE DIAGRAMS



LS192

LS192 LOGIC EQUATIONS FOR TERMINAL COUNT

$$\overline{TC}_U = Q_0 \cdot Q_3 \cdot \overline{CPU} \cdot \overline{CPD}$$

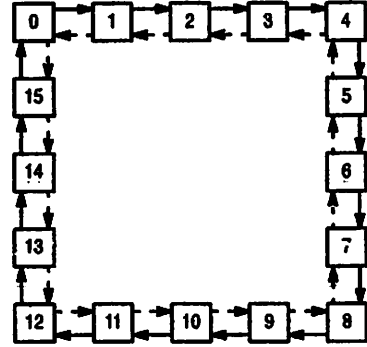
$$TC_D = Q_0 \cdot Q_1 \cdot Q_2 \cdot Q_3 \cdot CPD$$

LS193 LOGIC EQUATIONS FOR TERMINAL COUNT

$$\overline{TC}_U = Q_0 \cdot Q_1 \cdot Q_2 \cdot Q_3 \cdot \overline{CPU}$$

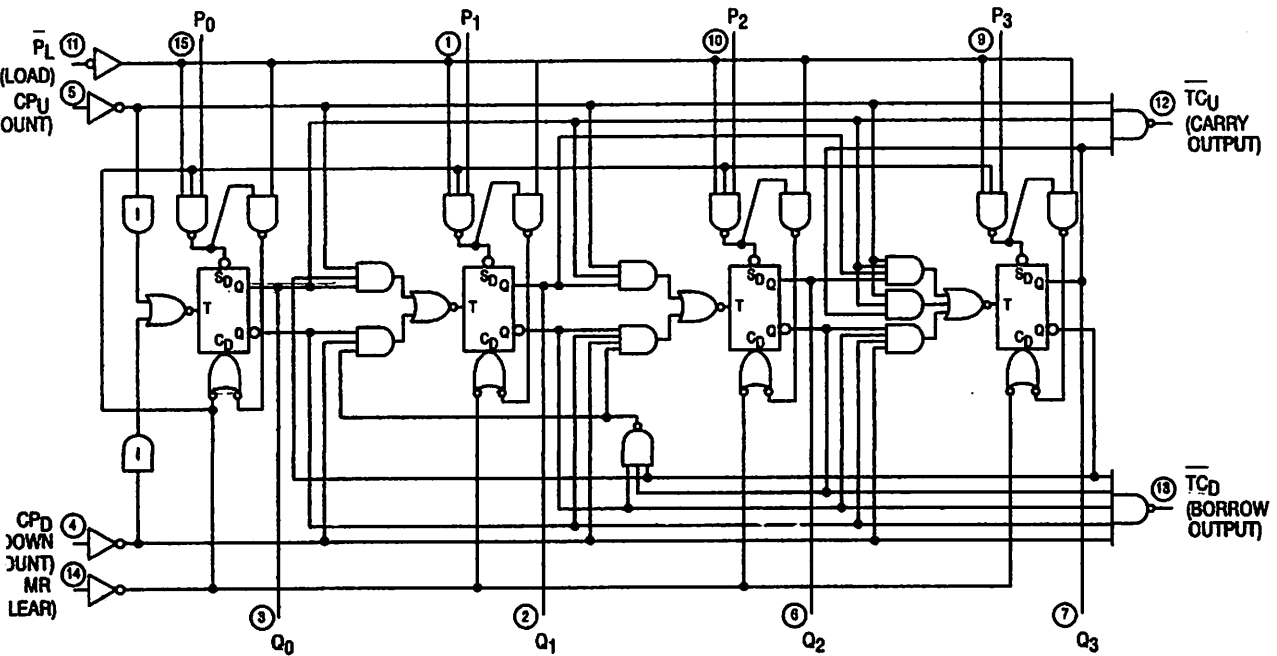
$$TC_D = Q_0 \cdot Q_1 \cdot Q_2 \cdot Q_3 \cdot CPD$$

COUNT UP ———
COUNT DOWN - - - - -



LS193

LOGIC DIAGRAMS

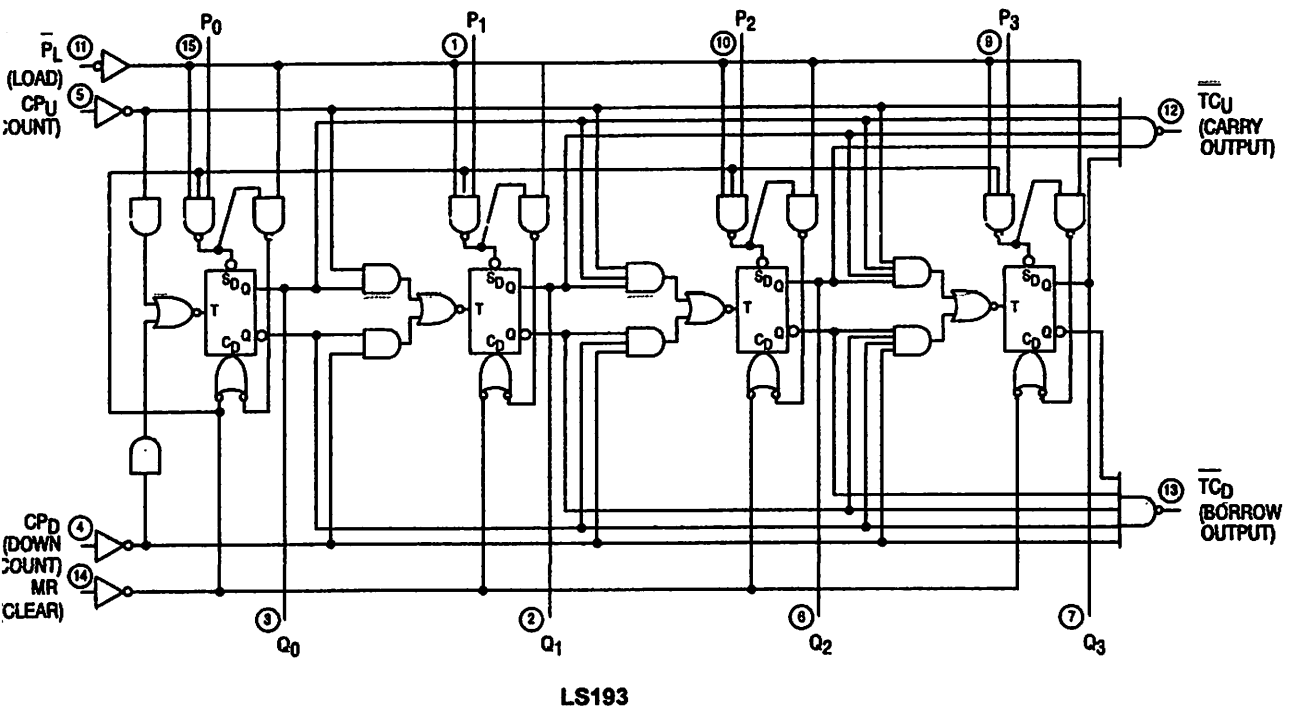


LS192

C = PIN 16
D = PIN 8
i = PIN NUMBERS

SN54/74LS192 • SN54/74LS193

LOGIC DIAGRAMS (continued)



V_{CC} = PIN 16
 GND = PIN 8
 ○ = PIN NUMBERS

SN54/74LS192 • SN54/74LS193

FUNCTIONAL DESCRIPTION

The LS192 and LS193 are Asynchronously Presettable Decade and 4-Bit Binary Synchronous UP/DOWN (Reversible) Counters. The operating modes of the LS192 decade counter and the LS193 binary counter are identical, with the only difference being the count sequences as noted in the Timing Diagrams. Each circuit contains four master/slave flip-flops, with internal gating and steering logic to provide master reset, individual preset, count up and count down operations.

Each flip-flop contains JK feedback from slave to master such that a LOW-to-HIGH transition on its T input causes the output to toggle, and thus the Q output to change state. Synchronous counting, as opposed to ripple counting, is achieved by driving the steering gates of all stages from a common Count Up line and a common Count Down line, thereby causing all state changes to be initiated simultaneously. A LOW-to-HIGH transition on the Count Up input will advance the count by one; a similar transition on the Count Down input will decrease the count by one. While counting with one clock input, the other clock input should be held HIGH. Otherwise, the circuit will either count by one or not at all, depending on the state of the first flip-flop, which cannot toggle as long as either Clock input is LOW.

The Terminal Count Up (\overline{TCU}) and Terminal Count Down (\overline{TCD}) outputs are normally HIGH. When a circuit has reached the maximum count state (9 for the LS192, 15 for the LS193), the next HIGH-to-LOW transition of the Count Up Clock will cause \overline{TCU} to go LOW. \overline{TCU} will stay LOW until CP_U goes HIGH again, thus effectively repeating the Count Up Clock, but delayed by two gate delays. Similarly, the \overline{TCD} output will go LOW when the circuit is in the zero state and the Count Down Clock goes LOW. Since the TC outputs repeat the clock waveforms, they can be used as the clock input signals to the next higher order circuit in a multistage counter.

Each circuit has an asynchronous parallel load capability permitting the counter to be preset. When the Parallel Load (PL) and the Master Reset (MR) inputs are LOW, information present on the Parallel Data inputs (P_0, P_3) is loaded into the counter and appears on the outputs regardless of the conditions of the clock inputs. A HIGH signal on the Master Reset input will disable the preset gates, override both Clock inputs, and latch each Q output in the LOW state. If one of the Clock inputs is LOW during and after a reset or load operation, the next LOW-to-HIGH transition of that Clock will be interpreted as a legitimate signal and will be counted.

MODE SELECT TABLE

MR	PL	CP _U	CP _D	MODE
H	X	X	X	Reset (Asyn.)
L	L	X	X	Preset (Asyn.)
L	H	H	H	No Change
L	H	⌋	H	Count Up
L	H	H	⌋	Count Down

L = LOW Voltage Level

H = HIGH Voltage Level

X = Don't Care

⌋ = LOW-to-HIGH Clock Transition

SN54/74LS192 • SN54/74LS193

GUARANTEED OPERATING RANGES

Symbol	Parameter		Min	Typ	Max	Unit
V _{CC}	Supply Voltage	54 74	4.5 4.75	5.0 5.0	5.5 5.25	V
T _A	Operating Ambient Temperature Range	54 74	-55 0	25 25	125 70	°C
I _{OH}	Output Current — High	54, 74			-0.4	mA
I _{OL}	Output Current — Low	54 74			4.0 8.0	mA

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions	
		Min	Typ	Max			
V _{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V _{IL}	Input LOW Voltage	54		0.7	V	Guaranteed Input LOW Voltage for All Inputs	
		74		0.8			
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA	
V _{OH}	Output HIGH Voltage	54	2.5	3.5	V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table	
		74	2.7	3.5	V		
V _{OL}	Output LOW Voltage	54, 74		0.25	0.4	V	I _{OL} = 4.0 mA V _{CC} = V _{CC} MIN, V _{IN} = V _{IL} or V _{IH} per Truth Table
		74		0.35	0.5	V	
I _{IH}	Input HIGH Current			20	μA	V _{CC} = MAX, V _{IN} = 2.7 V	
				0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V	
I _{IL}	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V	
I _{OS}	Short Circuit Current (Note 1)	-20		-100	mA	V _{CC} = MAX	
I _{CC}	Power Supply Current			34	mA	V _{CC} = MAX	

Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f _{MAX}	Maximum Clock Frequency	25	32		MHz	V _{CC} = 5.0 V C _L = 15 pF
t _{PLH} t _{PHL}	C _{EU} Input to T _{CU} Output		17 18	26 24	ns	
t _{PLH} t _{PHL}	C _{ED} Input to T _{CD} Output		16 15	24 24	ns	
t _{PLH} t _{PHL}	Clock to Q		27 30	38 47	ns	
t _{PLH} t _{PHL}	\overline{PL} to Q		24 25	40 40	ns	
t _{PHL}	MR Input to Any Output		23	35	ns	

FAST AND LS TTL DATA

SN54/74LS192 • SN54/74LS193

SETUP REQUIREMENTS ($T_A = 25^\circ\text{C}$)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
	Any Pulse Width	20			ns	$V_{CC} = 5.0\text{ V}$
	Data Setup Time	20			ns	
	Data Hold Time	5.0			ns	
	Recovery Time	40			ns	

DEFINITIONS OF TERMS

SETUP TIME (t_s) is defined as the minimum time required for correct logic level to be present at the logic input prior to the transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

DATA HOLD TIME (t_h) is defined as the minimum time following the transition from LOW-to-HIGH that the logic level must be maintained at the input in order to ensure continued recogni-

tion. A negative HOLD TIME indicates that the correct logic level may be released prior to the PL transition from LOW-to-HIGH and still be recognized.

RECOVERY TIME (t_{rec}) is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW-to-HIGH in order to recognize and transfer HIGH data to the Q outputs.

SN54/74LS192 • SN54/74LS193

AC WAVEFORMS

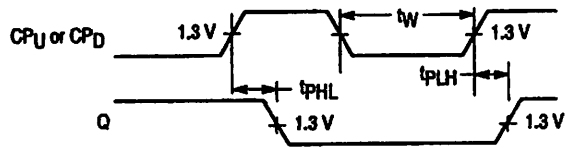


Figure 1

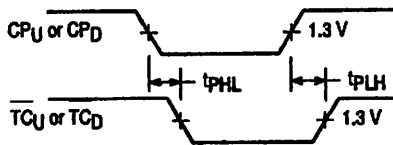
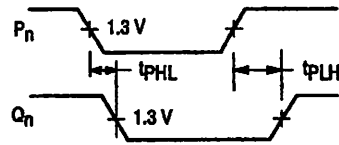


Figure 2



NOTE: $\overline{PL} = \text{LOW}$

Figure 3

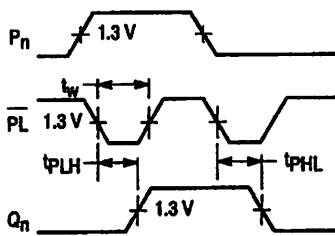


Figure 4

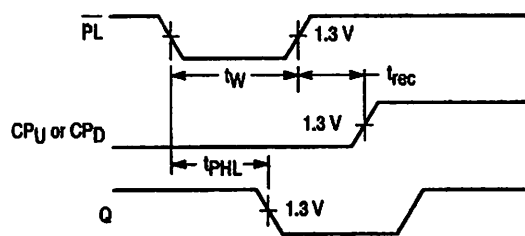
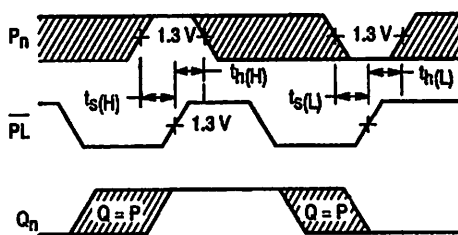


Figure 5



* The shaded areas indicate when the input is permitted to change for predictable output performance

Figure 6

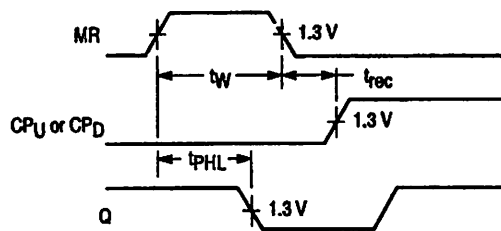
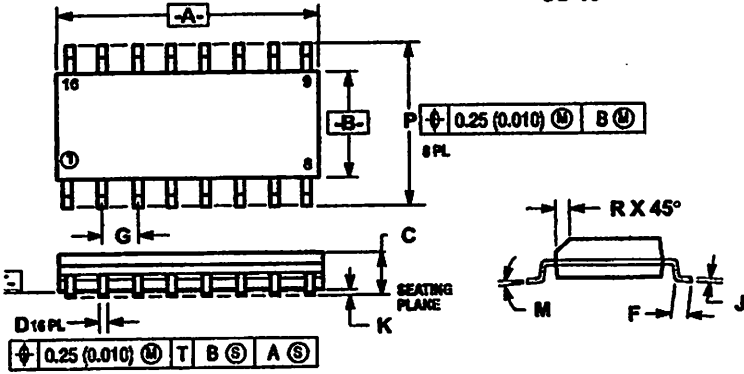


Figure 7

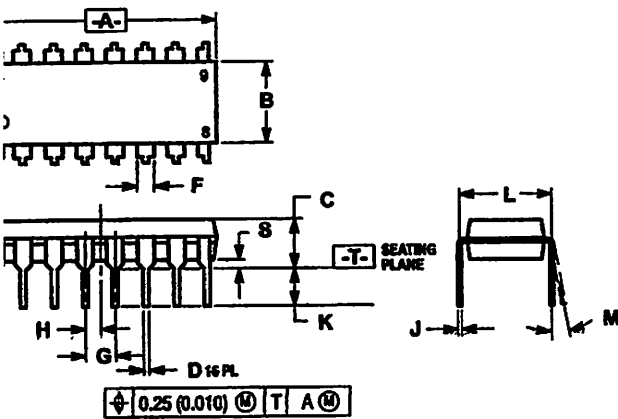
**Case 751B-03 D Suffix
16-Pin Plastic
SO-16**



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.005) PER SIDE.
 5. 751B-01 IS OBSOLETE, NEW STANDARD 751B-03.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.48	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.10	0.25	0.004	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	6.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

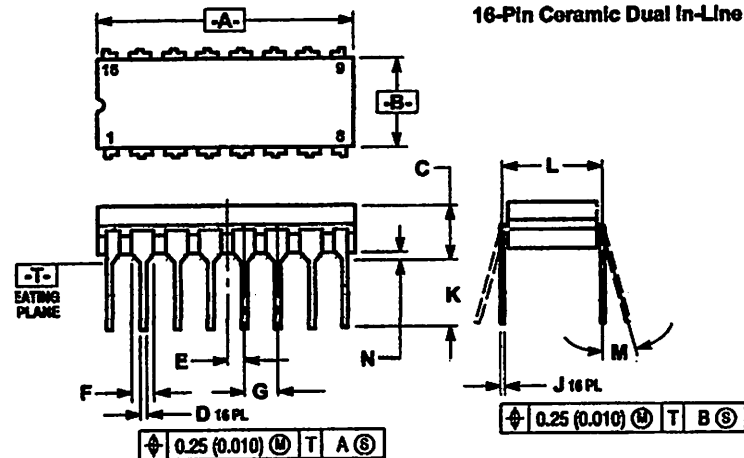
**Case 648-08 N Suffix
16-Pin Plastic**



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION "S" DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.
 6. 648-01 THRU -07 OBSOLETE, NEW STANDARD 648-06.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.50	19.55	0.740	0.770
B	6.85	6.85	0.269	0.270
C	3.69	4.44	0.145	0.175
D	0.59	0.53	0.015	0.021
F	1.02	1.77	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.27 BSC		0.050 BSC	
J	0.21	0.38	0.008	0.015
K	2.80	3.30	0.110	0.130
L	7.50	7.74	0.295	0.305
M	0°	10°	0°	10°
S	0.51	1.01	0.020	0.040

**Case 620-09 J Suffix
16-Pin Ceramic Dual In-Line**



- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.
 5. 620-01 THRU -06 OBSOLETE, NEW STANDARD 620-08.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	18.05	19.55	0.750	0.770
B	6.10	7.35	0.240	0.290
C	—	4.19	—	0.165
D	0.39	0.53	0.015	0.021
E	1.27 BSC		0.050 BSC	
F	1.40	1.77	0.055	0.070
G	2.54 BSC		0.100 BSC	
J	0.23	0.27	0.009	0.011
K	—	5.08	—	0.200
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.39	0.68	0.015	0.035

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and ^{AA} are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

Literature Distribution Centers:

USA: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036.

EUROPE: Motorola Ltd.; European Literature Centre; 88 Tanners Drive, Blakelands, Milton Keynes, MK14 5BP, England.

JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141, Japan.

ASIA PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dal King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.

MOTOROLA

◇

8-Bit Serial-Input/Serial or Parallel-Output Shift Register with Latched 3-State Outputs High-Performance Silicon-Gate CMOS

The MC54/74HC595A is identical in pinout to the LS595. The device outputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC595A consists of an 8-bit shift register and an 8-bit D-type latch with three-state parallel outputs. The shift register accepts serial data and provides a serial output. The shift register also provides parallel data to the latch. The shift register and latch have independent clock inputs. This device also has an asynchronous reset for the shift register.

The HC595A directly interfaces with the Motorola SPI serial data port on IOS MPUs and MCUs.

Output Drive Capability: 15 LSTTL Loads

Outputs Directly Interface to CMOS, NMOS, and TTL

Operating Voltage Range: 2.0 to 6.0 V

Low Input Current: 1.0 μ A

High Noise Immunity Characteristic of CMOS Devices

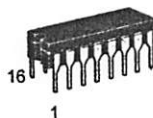
In Compliance with the Requirements Defined by JEDEC Standard No. 7A

Chip Complexity: 328 FETs or 82 Equivalent Gates

Improvements over HC595

- Improved Propagation Delays
- 50% Lower Quiescent Power
- Improved Input Noise and Latchup Immunity

MC54/74HC595A



J SUFFIX
CERAMIC PACKAGE
CASE 620-10



N SUFFIX
PLASTIC PACKAGE
CASE 648-08



D SUFFIX
SOIC PACKAGE
CASE 751B-05

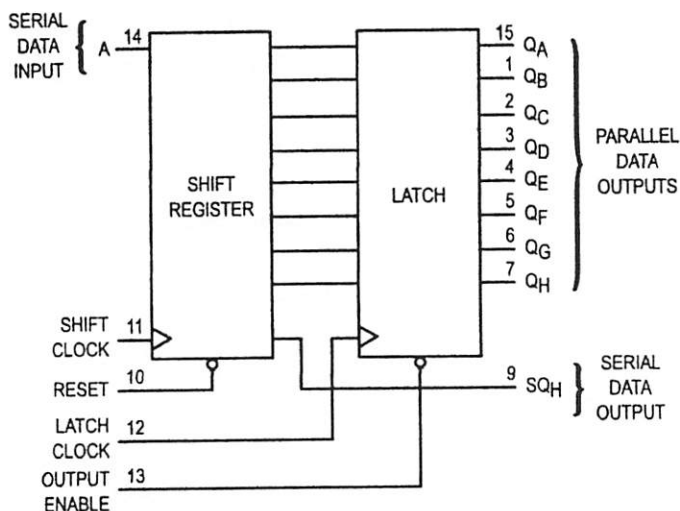


DT SUFFIX
TSSOP PACKAGE
CASE 948F-01

ORDERING INFORMATION

MC54HCXXXAJ	Ceramic
MC74HCXXXAN	Plastic
MC74HCXXXAD	SOIC
MC74HCXXXADT	TSSOP

LOGIC DIAGRAM



VCC = PIN 16
GND = PIN 8

PIN ASSIGNMENT

QB	1	16	VCC
QC	2	15	QA
QD	3	14	A
QE	4	13	OUTPUT ENABLE
QF	5	12	LATCH CLOCK
QG	6	11	SHIFT CLOCK
QH	7	10	RESET
GND	8	9	SQH

74HC595A

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	- 1.5 to V _{CC} + 1.5	V
V _{out}	DC Output Voltage (Referenced to GND)	- 0.5 to V _{CC} + 0.5	V
I _{in}	DC Input Current, per Pin	± 20	mA
I _{out}	DC Output Current, per Pin	± 35	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	± 75	mA
P _D	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package) (Ceramic DIP)	260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤ (V_{in} or V_{out}) ≤ V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

Power Rating — Plastic DIP: - 10 mW/°C from 65° to 125°C
Ceramic DIP: - 10 mW/°C from 100° to 125°C
SOIC Package: - 7 mW/°C from 65° to 125°C
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V	
T _A	Operating Temperature, All Package Types	- 55	+ 125	°C	
t _r , t _f	Input Rise and Fall Time (Figure 1)	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	0 0 0	1000 500 400	ns

ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				- 55 to 25°C	≤ 85°C	≤ 125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V _{IL}	Maximum Low-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	2.0	0.5	0.5	0.5	V
			4.5	1.35	1.35	1.35	
			6.0	1.8	1.8	1.8	
V _{OH}	Minimum High-Level Output Voltage, Q _A - Q _H	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
			V _{in} = V _{IH} or V _{IL} I _{out} ≤ 6.0 mA I _{out} ≤ 7.8 mA	4.5	3.98	3.84	
V _{OL}	Maximum Low-Level Output Voltage, Q _A - Q _H	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
			V _{in} = V _{IH} or V _{IL} I _{out} ≤ 6.0 mA I _{out} ≤ 7.8 mA	4.5	0.26	0.33	
6.0	0.26	0.33	0.4				

* Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

ELECTRICAL CHARACTERISTICS (Continued)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				- 55 to 25°C	≤ 85°C	≤ 125°C	
V _{OH}	Minimum High-Level Output Voltage, SQ _H	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA I _{out} ≤ 5.2 mA	4.5	3.98	3.84	3.7	V
			6.0	5.48	5.34	5.2	
V _{OL}	Maximum Low-Level Output Voltage, SQ _H	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA I _{out} ≤ 5.2 mA	4.5	0.26	0.33	0.4	V
			6.0	0.26	0.33	0.4	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I _{OZ}	Maximum Three-State Leakage Current, Q _A - Q _H	Output in High-Impedance State V _{in} = V _{IL} or V _{IH} V _{out} = V _{CC} or GND	6.0	± 0.5	± 5.0	± 10	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	6.0	4.0	40	160	μA

ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6.0 ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 7)	2.0	6.0	4.8	4.0	MHz
		4.5	30	24	20	
		6.0	35	28	24	
PL _H , PHL	Maximum Propagation Delay, Shift Clock to SQ _H (Figures 1 and 7)	2.0	140	175	210	ns
		4.5	28	35	42	
		6.0	24	30	36	
PHL	Maximum Propagation Delay, Reset to SQ _H (Figures 2 and 7)	2.0	145	180	220	ns
		4.5	29	36	44	
		6.0	25	31	38	
PL _H , PHL	Maximum Propagation Delay, Latch Clock to Q _A - Q _H (Figures 3 and 7)	2.0	140	175	210	ns
		4.5	28	35	42	
		6.0	24	30	36	
PL _Z , PHZ	Maximum Propagation Delay, Output Enable to Q _A - Q _H (Figures 4 and 8)	2.0	150	190	225	ns
		4.5	30	38	45	
		6.0	26	33	38	
PZL, PZH	Maximum Propagation Delay, Output Enable to Q _A - Q _H (Figures 4 and 8)	2.0	135	170	205	ns
		4.5	27	34	41	
		6.0	23	29	35	
TL _H , THL	Maximum Output Transition Time, Q _A - Q _H (Figures 3 and 7)	2.0	60	75	90	ns
		4.5	12	15	18	
		6.0	10	13	15	
TL _H , THL	Maximum Output Transition Time, SQ _H (Figures 1 and 7)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance	—	10	10	10	pF
C _{out}	Maximum Three-State Output Capacitance (Output in High-Impedance State), Q _A - Q _H	—	15	15	15	pF

E: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

C _{PD}	Power Dissipation Capacitance (Per Package)*	Typical @ 25°C, V _{CC} = 5.0 V		pF
		300		

*Add to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

4/74HC595A

REQUIREMENTS (Input $t_r = t_f = 6.0$ ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			25°C to - 55°C	≤ 85°C	≤ 125°C	
	Minimum Setup Time, Serial Data Input A to Shift Clock (Figure 5)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9.0	11	13	
	Minimum Setup Time, Shift Clock to Latch Clock (Figure 6)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
	Minimum Hold Time, Shift Clock to Serial Data Input A (Figure 5)	2.0	5.0	5.0	5.0	ns
		4.5	5.0	5.0	5.0	
		6.0	5.0	5.0	5.0	
	Minimum Recovery Time, Reset Inactive to Shift Clock (Figure 2)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9.0	11	13	
	Minimum Pulse Width, Reset (Figure 2)	2.0	60	75	90	ns
		4.5	12	15	18	
		6.0	10	13	15	
	Minimum Pulse Width, Shift Clock (Figure 1)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9.0	11	13	
	Minimum Pulse Width, Latch Clock (Figure 6)	2.0	50	65	75	ns
		4.5	10	13	15	
		6.0	9.0	11	13	
	Maximum Input Rise and Fall Times (Figure 1)	2.0	1000	1000	1000	ns
		4.5	500	500	500	
		6.0	400	400	400	

FUNCTION TABLE

Operation	Inputs					Resulting Function			
	Reset	Serial Input A	Shift Clock	Latch Clock	Output Enable	Shift Register Contents	Latch Register Contents	Serial Output SQ _H	Parallel Outputs Q _A - Q _H
Shift register	L	X	X	L, H, \sim	L	L	U	L	U
Load into shift	H	D	\surd	L, H, \sim	L	D → SR _A ; SR _N → SR _{N+1}	U	SR _G → SR _H	U
Shift register remains unchanged	H	X	L, H, \sim	L, H, \sim	L	U	U	U	U
Shift register to latch register	H	X	L, H, \sim	\surd	L	U	SR _N → LR _N	U	SR _N
Shift register remains disabled	X	X	X	L, H, \sim	L	•	U	•	U
Parallel outputs	X	X	X	X	L	•	**	•	Enabled
Outputs into high impedance state	X	X	X	X	H	•	**	•	Z

Shift register contents
Latch register contents

D = data (L, H) logic level
U = remains unchanged

X = don't care
Z = high impedance

* = depends on Reset and Shift Clock inputs
** = depends on Latch Clock input

PIN DESCRIPTIONS

INPUTS

Serial Data Input (Pin 14)

Serial Data Input. The data on this pin is shifted into the 8-bit serial shift register.

CONTROL INPUTS

Shift Register Clock (Pin 11)

Shift Register Clock Input. A low-to-high transition on this pin causes the data at the Serial Input pin to be shifted into the 8-bit shift register.

Reset (Pin 10)

Active-low, Asynchronous, Shift Register Reset Input. A low on this pin resets the shift register portion of this device. The 8-bit latch is not affected.

Latch Clock (Pin 12)

Storage Latch Clock Input. A low-to-high transition on this input latches the shift register data.

Output Enable (Pin 13)

Active-low Output Enable. A low on this input allows the data from the latches to be presented at the outputs. A high on this input forces the outputs (Q_A - Q_H) into the high-impedance state. The serial output is not affected by this control unit.

OUTPUTS

Q_A - Q_H (Pins 15, 1, 2, 3, 4, 5, 6, 7)

Noninverted, 3-state, latch outputs.

SQ_H (Pin 9)

Noninverted, Serial Data Output. This is the output of the eighth stage of the 8-bit shift register. This output does not have three-state capability.

SWITCHING WAVEFORMS

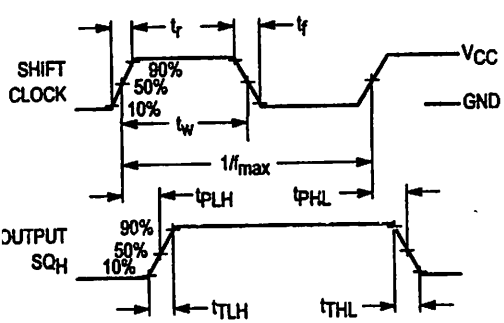


Figure 1.

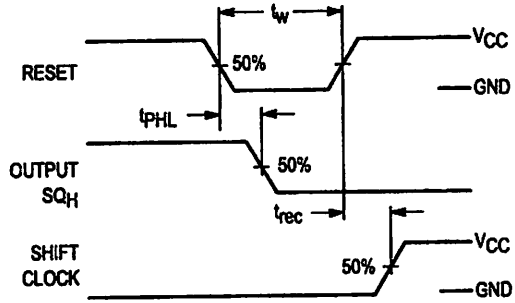


Figure 2.

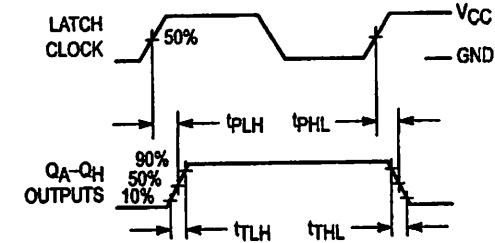


Figure 3.

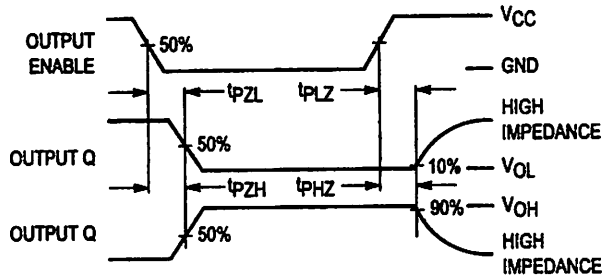


Figure 4.

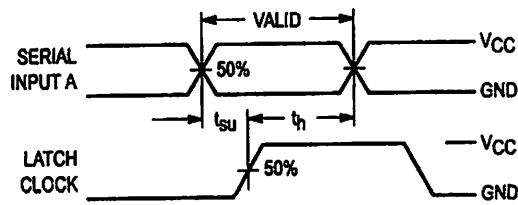


Figure 5.

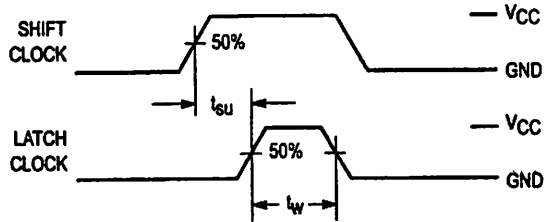
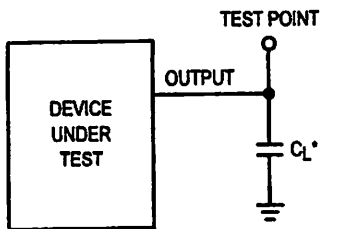


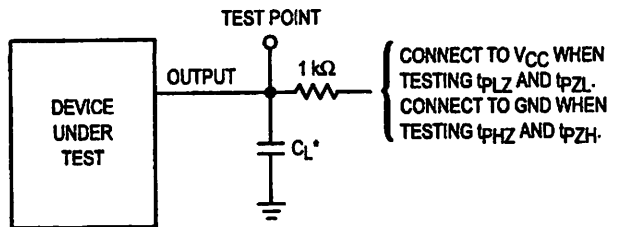
Figure 6.

TEST CIRCUITS



* Includes all probe and jig capacitance

Figure 7.

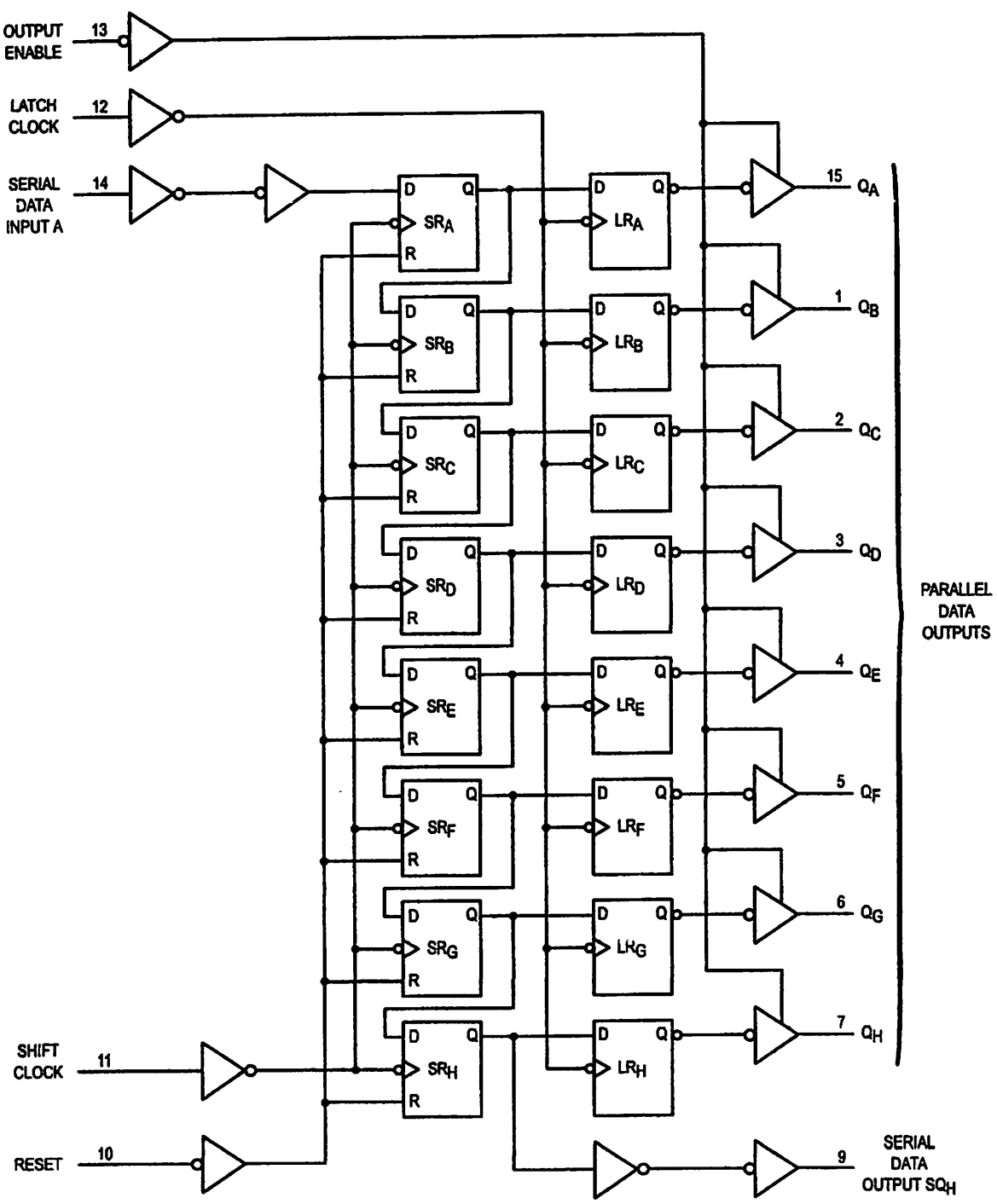


* Includes all probe and jig capacitance

Figure 8.

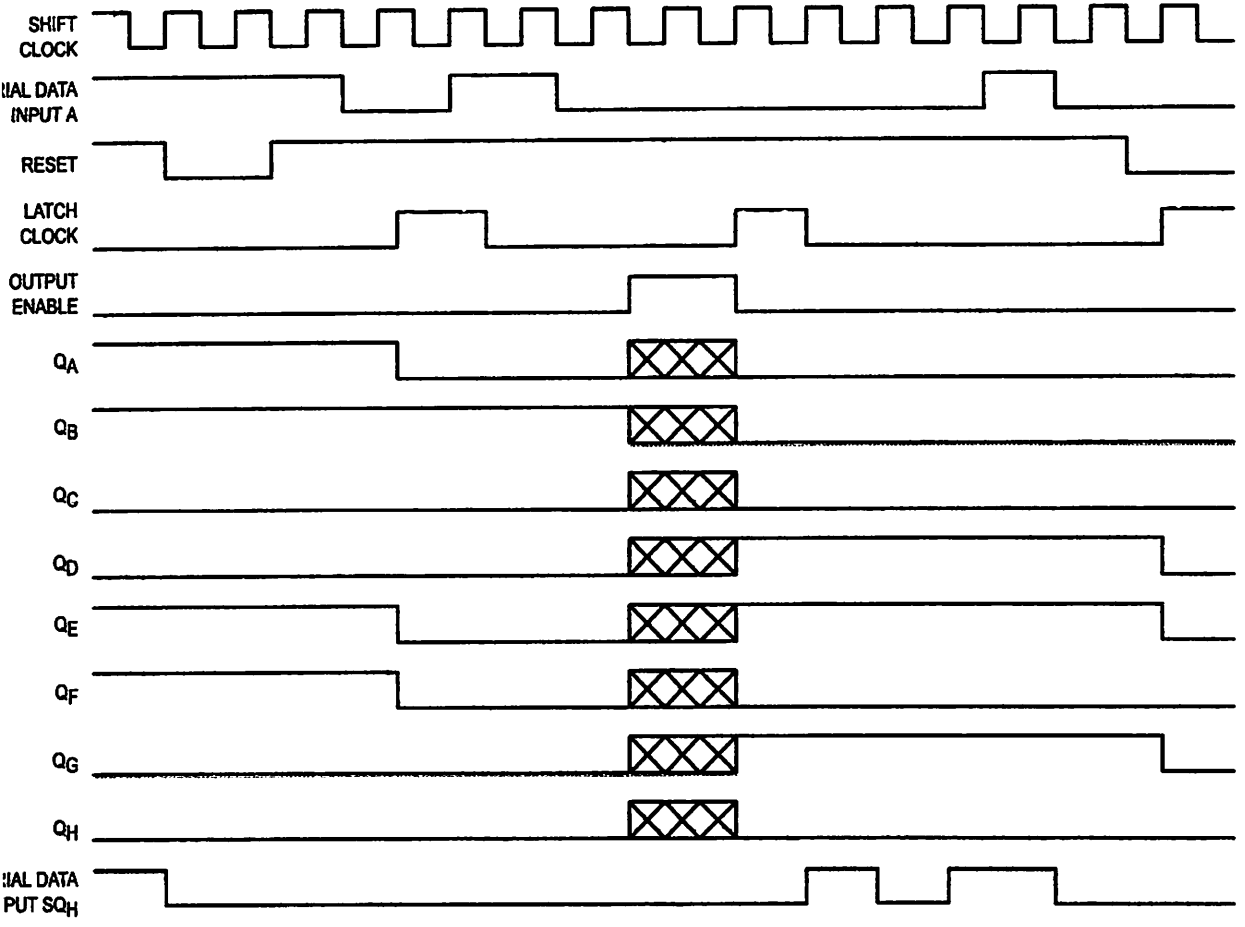
MC54/74HC595A

EXPANDED LOGIC DIAGRAM



74HC595A

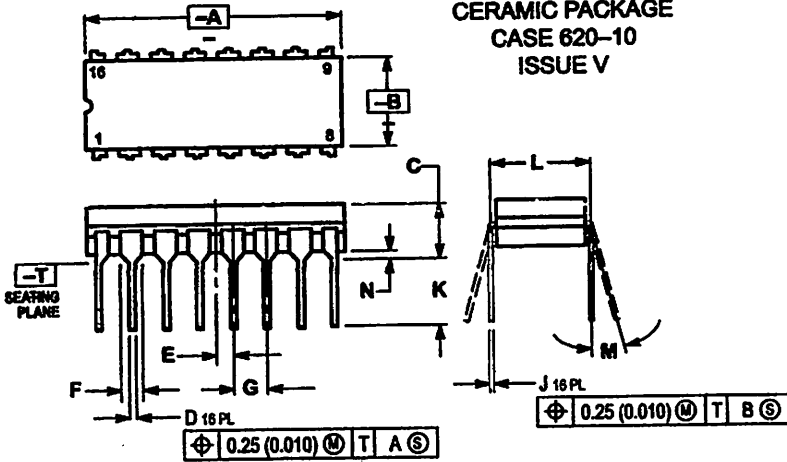
TIMING DIAGRAM



NOTE: XXXX implies that the output is in a high-impedance state.

OUTLINE DIMENSIONS

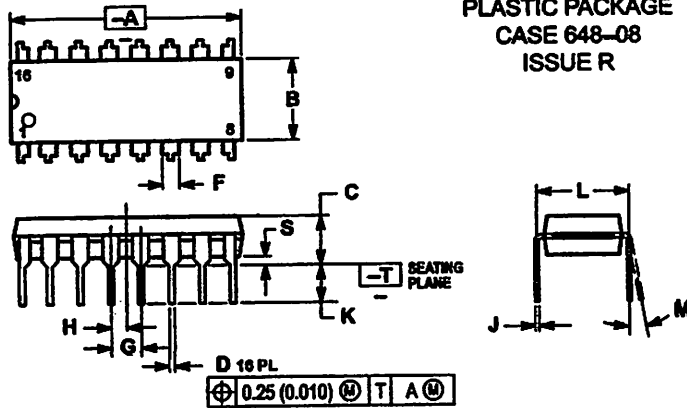
J SUFFIX
CERAMIC PACKAGE
CASE 620-10
ISSUE V



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIM F MAY NARROW TO 0.75 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.765	19.05	19.53
B	0.240	0.265	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	19°	0°	19°
N	0.020	0.040	0.51	1.01

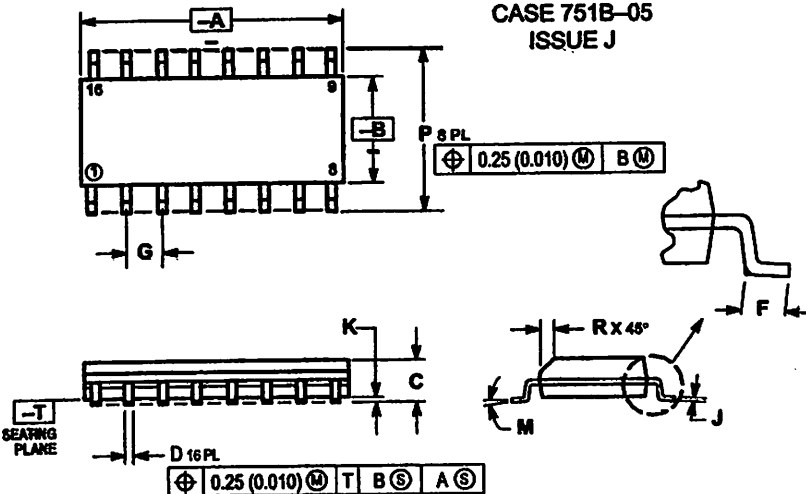
N SUFFIX
PLASTIC PACKAGE
CASE 648-08
ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.285	0.305	7.26	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B-05
ISSUE J

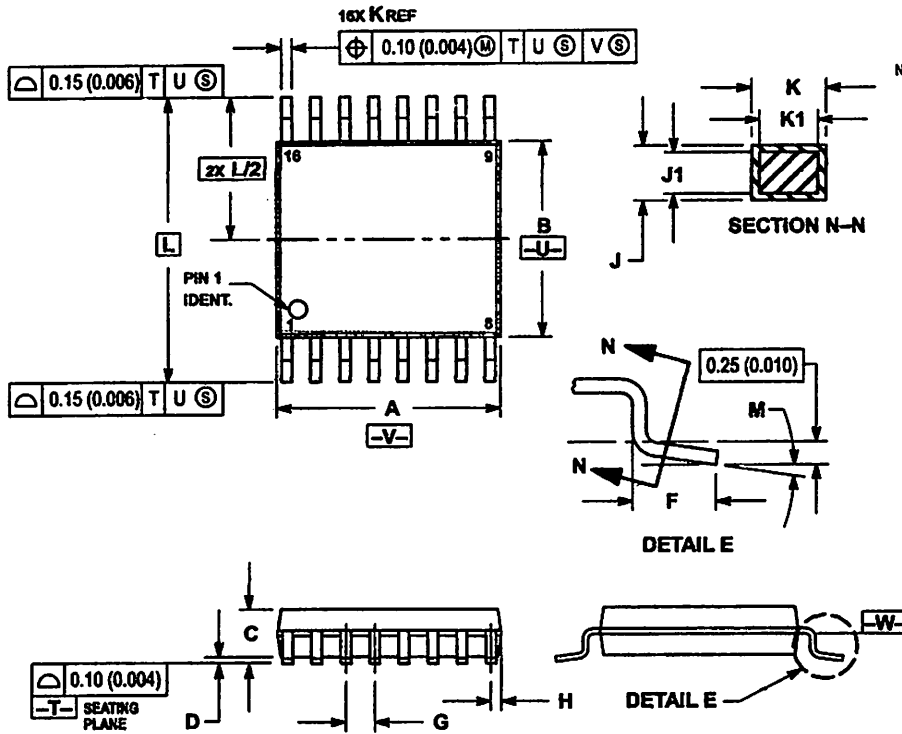


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.389	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.069
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.18	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

OUTLINE DIMENSIONS

DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F-01
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and [®] are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

How to reach us:
 EUROPE: Motorola Literature Distribution;
 P.O. Box 20912; Phoenix, Arizona 85038. 1-800-441-2447

JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, Toshikatsu Otsuki,
 6F Seibu-Butsuryu-Center, 3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-3521-8315

FAX: RMFAX0@email.sps.mot.com - TOUCHTONE (602) 244-6609
 INTERNET: http://Design-NET.com

HONG KONG: Motorola Semiconductors H.K. Ltd.; 68 Tai Ping Industrial Park,
 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298



◇ CODELINE

MC54/74HC595A/D





MICROCHIP

PIC16F84A
Data Sheet

18-pin Enhanced FLASH/EEPROM
8-bit Microcontroller

Note the following details of the code protection feature on PICmicro[®] MCUs.

- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable".
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

If you have any further questions about this matter, please contact the local sales office nearest to you.

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks


The Microchip name and logo, the Microchip logo, PIC, PICmicro, PICMASTER, PICSTART, PRO MATE, KEELOQ, SEEVAL, MPLAB and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

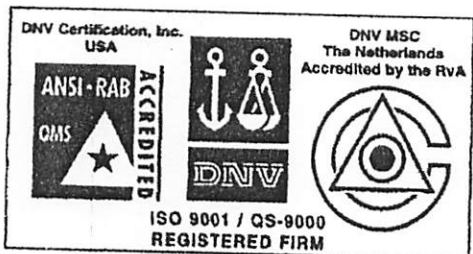
Total Endurance, ICSP, In-Circuit Serial Programming, Filter-Lab, MXDEV, microID, FlexROM, fuzzyLAB, MPASM, MPLINK, MPLIB, PICC, PICDEM, PICDEM.net, ICEPIC, Migratable Memory, FanSense, ECONOMONITOR, Select Mode and microPort are trademarks of Microchip Technology Incorporated in the U.S.A.

Serialized Quick Term Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2001, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro[®] 8-bit MCUs, KEELOQ[®] code hopping devices, Serial EEPROMs and microperipheral products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



MICROCHIP

PIC16F84A

18-pin Enhanced FLASH/EEPROM 8-Bit Microcontroller

High Performance RISC CPU Features:

- Only 35 single word instructions to learn
- All instructions single-cycle except for program branches which are two-cycle
- Operating speed: DC - 20 MHz clock input
DC - 200 ns instruction cycle
- 2048 words of program memory
- 256 bytes of Data RAM
- 256 bytes of Data EEPROM
- 4-bit wide instruction words
- 8-bit wide data bytes
- 5 Special Function Hardware registers
- 8-level deep hardware stack
- Direct, indirect and relative addressing modes
- Four interrupt sources:
 - External RB0/INT pin
 - TMR0 timer overflow
 - PORTB<7:4> interrupt-on-change
 - Data EEPROM write complete

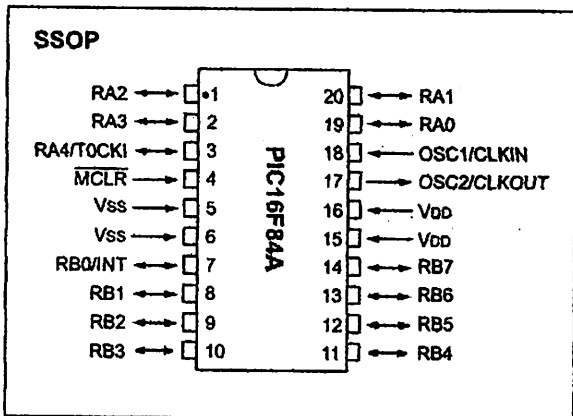
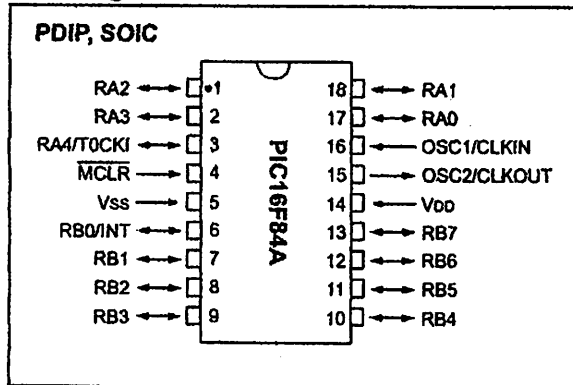
Peripheral Features:

- 3 I/O pins with individual direction control
- High current sink/source for direct LED drive
25 mA sink max. per pin
25 mA source max. per pin
- VR0: 8-bit timer/counter with 8-bit programmable prescaler

Special Microcontroller Features:

- 100,000 erase/write cycles Enhanced FLASH program memory typical
- 100,000 typical erase/write cycles EEPROM data memory typical
- EEPROM Data Retention > 40 years
- Circuit Serial Programming™ (ICSP™) - via 2 pins
- Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST)
- Watchdog Timer (WDT) with its own On-Chip RC oscillator for reliable operation
- Code protection
- Power saving SLEEP mode
- Selectable oscillator options

Pin Diagrams



CMOS Enhanced FLASH/EEPROM Technology:

- Low power, high speed technology
- Fully static design
- Wide operating voltage range:
 - Commercial: 2.0V to 5.5V
 - Industrial: 2.0V to 5.5V
- Low power consumption:
 - < 2 mA typical @ 5V, 4 MHz
 - 15 µA typical @ 2V, 32 kHz
 - < 0.5 µA typical standby current @ 2V

PIC16F84A

Table of Contents

1.0 Device Overview	3
2.0 Memory Organization	5
3.0 Data EEPROM Memory	13
4.0 I/O Ports	15
5.0 Timer0 Module	19
6.0 Special Features of the CPU	21
7.0 Instruction Set Summary	35
8.0 Development Support	43
9.0 Electrical Characteristics	49
10.0 DC/AC Characteristic Graphs	61
11.0 Packaging Information	71
Appendix A: Revision History	75
Appendix B: Conversion Considerations	76
Appendix C: Migration from Baseline to Mid-Range Devices	78
Index	79
On-Line Support	83
Reader Response	84
PIC16F84A Product Identification System	85

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at docerrors@mail.microchip.com or fax the Reader Response Form in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

<http://www.microchip.com>

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; <http://www.microchip.com>
- Your local Microchip sales office (see last page)
- The Microchip Corporate Literature Center; U.S. FAX: (480) 792-7277

When contacting a sales office or the literature center, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com/cn to receive the most current information on all of our products.

PIC16F84A

DEVICE OVERVIEW

This document contains device specific information for the operation of the PIC16F84A device. Additional information may be found in the PICmicro™ Mid-range Reference Manual, (DS33023), which may be downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the architecture and operation of the peripheral modules.

The PIC16F84A belongs to the mid-range family of the PICmicro® microcontroller devices. A block diagram of the device is shown in Figure 1-1.

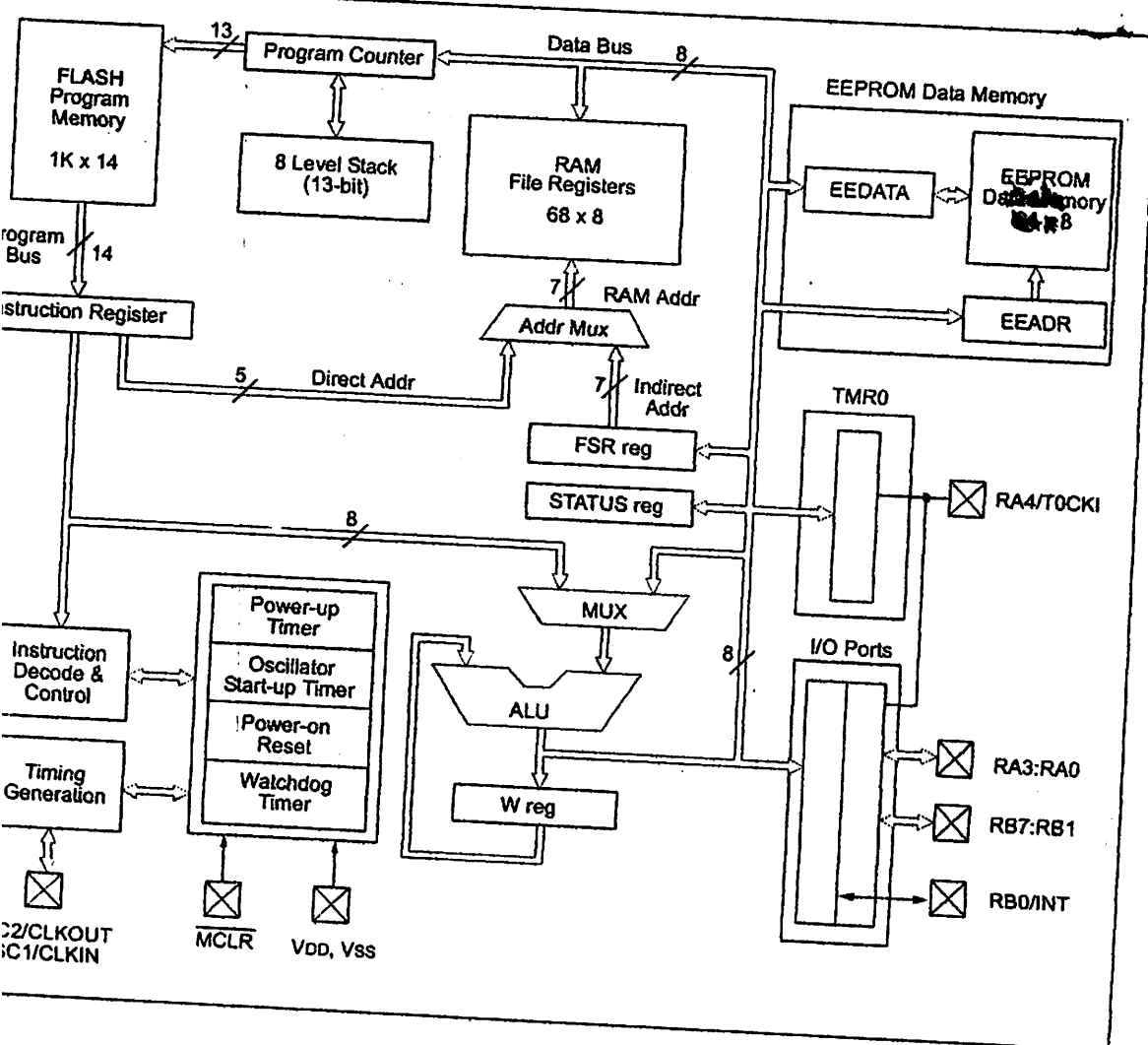
The program memory contains 1K words, which translates to 1024 instructions, since each 14-bit program memory word is the same width as each device instruction. The data memory (RAM) contains 68 bytes. Data EEPROM is 64 bytes.

There are also 13 I/O pins that are user-configured on a pin-to-pin basis. Some pins are multiplexed with other device functions. These functions include:

- External interrupt
- Change on PORTB interrupt
- Timer0 clock input

Table 1-1 details the pinout of the device with descriptions and details for each pin.

FIGURE 1-1: PIC16F84A BLOCK DIAGRAM



PIC16F84A

TABLE 1-1: PIC16F84A PINOUT DESCRIPTION

Pin Name	PDIP No.	SOIC No.	SSOP No.	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	16	16	18	I	ST/CMOS ⁽³⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	15	15	19	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
MCLR	4	4	4	I/P	ST	Master Clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
RA0	17	17	19	I/O	TTL	PORTA is a bi-directional I/O port. Can also be selected to be the clock input to the TMR0 timer/counter. Output is open drain type.
RA1	18	18	20	I/O	TTL	
RA2	1	1	1	I/O	TTL	
RA3	2	2	2	I/O	TTL	
RA4/T0CKI	3	3	3	I/O	ST	
RB0/INT	6	6	7	I/O	TTL/ST ⁽¹⁾	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. RB0/INT can also be selected as an external interrupt pin. Interrupt-on-change pin. Interrupt-on-change pin. Interrupt-on-change pin. Serial programming clock. Interrupt-on-change pin. Serial programming data.
RB1	7	7	8	I/O	TTL	
RB2	8	8	9	I/O	TTL	
RB3	9	9	10	I/O	TTL	
RB4	10	10	11	I/O	TTL	
RB5	11	11	12	I/O	TTL	
RB6	12	12	13	I/O	TTL/ST ⁽²⁾	
RB7	13	13	14	I/O	TTL/ST ⁽²⁾	
/SS	5	5	5,6	P	—	Ground reference for logic and I/O pins.
/DD	14	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = Output I/O = Input/Output P = Power
 — = Not used TTL = TTL input ST = Schmitt Trigger input

- Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
- Note 2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
- Note 3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

PIC16F84A

0 MEMORY ORGANIZATION

There are two memory blocks in the PIC16F84A. These are the program memory and the data memory. Each block has its own bus, so that access to each block can occur during the same oscillator cycle.

The data memory can further be broken down into the general purpose RAM and the Special Function Registers (SFRs). The operation of the SFRs that control the "core" are described here. The SFRs used to control the peripheral modules are described in the section discussing each individual peripheral module.

The data memory area also contains the data EEPROM memory. This memory is not directly mapped to the data memory, but is indirectly mapped. That is, an indirect address pointer specifies the address of the data EEPROM memory to read/write. The 64 bytes of data EEPROM memory have the address range 0000h-00FFh. More details on the EEPROM memory can be found in Section 3.0.

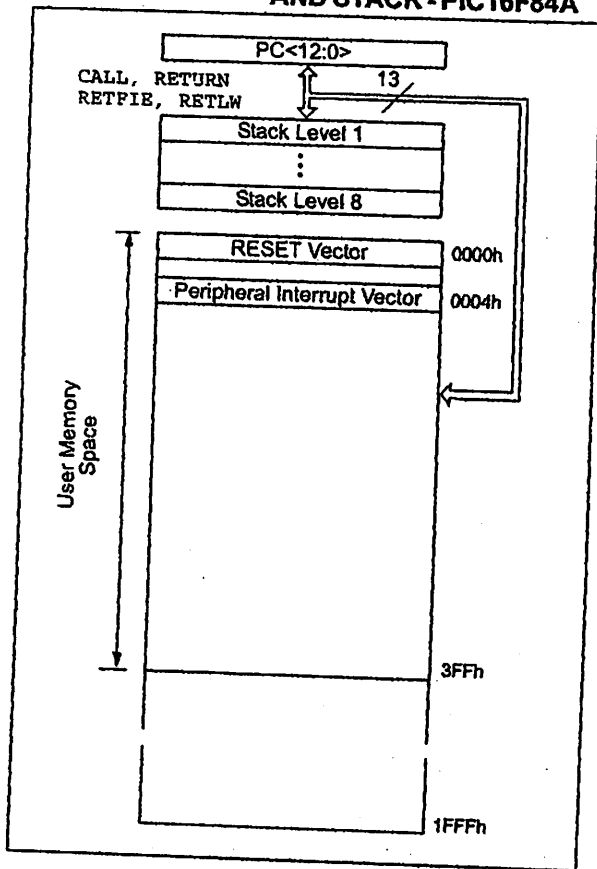
Additional information on device memory may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

Program Memory Organization

The PIC16FXX has a 13-bit program counter capable of addressing an 8K x 14 program memory space. For the PIC16F84A, the first 1K x 14 (0000h-03FFh) are physically implemented (Figure 2-1). Accessing a location above the physically implemented address will result in a wraparound. For example, for locations 20h, 1020h, C20h, 1020h, 1820h, and 1C20h, the instruction will be the same.

The RESET vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK - PIC16F84A



PIC16F84A

2.2 Data Memory Organization

The data memory is partitioned into two areas. The first is the Special Function Registers (SFR) area, while the second is the General Purpose Registers (GPR) area. The SFRs control the operation of the device.

Portions of data memory are banked. This is for both the SFR area and the GPR area. The GPR area is banked to allow greater than 116 bytes of general purpose RAM. The banked areas of the SFR are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the STATUS Register. Figure 2-2 shows the data memory map organization.

Instructions *MOVWF* and *MOVF* can move values from the W register to any location in the register file ("F"), and vice-versa.

The entire data memory can be accessed either directly using the absolute address of each register file or indirectly through the File Select Register (FSR) (Section 2.5). Indirect addressing uses the present value of the RP0 bit for access into the banked areas of data memory.

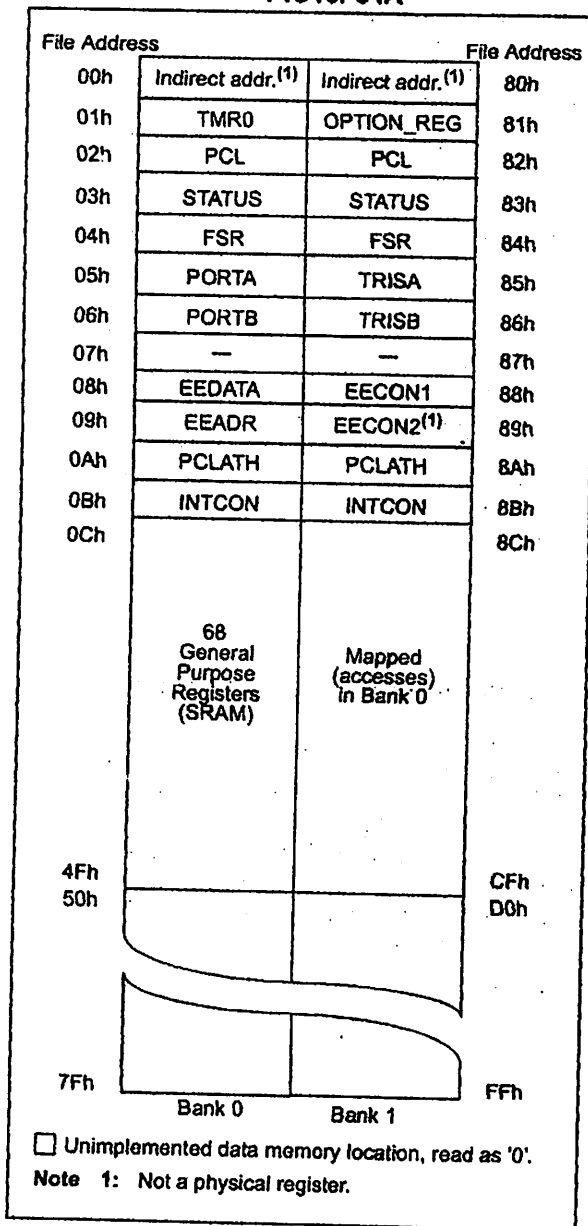
Data memory is partitioned into two banks which contain the general purpose registers and the special function registers. Bank 0 is selected by clearing the RP0 bit (*STATUS<5>*). Setting the RP0 bit selects Bank 1. Each Bank extends up to 7Fh (128 bytes). The first twelve locations of each Bank are reserved for the Special Function Registers. The remainder are General Purpose Registers, implemented as static RAM.

2.2.1 GENERAL PURPOSE REGISTER FILE

Each General Purpose Register (GPR) is 8-bits wide and is accessed either directly or indirectly through the FSR (Section 2.5).

The GPR addresses in Bank 1 are mapped to addresses in Bank 0. As an example, addressing location 0Ch or 8Ch will access the same GPR.

FIGURE 2-2: REGISTER FILE MAP - PIC16F84A



PIC16F84A

Special Function Registers

Special Function Registers (Figure 2-2 and 2-3) are used by the CPU and Peripheral Modules to control the device operation. These registers are static RAM.

The special function registers can be classified into two sets, core and peripheral. Those associated with the core functions are described in this section. Those related to the operation of the peripheral features are described in the section for that specific feature.

2-1: SPECIAL FUNCTION REGISTER FILE SUMMARY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on RESET	Details on page
DFSR	Uses contents of FSR to address Data Memory (not a physical register)								---- ----	11
RTCCON	8-bit Real-Time Clock/Counter								xxxx xxxx	20
PCON	Low Order 8 bits of the Program Counter (PC)								0000 0000	11
STATUS ⁽²⁾	IRP	RF1	RP0	\overline{TO}	\overline{PD}	Z	DC	C	0001 1xxx	8
INDR	Indirect Data Memory Address Pointer 0								xxxx xxxx	11
PORTA ⁽⁴⁾	—	—	—	RA4/T0CKI	RA3	RA2	RA1	RA0	---x xxxx	16
PORTB ⁽⁵⁾	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0/INT	xxxx xxxx	18
—	Unimplemented location, read as '0'								—	—
EECON1	EEPROM Data Register								xxxx xxxx	13,14
EEADR	EEPROM Address Register								xxxx xxxx	13,14
PCLATH	—	—	—	Write Buffer for upper 5 bits of the PC ⁽¹⁾				---	0 0000	11
TCON	GIE	EEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	10
DFSR	Uses Contents of FSR to address Data Memory (not a physical register)								---- ----	11
OPTION_REG	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	9
PCON	Low order 8 bits of Program Counter (PC)								0000 0000	11
STATUS ⁽²⁾	IRP	RP1	RP0	\overline{TO}	\overline{PD}	Z	DC	C	0001 1xxx	8
INDR	Indirect data memory address pointer 0								xxxx xxxx	11
PORTA	—	—	—	PORTA Data Direction Register				---	1 1111	16
PORTB	PORTB Data Direction Register								1111 1111	18
—	Unimplemented location, read as '0'								—	—
EECON1	—	—	—	EEIF	WRERR	WREN	WR	RD	---0 x000	13
EECON2	EEPROM Control Register 2 (not a physical register)								---- ----	14
PCLATH	—	—	—	Write buffer for upper 5 bits of the PC ⁽¹⁾				---	0 0000	11
TCON	GIE	EEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	10

x = unknown, u = unchanged, - = unimplemented, read as '0', q = value depends on condition

The upper byte of the program counter is not directly accessible. PCLATH is a slave register for PC<12:8>. The contents of PCLATH can be transferred to the upper byte of the program counter, but the contents of PC<12:8> are never transferred to PCLATH.

The \overline{TO} and \overline{PD} status bits in the STATUS register are not affected by a MCLR Reset.

Other (non power-up) RESETS include: external RESET through MCLR and the Watchdog Timer Reset.

On any device RESET, these pins are configured as inputs.

This is the value that will be in the port output latch.

PIC16F84A

2.3.1 STATUS REGISTER

The STATUS register contains the arithmetic status of the ALU, the RESET status and the bank select bit for data memory.

As with any register, the STATUS register can be the destination for any instruction. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to device logic. Furthermore, the \overline{TO} and \overline{PD} bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as 000u u1uu (where u = unchanged).

Only the `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions should be used to alter the STATUS register (Table 7-2), because these instructions do not affect any status bit.

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16F84A and should be programmed as cleared. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

2: The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

3: When the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. The specified bit(s) will be updated according to device logic.

REGISTER 2-1: STATUS REGISTER (ADDRESS 03h, 83h)

RW-0	RW-0	RW-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	\overline{TO}	\overline{PD}	Z	DC	C
bit 7					bit 0		

- bit 7-6 **Unimplemented:** Maintain as '0'
- bit 5 **RP0:** Register Bank Select bits (used for direct addressing)
01 = Bank 1 (80h - FFh)
00 = Bank 0 (00h - 7Fh)
- bit 4 **\overline{TO} :** Time-out bit
1 = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
0 = A WDT time-out occurred
- bit 3 **\overline{PD} :** Power-down bit
1 = After power-up or by the `CLRWDT` instruction
0 = By execution of the `SLEEP` instruction
- bit 2 **Z:** Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero
- bit 1 **DC:** Digit carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for borrow, the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result
- bit 0 **C:** Carry/borrow bit (`ADDWF`, `ADDLW`, `SUBLW`, `SUBWF` instructions) (for borrow, the polarity is reversed)
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note: A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF`, `RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared
		x = Bit is unknown

PIC16F84A

2 OPTION REGISTER

OPTION register is a readable and writable register which contains various control bits to configure TMR0/WDT prescaler, the external INT interrupt, PORTB pull-ups, and the weak pull-ups on PORTB.

Note: When the prescaler is assigned to the WDT (PSA = '1'), TMR0 has a 1:1 prescaler assignment.

REGISTER 2-2: OPTION REGISTER (ADDRESS 81h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
						bit 7	bit 0

- bit 7 **RBPU:** PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values
- bit 6 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin
- bit 5 **T0CS:** TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)
- bit 4 **T0SE:** TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin
- bit 3 **PSA:** Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module
- bit 2-0 **PS2:PS0:** Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1:2	1:1
001	1:4	1:2
010	1:8	1:4
011	1:16	1:8
100	1:32	1:16
101	1:64	1:32
110	1:128	1:64
111	1:256	1:128

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

2.4 PCL and PCLATH

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 13 bits wide. The low byte is called the PCL register. This register is readable and writable. The high byte is called the PCH register. This register contains the PC<12:8> bits and is not directly readable or writable. If the program counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP. All updates to the PCH register go through the PCLATH register.

2.4.1 STACK

The stack allows a combination of up to 8 program calls and interrupts to occur. The stack contains the return address from this branch in program execution.

Mid-range devices have an 8 level deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not modified when the stack is PUSHed or POPed.

After the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

2.5 Indirect Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

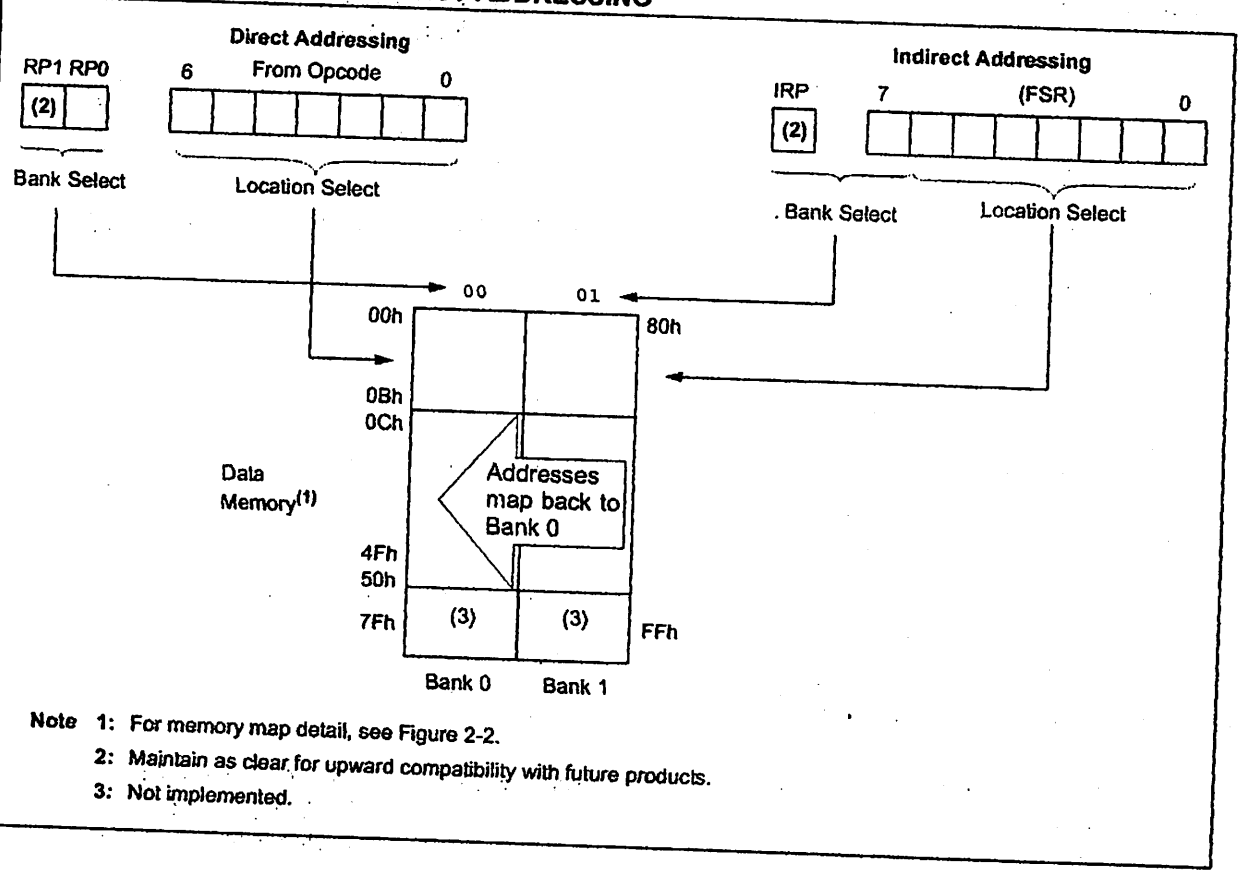
```

movlw 0x20 ;initialize pointer
movwf FSR ;to RAM
NEXT   clrf INDF ;clear INDF register
       incf FSR ;inc pointer
       btfss FSR,4 ;all done?
       goto NEXT ;NO, clear next
CONTINUE
       : ;YES, continue
    
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-3. However, IRP is not used in the PIC16F84A.

PIC16F84A

FIGURE 2-3: DIRECT/INDIRECT ADDRESSING



- Note 1:** For memory map detail, see Figure 2-2.
- Note 2:** Maintain as clear for upward compatibility with future products.
- Note 3:** Not implemented.